

HC32F467 Series

32-bit ARM[®] Cortex[®]-M4 Microcontroller

Datasheet

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Features

ARM Cortex-M4 32bit MCU+FPU, 300DMIPS, 1MB Flash, 516KB SRAM, 2USBs (HS/FS OTG), Ethernet MAC, 2CANs (2.0B), 2SDIOs, DVP, EXMC, 19 Timers, 3ADCs, 2DACs, 2PGAs, 3CMPs, 8UARTs, 6SPIs, 3I2Cs, 4I2Ss, QSPI, AES, HASH (SHA256/HMAC), FMAC (FIR), MAU

- **ARMv7-M architecture 32bit Cortex-M4 CPU, integrated FPU, MPU, DSP supporting SIMD instructions, full instruction tracking unit ETM, and CoreSight standard debug unit. The highest working frequency is 240MHz, reaching the computing performance of 300DMIPS or 825Coremarks**
- **Built-in memory**
 - Maximum 1024KByte single bank Flash memory
 - Maximum 516KByte SRAM, including 128KByte single-cycle access high-speed RAM
- **Power, Clock, Reset Management**
 - System Power (Vcc): 1.8-3.6 V
 - 6 independent clock sources: External high-speed oscillator (4-25 MHz), external low-speed oscillator (32.768 kHz), internal high-speed RC (16/20 MHz), internal medium-speed RC (8 MHz), internal low-speed RC (32.768 kHz), internal WDT dedicated RC (10 kHz)
 - 15 reset sources including power-on reset (POR), low voltage detection reset (PVD1R/PVD2R), port reset (NRST), each reset source has an independent flag bit
- **Low power operation**
 - Peripherals can be turned off or on independently
 - Three low power modes: Sleep, Stop, Power down mode
 - VBAT independent power supply supports ultra-low power RTC, 128Byte backup register, 4KByte backup SRAM
- **Peripheral operation support system significantly reduces CPU processing load**
 - 16-channel dual-host DMAC
 - DMAC for USBHS, USBFS, Ethernet MAC
 - 8 Data Computation Units (DCUs)
 - Math co-processing unit (MAU), supports Sin/Sqrt
 - Support 16th order FIR digital filter (FMAC)
 - Support peripheral event mutual trigger (AOS)
- **High performance simulation**
 - 3 independent 12bit 2.5MSPS ADCs
 - 3 simultaneous sample and hold circuits to achieve simultaneous sampling of 3 channels
 - 2 independent 12bit 15MSPS DACs
 - 2 Programmable Gain Amplifiers (PGA)
 - 3 independent voltage comparators (CMP)
 - 1 On-Chip Temperature Sensor (OTS)
- **Timer**
 - 3 multi-function 32bit PWM Timer (Timer6)
 - 3 16-bit motor PWM Timers (Timer4)
 - 8 16bit general-purpose Timer (TimerA)
 - 2 16bit basic Timer (Timer0)
 - Real Time Clock Timer (RTC)
 - 2 WDTs, support internal dedicated clock
- **Up to 116 GPIOs**
 - Up to 112 5V-tolerant IOs
- **Maximum 32 communication interfaces**
 - 8 USARTs, support ISO7816-3 protocol
 - 6 SPIs
 - 3 I2C, support SMBus protocol
 - 4 I2S, built-in audio PLL
 - 2 SDIO, support SD/MMC/eMMC format
 - 1 QSPI, support 240Mbps high-speed access (XIP)
 - 2 CAN, support CAN2.0B
 - 2 USB 2.0, respectively support HS, FS, built-in FS-PHY, support Device/Host
 - 1 10/100M Ethernet MAC, support dedicated DMA, IEEE 1588-2018 PTP, MII/RMII interface
- **External Memory Controller EXMC**
 - Support for static memory controller
 - Support dynamic memory controller
- **Data encryption function**
 - AES/ HASH (SHA256/HMAC)/ TRNG
- **Encapsulation form:**
 - LQFP144 (20×20mm)
 - LQFP100 (14×14mm)
 - LQFP64 (10×10mm)

Support Model:

HC32F467KGTI-LQFP64	HC32F467PGTI-LQFP100
HC32F467RGTI-LQFP144	-

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1 Overview

The HC32F467 series is a high-performance MCU based on ARM® Cortex®-M4 32-bit RISC CPU with a maximum operating frequency of 240 MHz. The Cortex-M4 core integrates a floating-point arithmetic unit (FPU) and a DSP to implement single-precision floating-point arithmetic operations, supports all ARM single-precision data processing instructions and data types, and supports the complete DSP instruction set. The kernel integrates the MPU unit and superimposes the DMAC dedicated MPU unit at the same time to ensure the safety of system operation.

The HC32F467 series integrates high-speed on-chip memory, including a maximum of 1 MB of Flash and a maximum of 512 KB of SRAM. Integrated Flash access acceleration unit to achieve single cycle program execution of the CPU on Flash. The polled bus matrix supports multiple bus hosts to access memory and peripherals simultaneously, improving performance. The bus host includes CPU, DMA, USB dedicated DMA, ETHMAC dedicated DMA. In addition to the bus matrix, data transfer between peripherals is supported, and basic arithmetic operations and events are triggered each other, which can significantly reduce the transaction processing load of the CPU.

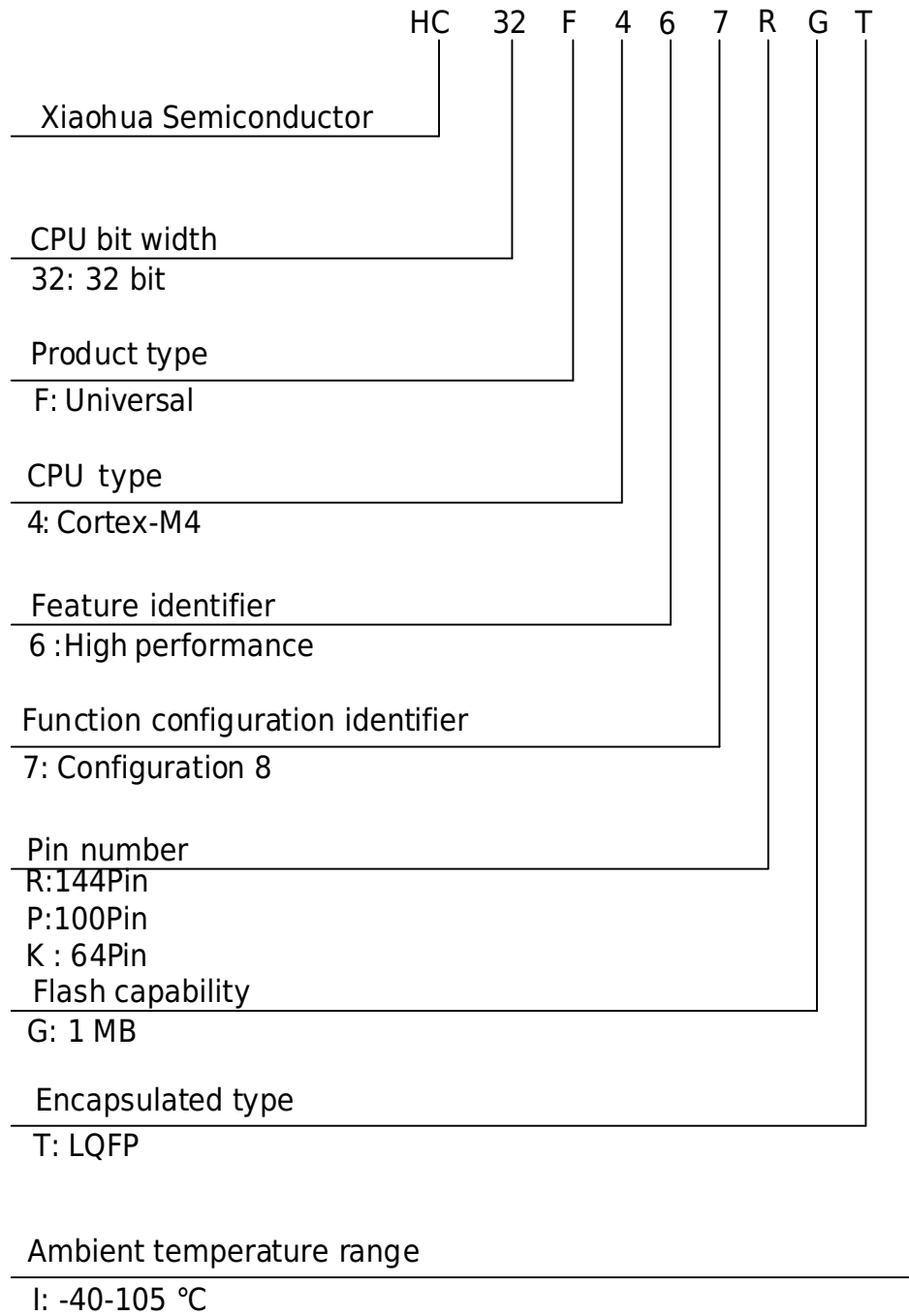
The HC32F467 series integrates rich peripheral functions. Including 3 independent 12bit 2.5MSPS ADC, 2 gain adjustable PGA, 2 12-bit 15MSPS DAC, 3 high-speed voltage comparator (CMP), 3 multi-function PWM Timer (Timer6), support 6 complementary PWM Output, 3 motor PWM Timer (Timer4) support 18 complementary PWM outputs, 8 16bit general Timer (TimerA) support 4 3-phase quadrature Code input and 32 independent PWM outputs for Duty, 17 serial communication interfaces (I2C/UART/SPI), 1 QSPI interface, 2 CAN, 4 I2S support audio PLL, 2 SDIO, 1 ETHMAC, USBFS Controller and USBHS Controller with built-in USBFS PHY, 1 external expansion bus controller, including NFC controller, SMC controller and DMC controller, 1 digital video interface DVP, 1 math operation unit (MAU) and 4 filtering Mathematics Accelerator (FMAC).

HC32F467 series supports wide voltage range (1.8~3.6V), wide temperature range (-40~105 °C) and various low power consumption modes. Supports fast wake-up in low power consumption mode, the fastest wake-up to STOP mode is 2 μs, and the fastest wake-up to Power-down mode is 25 μs.

Typical application

HC32F467 series provides 64pin, 100pin, 144pin LQFP package, used in high-performance frequency conversion control, digital power supply, intelligent hardware, IoT connection module and other fields.

1.1 Part Naming Rules



1.2 Part Function Comparison Table

Table 1-1 Model function comparison table

Function	Product		
	HC32F467 RGTI	HC32F467 PGTI	HC32F467 KGTI
Pin number	144	100	64
Number of GPIOs	116	83	52
5 V Tolerant GPIO number	108	75	48
Pin Pitch	LQFP		
Temperature range	-40 ~ 105 °C		
Supply voltage range	1.8 ~ 3.6 V		
Memory	Flash	1 MB	
	OTP	134KByte	
	SRAM	512 + 4 KB	
DMA	2unit * 8ch		
External port interrupt	EIRQ * 16vec		
Communcation Interfaces (In parentheses is the minimum number of IO required for each ch)	UART	8ch (1)	5ch (1)
	SPI	6ch (3)	
	I2C	3ch (2)	
	I2S	4ch (3)	
	CAN2.0B	2ch (2)	
	QSPI	1ch (3)	
	SDIO	2ch (3)	
	ETHMAC	1ch (10)	
USB HS	1ch (2)		

Function		Product		
		HC32F467 RGTI	HC32F467 PGTI	HC32F467 KGTI
	USB FS	1ch (2)		
Timers	Timer0	2unit		
	TimerA	8unit		
	Timer4	3unit		
	Timer6	3unit		
	WDT	1ch		
	SWDT	1ch		
	RTC	1ch		
Analog	12bit ADC	3unit, 24ch	3unit,16ch	
	12bitDAC	2ch		
	PGA	2ch		
	CMP	3ch		
	OTS	✓		
DVP		✓		
DCU		✓		
FMAC		✓		
MAU		✓		
AES256		✓		
HASH(SHA256)		✓		
TRNG		✓		
EXMC		1	0	
Frequency Monitoring Module (FCM)		✓		
Programmable Voltage		✓		

Function	Product		
	HC32F467 RGTI	HC32F467 PGTI	HC32F467 KGTI
Detection Function (PVD)			
Debug interface	SWD		
	JTAG		

1.3 Functional Block Diagram

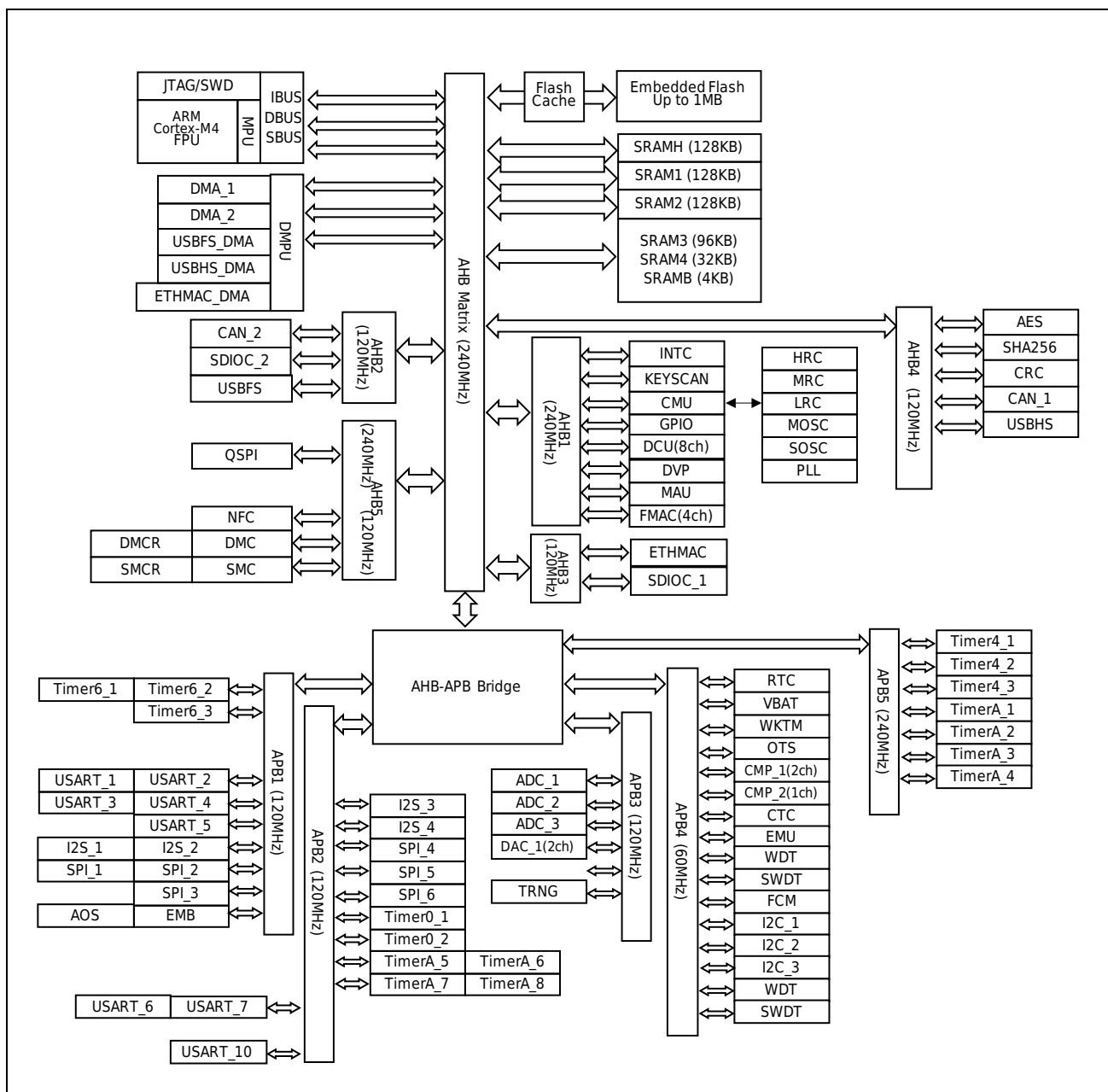


Figure 1-1 Functional block diagram

1.4 Feature Brief

1.4.1 CPU

The HC32F467 series integrates the latest generation of embedded ARM® Cortex®-M4 with FPU 32bit reduced instruction CPU, which achieves less pins and low power consumption, while providing excellent computing performance and rapid interrupt response capabilities. The on-chip integrated memory capacity can give full play to the excellent instruction efficiency of the ARM® Cortex®-M4 with FPU. The CPU supports DSP instructions, which can realize efficient signal processing operations and complex algorithms. The single-point precision FPU (Floating Point Unit) unit can avoid instruction saturation and speed up software development.

1.4.2 Bus Architecture (BUS)

The main system is composed of 32-bit multilayer AHB bus matrix, which can interconnect the following host bus and slave bus.

- Host bus
 - Cortex-M4F core CPU-I bus, CPU-D bus, CPU-S bus
 - System DMA_1 bus, system DMA_2 bus
 - USBFS_DMA bus
 - USBHS_DMA bus
 - ETHMAC_DMA bus
- Slave bus
 - Flash ICODE bus
 - Flash DCODE bus
 - Flash MCODE bus (bus for other hosts other than CPU to access Flash)
 - High-speed SRAMH (SRAMH 128 kB) bus
 - System SRAMA (SRAM1 128 KB) bus
 - System SRAMB (SRAM2 128 KB) bus
 - System SRAMC (SRAM3 96 KB, SRAM4 32 KB, SRAMB 4 KB)
 - APB1 peripheral bus (EMB/Timers/SPI/USART/I2S/HRPWM/EFM)
 - APB2 peripheral bus (Timers/SPI/USART/I2S)
 - APB3 peripheral bus (ADC/DAC/TRNG)
 - APB4 peripheral bus (FCM/WDT/SWDT/CMP/EMU/CTC/OTS/RTC/VBAT/WKTM/I2C)
 - APB5 peripheral bus (Timers)
 - AHB1 peripheral bus (DMPU/KEYSCAN/INTC/DCU/GPIO/DMA/CMU/DVP/MAU/FMAC)
 - AHB2 peripheral bus (CAN/SDIOC/USBFS)
 - AHB3 peripheral bus (SDIOC /ETHMAC)
 - AHB4 peripheral bus (AES/HASH/CRC/CAN/USBHS)
 - AHB5 peripheral bus (SMC/DMC/SMCR/DMCR/NFC/QSPI)

With the help of the bus matrix, high-efficiency concurrent access from the host bus to the slave bus can be realized.

1.4.3 Reset Control (RMU)

The chip is configured with 15 reset modes.

- Power-on Reset (POR)
- NRST pin reset (NRST)
- Brown-out Reset (BOR)
- Programmable Voltage Detect 1 Reset (PVD1R)
- Programmable Voltage Detect 2 Reset (PVD2R)
- Watchdog Reset (WDTR)
- Special watchdog reset (SWDTR)
- Power-Down Wake-Up Reset (PDRST)
- Software Reset (SRST)
- MPU Error Reset (MPUR)
- RAM Parity Reset (RAMPR)
- RAMECC reset (RAMECCR)
- Clock Abnormal Reset (CKFER)
- External High Speed Oscillator Abnormal Shock Reset (XTALER)
- Cortex-M4 LOCKUP Reset (LKUPR)

1.4.4 Clock Control (CMU)

The clock control unit provides clock functions for a range of frequencies, including: One external high-speed oscillator, one external low-speed oscillator, two PLL clock, one internal high-speed oscillator, a Internal medium speed oscillator, one internal low-speed oscillator, an internal low-speed oscillator for RTC, an SWDT dedicated internal low-speed oscillator, Clock prescaler, clock multiplexing and clock gating circuit.

The clock control unit also provides a clock frequency measurement function. The clock frequency measurement circuit (FCM) monitors and measures the measurement target clock using the measurement reference clock. An interrupt or reset occurs when the setting range is exceeded.

The AHB, APB and Cortex-M4 clocks are all derived from the system clock, and the source of the system clock can be selected from 6 clock sources:

- 1) External high-speed oscillator (XTAL)
- 2) External low speed oscillator (XTAL32)
- 3) PLLH clock (PLLH)
- 4) Internal high-speed oscillator (HRC)
- 5) Internal Medium Speed Oscillator (MRC)

6) Internal low-speed oscillator (LRC)

The maximum operating clock frequency of the system clock can reach 240 MHz. SWDT has independent clock source: SWDT dedicated internal low-speed oscillator (SWDTLRC). The real-time clock (RTC) uses the external low-speed oscillator or the internal low-speed oscillator as the clock source. The 48 MHz clock of USB-FS can choose system clock, PLLH, PLLA as the clock source.

For each timer, you can turn it on and off separately when not in use to reduce power consumption.

1.4.5 Power Control (PWC)

Power controller is used to control the supply, switching and detection of multiple power domains in multiple operation modes and low power modes. The power controller is composed of a power consumption control logic (PWC), a power supply voltage detection unit (PVD), and a battery backup control module (BATBKUP) that automatically switches between VCC and battery power.

The chip's operating voltage (VCC) is 1.8V to 3.6V. The voltage regulator (LDO) powers the VDD domain and the VDDR domain, and the VDDR voltage regulator (RLDO) powers the VDDR domain in power-down mode or VCC power-down conditions. The chip provides two operating modes such as high-speed and ultra-low speed through the power control logic (PWC), and three low-power modes such as sleep, stop and power-down.

Power supply voltage detection unit (PVD) provides power-on reset (POR), power-down reset (PDR), brown-out reset (BOR), programmable voltage detection 1 (PVD1), programmable voltage detection 2 (PVD2), reference voltage Measurement path, VBAT voltage detection, VBAT voltage measurement and other functions, among which POR, PDR, BOR control the reset action of the chip by detecting the VCC voltage. PVD1 resets or interrupts the chip according to the register setting by detecting the VCC voltage. PVD2 generates reset or interrupt according to register selection by detecting VCC voltage or external input detection voltage. The reference voltage measurement path is the function of using the ADC to measure the reference voltage. VBAT voltage detection is the function of reading the register to get the VBAT voltage higher or lower than the VBAT detection voltage. The VBAT detection voltage can be selected by register to 1.8V or 2.0V. The VBAT voltage measurement function refers to the function of using the ADC to measure the 1/2 voltage of VBAT to obtain the VBAT voltage.

The battery backup domain maintains the power supply through VBAT under the condition of VCC power failure, which ensures that the real-time clock module (RTC) and the wake-up timer (WKTM) can continue to operate, and provide power for the RLDO. The VDDR area can maintain the power supply through RLDO when the chip enters the power-down mode or the VCC is powered down, and maintains the data of the 4KB backup SRAM (Backup-SRAM). The analog modules are equipped with dedicated power supply pins for improved analog performance.

1.4.6 Initialization Configuration (ICG)

After the chip reset is released, the hardware circuit will read the FLASH address 0x0000_0400 ~ 0x0000_045F and load the data into the initialization configuration register. Addresses 0x0000_0408 ~ 0x0000_040B, 0x0000_0410 ~ 0x0000_041F, 0x0000_0438 ~ 0x0000_045F are reserved functional areas, please write all 1s to ensure the normal operation of the chip. The user can modify the Initial Config register by programming or erasing sector 0. The address 0x0000_0420 ~ 0x0000_0437 is the data security protection enable area. The register reset value is determined by the FLASH address data.

1.4.7 Embedded FLASH Interface (EFM)

The FLASH interface accesses FLASH through ICODE, DCODE and MCODE buses, and can perform programming, erasing and full erasing operations on FLASH; code execution is accelerated through instruction prefetching and caching mechanisms.

Main features:

- 134Kbytes of OTP space
- ICODE bus 16Bytes prefetch
- Two independent buffers: ICODE bus buffer space 4Kbytes (256x128); DCODE bus buffer space 1Kbytes (64x128)
- Support data security protection

1.4.8 Built-in SRAM (SRAM)

This product has 4 KB power-down mode retention SRAM (SRAMB) and 512 KB system SRAM (SRAMH/ SRAM1/ SRAM2/ SRAM3/ SRAM4).

Each SRAM can be accessed in bytes, half words (16 bits) or full words (32 bits). High-speed SRAM (SRAMH) read and write operations can be executed at the fastest CPU speed (240 MHz) with 0 wait (ie 1 cycle), or a wait cycle can be inserted. The wait period for read and write access of each SRAM is set by the SRAM wait control register (SRAM_WTCR).

SRAMB can provide 4 KB data retention space in Power down mode.

SRAM4 and SRAMB are equipped with ECC check (Error Checking and Correcting). ECC check is correct one and check two codes, which can correct one bit error and check two bit errors; SRAMH/SRAM1/SRAM2/SRAM3 have parity check (Even-parity check), with one check bit per byte of data.

1.4.9 General IO (GPIO)

GPIO main features:

- Each port group has 16 I/O Pins, which may be less than 16 depending on actual configuration

- Support pull-up
- Support push-pull, open-drain output mode
- Supports high, medium and low drive modes
- Support for external interrupt input
- Support I/O pin peripheral function multiplexing, each I/O pin has up to 64 selectable multiplexing functions
- Individual I/O pins can be programmed independently
- Each I/O pin can select two functions to be active at the same time (two output functions are not supported to be active at the same time)

1.4.10 Interrupt Control (INTC)

The function of the interrupt controller (INTC) is to select the interrupt event request as an interrupt input to the NVIC to wake up the WFI; as an event input, to wake up the WFE. Select interrupt event request as wake-up condition for low power consumption mode (sleep mode and stop mode); interrupt control function of external pin EIRQ; interrupt/event selection function of software interrupt.

Main specifications:

- 1) NVIC interrupt vector: For the actual number of interrupt vectors used, please refer to the interrupt vector table in the user manual (excluding the 16 interrupt lines of Cortex™-M4F). Each interrupt vector can select the corresponding peripheral interrupt event request according to the interrupt selection register. For more instructions on exceptions and NVIC programming, please refer to Chapter 5 of the ARM Cortex™-M4F Technical Reference Manual: Exceptions and Chapter 8: Nested vectored interrupt controller.
- 2) Programmable priority: 16 programmable priority levels (4-bit interrupt priority levels are used).
- 3) Non-maskable interrupts: A variety of system interrupt event requests can be independently selected as non-maskable interrupts, and each interrupt event request is equipped with an independent enable selection, suspend, and clear the suspend register.
- 4) Equipped with 16 external pin interrupts.
- 5) Configure various peripheral interrupt event requests. For details, please refer to the list of interrupt event request numbers.
- 6) Equipped with 32 software interrupt event requests.
- 7) Interrupt wakes up system sleep mode and stop mode.

1.4.11 Automatic Operating System (AOS)

The Automatic Operation System is used to realize the linkage between peripheral hardware circuits without the aid of the CPU. Use the events generated by the peripheral circuit as the AOS source (AOS Source), such as the comparison match of the timer, the timing overflow, the periodic signal

of the RTC, the various states of the data sent and received by the communication module (idle, the received data is full, the sending data is over, Send data empty), ADC conversion ends, etc., to trigger other peripheral circuit actions. The peripheral circuit action that is triggered is called AOS Target (AOS Target).

1.4.12 Storage Protection Unit (MPU)

The MPU can provide memory protection and improve system security by preventing unauthorized access.

This chip has built-in six MPU units for the host and one MPU unit for the IP.

Among them, ARM MPU provides CPU access control to all 4G address space.

SMPU1/ SMPU2/ FMPU/ HMPU/ EMPU respectively provide system DMA_1/ system DMA_2/ USBFS-DMA/ USBHS-DMA/ ETH-DMA read and write access control to all 4G address space. When accessing the forbidden space, the MPU action can be set to ignore/bus error/non-maskable interrupt/reset.

IPMPU provides access control to system IP and security-related IP in unprivileged mode.

1.4.13 Keyboard Scanning (KEYSCAN)

This product is equipped with a keyboard control module (KEYSCAN) unit. The KEYSCAN module supports keyboard array (row and column) scanning, the column is driven by the independent scan output KEYOUT_m (m=0~7), and the row KEYIN_n (n=0~15) is input as EIRQ_n (n=0~15) be detected. This module realizes the key recognition function through the line scan query method.

1.4.14 Internal Clock Calibrator (CTC)

The Clock Trimming Controller (CTC) automatically calibrates the internal high-speed oscillator (HRC). Because the influence of working environment on HRC frequency may cause deviation, CTC can automatically adjust HRC frequency by hardware based on external high precision reference clock to obtain an accurate HRC clock.

The main features of CTC are as follows:

- Two external reference clock sources: XTAL, CTCREF
- 16-bit calibration counter for frequency measurement with heavy load function
- 8-bit calibration deviation and 6-bit calibration values for frequency calibration
- Error interrupt to prompt calibration failure

1.4.15 DMA Controller (DMA)

DMA is used to transfer data between memory and peripheral functional modules. It can exchange data between memory, between memory and peripheral functional modules and between peripheral functional modules without CPU involvement.

- DMA bus is independent of CPU bus and transmitted according to AMBA AHB-Lite bus protocol.
- With 2 DMA control units, a total of 16 independent channels, can independently operate different DMA transfer functions
- The startup source of each channel is configured through the independent trigger source selection register
- One block per request
- The data block is a minimum of one data and can be up to 1024 data
- The width of each data can be configured as 8bit, 16bit or 32bit
- Up to 65535 transmissions can be configured
- Source and destination addresses can be independently configured as fixed, increment, decrement, loop or jump at specified offset
- Three types of interrupts can be generated: Block transfer complete interrupt, transfer complete interrupt, transfer error interrupt. Each interrupt can be configured with a mask or not. Among them, the block transmission is completed, and the transmission completion can be used as an event output and can be used as a trigger source for other peripheral modules
- Support for linked transmission to enable multiple blocks of data to be transmitted at a time
- Support external event-triggered channel reset
- You can set the module stop state to reduce power consumption when not in use

1.4.16 Voltage Comparator (CMP)

The voltage comparator (Comparator, CMP for short) is a peripheral module that compares two analog voltages. There are three comparison channels CMP1~3.

CMP main features:

- CMP1~3 can be independently compared for voltage
- Window comparison can be completed when CMP1, 2 are used at the same time
- Both positive and negative terminal voltages have multiple input voltage sources for selection
- Optional sampling clock for digital noise filter
- The output can be switched on and off using the PWM waveform output by the timer
- Can generate events that trigger other peripherals to start
- Interrupt and wake-up from system stop mode
- The comparison result can be output to the external pin VCOU

1.4.17 Analog-to-Digital Converter (ADC)

12-bit ADC is an analog-to-digital converter with successive approximation. This MCU is equipped with 3 ADC units, each unit supports 16 channels, which can convert analog signals from external pins and inside the chip. Analog input channels can be arbitrarily combined into a sequence, a sequence can be single scan conversion, or continuous scan conversion. Supports continuous multiple conversions for any specified channel and averages the conversion results. The ADC

module is also equipped with an analog watchdog function, which monitors the conversion result of any specified channel and detects whether it exceeds the range set by the user.

ADC main characteristics:

- High performance
 - Configurable 12-bit, 10-bit and 8-bit resolution
 - ADC digital interface clock PCLK4 and conversion clock PCLK2 (Also called ADCLK) The frequency ratio can be set to 1:1, 2:1, 4:1, 8:1, 1:2, 1:4
PCLK2 can choose a PLL clock that is asynchronous with the system clock HCLK. At this time, the frequency is higher than
PCLK4:PCLK2=1:1
PCLK2 frequency supports up to 60 MHz
 - Sampling Rate: 2.5MSPS (PCLK2=60 MHz, 12 bits, sampling 11 cycles, conversion 13 cycles)
 - Independent programming of sampling time for each channel
 - Channel-independent data register
 - Data register configurable left/right justification
 - Continuous multiple conversion averaging function
 - Simulation watchdog, monitoring conversion results
 - The ADC module can be set to stop when not in use
- Analog input channel
 - Maximum 16 external analog input channels
 - 2 internal analog inputs: Internal reference voltage, divided by VBAT
- Conversion start condition
 - Software Setup Conversion Started
 - Start of Peripheral Device Synchronization Trigger Conversion
 - External Pin Triggering Start
- Conversion mode
 - 2 scan sequences A and B, optionally specifying a single or multiple channels
 - Sequence A single scan
 - Sequence A continuous scanning
 - Double sequence scanning, sequence A and B independently select trigger source, sequence B has higher priority than A
 - Cooperative mode (for devices with two or three ADCs)
- Interrupt and Event Signal Output
 - Sequence A Scan End Interrupt and Event ADC_EOCA
 - Sequence B Scan End Interrupt and Event ADC_EOCB
 - Simulation watchdog 0 comparing interrupt and event ADC_CMP0

- Simulation watchdog 1 comparing interrupt and event ADC_CMP1
- All four of these event outputs can start the DMA

This MCU is equipped with 2 unit programmable gain amplifiers PGA, the gain range of x2~x32 can be selected. The analog input can be amplified by the PGA circuit first, and then input to the ADC module for conversion.

This MCU is equipped with a sample-and-hold circuit SH dedicated to three units. When the dedicated sample and hold circuit is valid, each time the sequence starts, all SH valid channels are sampled at the same time, and then the ADC is started to perform A/D conversion on each channel in the sequence in turn. In continuous scan mode, the sequence inserts the SH sample time at the start of the second and subsequent scans.

1.4.18 Digital-to-Analog Converter (DAC)

This MCU is equipped with one 12-bit digital-to-analog voltage converter units DAC1. DAC unit contains two D/A conversion channels, which can be converted independently or synchronously converted by synchronous update of conversion data. Each conversion channel features an output amplifier that can directly drive an external load without an external op amp. Independent pin input reference voltages VREFH and VREFL can be used to improve conversion accuracy.

DAC main features:

- One DAC unit, with two D/A conversion channels
- 12-bit conversion data can be configured as left-aligned or right-aligned format
- Two conversion channels of the same DAC module can achieve simultaneous conversion
- Convert external data (from DCU) to output triangle wave and sawtooth wave
- Output amplification function, can directly drive external load
- A/D conversion priority mode reduces interference to A/D conversion
- Output available for voltage comparator as negative terminal voltage
- Independent pin input reference voltage VREFH/VREFL

1.4.19 Temperature Sensor (OTS)

The OTS can obtain the temperature inside the chip to support the reliable operation of the system. After using software or hardware to trigger and start the temperature measurement, OTS provides a set of digital quantities related to temperature, and the temperature value can be calculated through the calculation formula.

1.4.20 Advanced Control Timer (Timer6)

Advanced control timer 6 (Timer6) is a high-performance timer with a 32-bit count width, which can provide rich and flexible combinations and various interrupts, events, and PWM outputs in various complex application scenarios. The timer supports two waveform modes of sawtooth wave and triangle wave, and can generate various PWM waveforms (unilaterally aligned independent PWM,

bilaterally symmetrical independent PWM, bilaterally symmetrical complementary PWM, bilaterally asymmetrical PWM, etc.); software synchronization and Hardware synchronization (synchronous start, stop, clear, refresh, etc.); each reference value register supports buffer function (single-level buffer and double-level buffer); supports pulse width measurement and period measurement; supports 2-phase quadrature encoding and 3-phase positive Interchange coding; support EMB control. This series of products are equipped with 3-unit Timer6.

1.4.21 General Control Timer (Timer4)

General control timer 4 (Timer4) is a timer module for three-phase motor control. It provides three-phase motor control schemes for various applications. The timer supports triangular wave and sawtooth wave modes and generates various PWM waveforms. Supporting cache function; Support EMB control. 3 unit of Timer 4 is carried in this product family.

1.4.22 Emergency Brake Module (EMB)

The emergency braking module is a functional module that generates control events and outputs them to the timer when certain conditions are met, so as to control the timer to stop outputting PWM signals to external motors. The following factors are used to generate control events:

- Change of input level of external port
- Level of PWM output port occurs in phase (same high or same low)
- Voltage comparator comparison results
- External oscillator stop oscillation
- Write register software control

1.4.23 General Timer (TimerA)

General Timer A (Timer A) is a timer with 16-bit count width and 4 PWM outputs. The timer supports two waveform modes of triangular wave and sawtooth wave, and can generate various PWM waveforms (unilaterally aligned PWM, bilaterally symmetrical PWM); supports synchronous start of counters; compares the reference value register to support the buffer function; supports cascaded implementation between units 32 Bit counting; supports 2-phase quadrature encoding counting and 3-phase quadrature encoding counting. This series of products is equipped with 8 units of TimerA, which can achieve a maximum of 32 PWM outputs.

1.4.24 General Timer (Timer0)

General-purpose timer 0 (Timer0) is a basic timer that can realize synchronous counting and asynchronous counting. The timer contains 2 channels (CH-A and CH-B) that can generate compare match events during counting. The event can trigger interrupt, or can be output as an event to control other modules. This series of products is equipped with 2 units of Timer0.

1.4.25 Real Time Clock RTC

A real-time clock (RTC) is a counter that stores time information in BCD code format. Record specific calendar times from 00 to 99. Supports 12/24 hour two time systems, automatically calculates the number of days 28, 29 (leap year), 30 and 31 according to the month and year.

1.4.26 Watchdog Counter (WDT)

There are two watchdog counters, one is the dedicated watchdog counter (SWDT) whose counting clock source is dedicated internal RC (SWDTLRC: 10KHz), and the other is the general-purpose watchdog counter (WDT) whose counting clock source is PCLK3. Dedicated watchdogs and general purpose watchdogs are 16-bit down counters used to monitor software faults caused by external disturbances or unforeseen logic conditions that cause the application to deviate from normal operation.

Both watchdogs support the window function. The window interval can be preset before the count starts. When the count value is in the window interval, the counter can be refreshed and the count restarts.

1.4.27 Serial Communication Interface (USART)

This product is equipped with 8 units of Universal Serial Transceiver Module (USART). Universal Serial Transceiver Module (USART) can flexibly exchange full-duplex data with external devices; this USART supports Universal Asynchronous Serial Communication Interface (UART), Clock Synchronous Communication Interface, Smart Card Interface (ISO/ IEC7816-3) and LIN communication interface. Support modem operation (CTS/ RTS operation), multi-processor operation. Cooperate with Timer0 module to support UART receiving TIMEOUT function. USART_1 supports wake-up STOP mode function via RX line.

The specific function distribution is as follows:

- UART: Full channel support
- Multiprocessor Communication: Full channel support
- Clock synchronization communication: Full channel support
- RX line wake-up STOP mode function: USART_1 support
- Fractional baud rate: USART_1, USART_2, USART_3, USART_4, USART_6, USART_7 support
- LIN: USART_5, USART_10 support
- smart card: USART_1, USART_2, USART_3, USART_4, USART_6, USART_7 support
- UART receive timeout function: USART_1, USART_2, USART_6, USART_7 support

1.4.28 Inter-Integrated Circuit Bus (I2C)

I2C (Integrated Circuit Bus) is used as the interface between the microcontroller and the I2C serial bus. Provides multi-master mode function, which can control the protocol and arbitration of all I2C buses. Standard mode and fast mode are supported. SMBus is also supported.

I2C main features:

- 1) I2C bus mode and SMBUS bus mode are optional. Host mode and slave mode are optional. Various prepare times, hold times, and bus idle times relative to the transfer rate are automatically ensured.
- 2) The standard mode is up to 100 Kbps, and the fast mode is up to 400 Kbps.
- 3) The start condition, restart condition, and stop condition are automatically generated, and the start condition, restart condition, and stop condition of the bus can be detected.
- 4) Two slave mode addresses can be set. 7-bit address format and 10-bit address format can be set at the same time. Broadcast call address, SMBus host address, SMBus device default address, SMBus alarm address can be detected.
- 5) Answer bits can be automatically determined when sent. Answer bits can be sent automatically upon reception.
- 6) Handshake function.
- 7) Arbitration function.
- 8) A time-out function can detect that the SCL clock is stopped for a long time.
- 9) SCL input and SDA input have built-in digital filters that are programmable to filter.
- 10) Communication error, receive data full, send data empty, one frame send end, address match unanimously interrupt.

1.4.29 Serial Peripheral Interface (SPI)

SPI is equipped with six channel serial peripheral interface, which supports high-speed full-duplex serial synchronous transmission and convenient data exchange with peripheral equipment. Users can set the range of 3/4-wire, host/slave and baud rate as needed.

Table 1-2 SPI main features

Essentials	Description
Number of channels	1 channel
Serial communication function	<ul style="list-style-type: none"> • Supporting 4-wire SPI mode and 3-wire clock synchronization mode • Support full-duplex and only send two communication methods • Polarity and phase of adjustable communication clock SCK
Data format	<ul style="list-style-type: none"> • Selectable data shift order: MSB start/LSB start • Selectable data width:4/5/6/7/8/9/10/11/12/13/14/15/16/20/24/32 bit • A maximum of 32 bits of data can be transmitted or received in four frames
Baud rate	<ul style="list-style-type: none"> • In the host mode, the baud rate can be adjusted through the built-in dedicated baud rate generator. The baud rate range is the frequency division of PCLK1 by 2~256. • The maximum baud rate allowed in slave mode is PCLK1 divided by 6
data buffer	<ul style="list-style-type: none"> • with 16-byte data buffer area

Essentials	Description
	<ul style="list-style-type: none"> Support double buffering
Error monitoring	<ul style="list-style-type: none"> Mode fault error monitoring Data overload error monitoring Data underload error monitoring Parity error monitoring
Chip selection signal control	<ul style="list-style-type: none"> Each channel is configured with four chip select signal lines The relative timing relationship between the chip select signal and the communication clock can be adjusted The chip select signal inactive time between two consecutive communications can be adjusted Polarity adjustable
Transmission Control in Host Mode	<ul style="list-style-type: none"> Start transmission by writing data to the data register Communication auto-suspend function
Interrupt	<ul style="list-style-type: none"> Received data area full Sending data area is empty SPI error (mode/overload/underload/parity) SPI is vacant Transfer complete (event source only)
Low power control	Configurable module stop
Other functions	<ul style="list-style-type: none"> SPI initialization function

1.4.30 Four-Wire Serial Peripheral Interface (QSPI)

The Four-Wire Serial Peripheral Interface (QSPI) is a memory control module mainly used to communicate with a serial ROM with an SPI-compatible interface. Its objects mainly include serial flash memory, serial EEPROM and serial FeRAM.

1.4.31 Integrated Circuit Built-In Audio Bus (I2S)

I2S (Inter_IC Sound Bus), an integrated circuit built-in audio bus, which is dedicated to data transmission between audio devices.

Table 1-3 I2S main features

Function	Main characteristics
Communication mode	<ul style="list-style-type: none"> Supports full-duplex and half-duplex communication Support host mode or slave mode operation
Data format	<ul style="list-style-type: none"> Optional channel lengths: 16/32 bits Optional transmit data length: 16/24/32bits Data shift order: MSB starts
Baud rate	<ul style="list-style-type: none"> 8-bit programmable linear prescaler for precise audio sampling frequency Support sampling frequency 192 k, 96 k, 48 k, 44.1 k, 32 k, 22.05 k, 16k, 8 k Can output drive clock to drive external audio components, the ratio is fixed at 256*Fs (Fs is the audio sampling frequency)
Support I2S protocol	<ul style="list-style-type: none"> I2S Philips Standard MSB alignment criteria LSB alignment criteria PCM standard
data buffer	<ul style="list-style-type: none"> With 4-word deep, 32-bit wide input and output FIFO buffer area
Timer	<ul style="list-style-type: none"> Can use internal I2SCLK (UPLLQ/UPLLQ/UPLLQ/MPLLQ/MPLLQ/MPLLQ); can also be provided by an external clock on the I2S_EXCK pin
Interrupt	<ul style="list-style-type: none"> An interrupt is generated when the valid space of the send buffer reaches the alarm threshold An interrupt is generated when the valid space of the receive buffer reaches the alarm threshold The receive data area is full, there is still a write data request, and the receive overflows The send data area is empty and there is still a send request, send underflow

Function	Main characteristics
	<ul style="list-style-type: none"> The send data area is full and there is still a write data request, sending overflow

1.4.32 USB2.0 High Speed Module (USBHS)

This product is equipped with one unit of USB2.0 high-speed module (USBHS), built-in on-chip full-speed PHY, and supports ULPI (SDR) interface. USBHS is a dual role (DRD) controller that supports both slave and master functions. In host mode, USBHS supports high-speed, full-speed and low-speed transceivers, while in slave mode only high-speed and full-speed transceivers are supported. The USBHS controller supports all four transfer modes (control transfer, bulk transfer, interrupt transfer and isochronous transfer) defined by the USB 2.0 protocol. The USBHS controller supports LPM (Link Power Management) function.

1.4.33 USB2.0 Full Speed Module (USBFS)

The USB Full Speed (USBFS) controller provides a set of USB communication solutions for portable devices. The USBFS controller supports host mode and device mode, and the chip integrates a full-speed PHY. In host mode, the USBFS controller supports full-speed (FS, 12 Mb/s) and low-speed (LS, 1.5 Mb/s) transceivers, while in device mode only full-speed (FS, 12 Mb/s) transceivers are supported. The USBFS controller supports all four transfer modes defined by the USB 2.0 protocol (control transfer, bulk transfer, interrupt transfer, and isochronous transfer). The USBFS controller supports LPM (Link Power Management) function.

1.4.34 CAN2.0B Controller (CAN2.0B)

The CAN2.0B controller follows the CAN bus CAN2.0 (2.0A, CAN2.0B) protocol.

The CAN bus controller can handle data transmission and reception on the bus. In this product, the CAN2.0B controller has 16 sets of filters. Filters are used to select messages for an application to receive.

The application program in the CAN2.0B controller can send data to a high-priority primary transmit buffer (Primary Transmit Buffer, hereinafter referred to as PTB) and 3 secondary transmit buffers (Secondary Transmit Buffer, hereinafter referred to as STB). Bus, the sending scheduler determines the sending order of mailboxes. The bus data is acquired through 8 receive buffers (Receive Buffer, hereinafter referred to as RB). 3 STBs and 8 RBs can be understood as a 3-level FIFO and an 8-level FIFO, and the FIFO is completely controlled by hardware.

CAN2.0B bus controller can also support time-triggered CAN communication (Time-trigger communication).

1.4.35 SDIO Controller (SDIOC)

SDIOC provides an SD host interface and an MMC host interface for communicating with SD cards supporting SD2.0 protocol, SDIO devices and MMC devices supporting eMMC4.2 protocol. This

product has 2 SDIO controllers and can communicate with 2 SD/ MMC/ SDIO devices at the same time.

SDIOC features are as follows:

- Support SDSC, SDHC, SDXC format SD card and SDIO device
- Support one-line (1bit) and four-line (4bit) SD bus
- Support one-line (1bit), four-line (4bit) and eight-line (8bit) MMC bus
- SD clock up to 50MHz
- With card recognition and hardware write protection

1.4.36 Ethernet MAC Controller (ETHMAC)

The Ethernet MAC controller (ETHMAC) is used to send and receive data in accordance with the IEEE802.3-2002 standard in the Ethernet network, and has various application fields, such as switches, network interface cards, and so on. The MAC controller supports two industry standard interfaces to the external physical layer (PHY): Media Independent Interface (MII) (defined in the IEEE802.3 specification) and Reduced Media Independent Interface (RMII).

Mainly follow the following protocol specifications:

- IEEE802.3-2002 for Ethernet MAC
- IEEE1588-2008 standard for specifying networked clock synchronization
- AMBA2.0, used for AHB host/slave port
- RMII interface specification

1.4.37 External Memory Controller (EXMC)

The external memory controller EXMC (External Memory Controller) is an independent module used to access various off-chip memories and realize data exchange. EXMC can convert the internal AMBA protocol interface into various types of dedicated off-chip memory communication protocol interfaces through configuration, including SRAM, PSRAM, NOR Flash, NAND Flash and SDRAM. EXMC is divided into multiple sub-modules, each sub-module supports a specific memory type, and the user can control the external corresponding type of memory by configuring the registers of the sub-module.

1.4.38 Digital Video Interface (DVP)

The Digital Camera Interface (DVP) is a synchronous parallel interface that captures 8-, 10-, 12- or 14-bit high-speed data streams from an external CMOS camera module. Software synchronization and hardware synchronization are supported. Supports acquisition frequency control and window clipping control of data streams. Supports data stream capture in different formats such as monochrome or raw Bayer format/YCbCr4:2:2/RGB565 progressive video and compressed data (JPEG).

1.4.39 Cryptographic Coprocessing Module (CPM)

The encryption co-processing module (CPM) includes three sub-modules: AES encryption and decryption algorithm processor, HASH secure hash algorithm, and TRNG true random number generator.

The AES encryption and decryption algorithm processor follows the new data encryption standard officially announced by the National Institute of Standards and Technology (NIST) on October 2, 2000. The block length is fixed at 128 bits, and the key length supports 128/192/256 bits.

The HASH secure hash algorithm is the SHA-2 version of SHA-256 (Secure Hash Algorithm), which complies with the national standard "FIPS PUB 180-3" issued by the National Bureau of Standards and Technology of the United States. Produces 256-bit message digest output.

The TRNG true random number generator is a random number generator based on continuous analog noise, providing 64bit random numbers.

1.4.40 CRC Unit (CRC)

The CRC algorithm of this module complies with the definition of ISO/IEC 13239 and adopts 32-bit and 16-bit CRC respectively. The polynomial of CRC 32 is $X^{32} + X^{26} + X^{23} + X^{22} + X^{16} + X^{12} + X^{11} + X^{10} + X^8 + X^7 + X^5 + X^4 + X^2 + X + 1$, 32-bit initial value is "0xFFFFFFFF". The polynomial of CRC 16 is $X^{16} + X^{12} + X^5 + 1$, the initial value of 16 bits is "0xFFFF".

1.4.41 Data Computation Unit (DCU)

The Data Computing Unit is a module that simply processes data without the aid of a CPU. Each DCU unit has 3 data registers, capable of adding and subtracting 2 data and comparing sizes, as well as a window comparison function. It can also be triggered by a timer to provide a digital-to-analog conversion module (DAC) with continuously changing digital quantities to generate triangular wave and sawtooth wave output. This product is equipped with 8 DCU units, each unit can independently complete its own function.

1.4.42 Mathematical Operations Unit (MAU)

The Mathematical Operation Unit (MAU) is a hardware-accelerated operation module that includes two types of operations, the square root operation and the sine operation, and supports the square root and sine operations of fixed-point numbers. The sine function supports $360^\circ/2^{12}$ arithmetic precision.

1.4.43 Filter Math Accelerator (FMAC)

Filter Math Accelerator (FMAC) is a hardware acceleration module for FIR filter computation. This module can perform up to 16-order FIR digital filtering with configurable orders. Built-in 16x16 bit

multiplier, 32+5bit adder, users can customize the output data precision. This series is equipped with 4 FMAC modules.

1.4.44 Debug Controller (DBGC)

The core of this MCU is Cortex™-M4F, which contains hardware for advanced debug functions and supports Embedded Trace Macrocell (ETM). With these debugging features, you can stop the kernel when fetching fingers (instruction breakpoints) or accessing data (data breakpoints). When the kernel stops, you can query the internal state of the kernel and the external state of the system. After the query completes, the kernel and system are restored and program execution is restored.

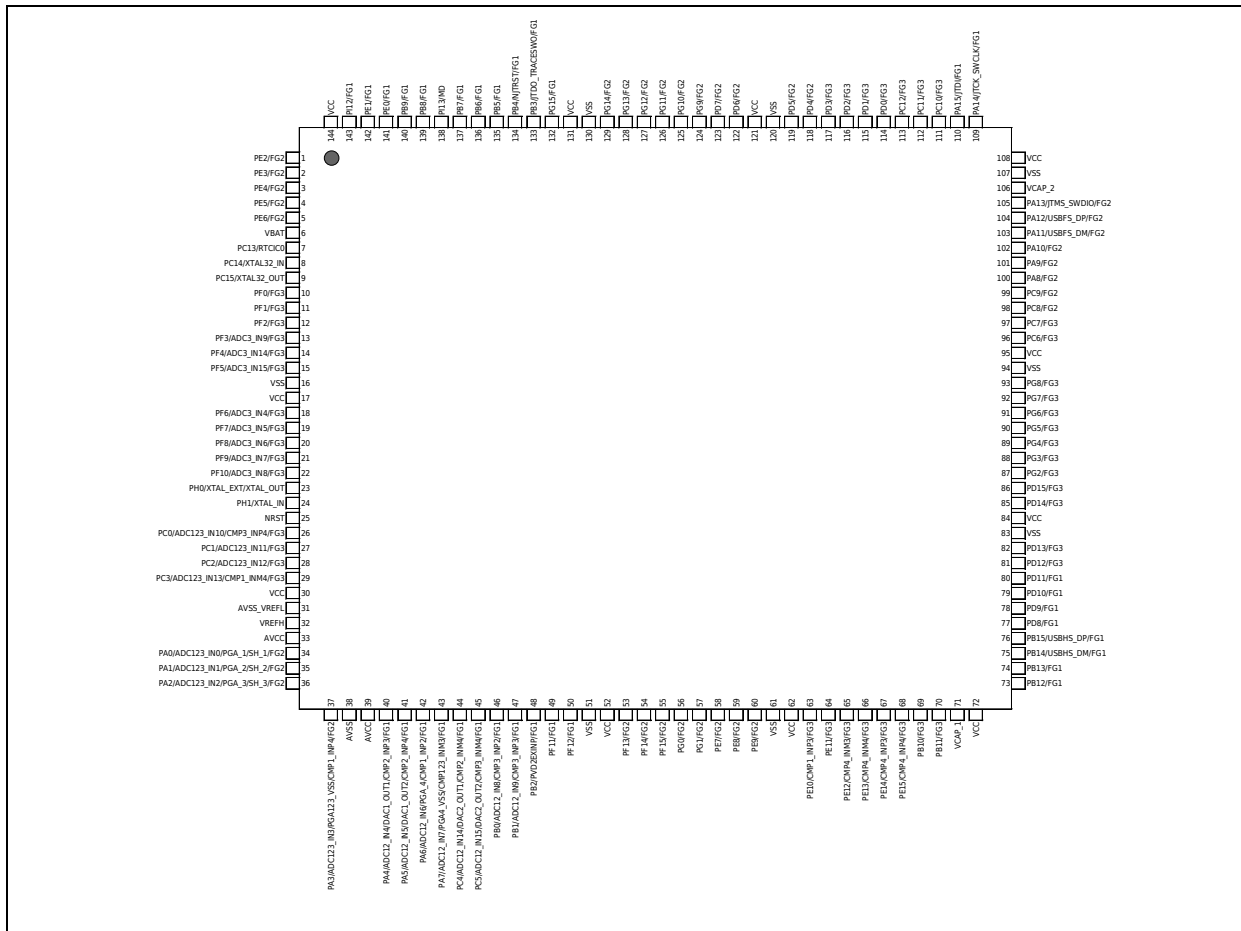
Provides two debugging interfaces:

- Serial Debugging Tracking Interface SWD
- Parallel Debug Trace Interface JTAG

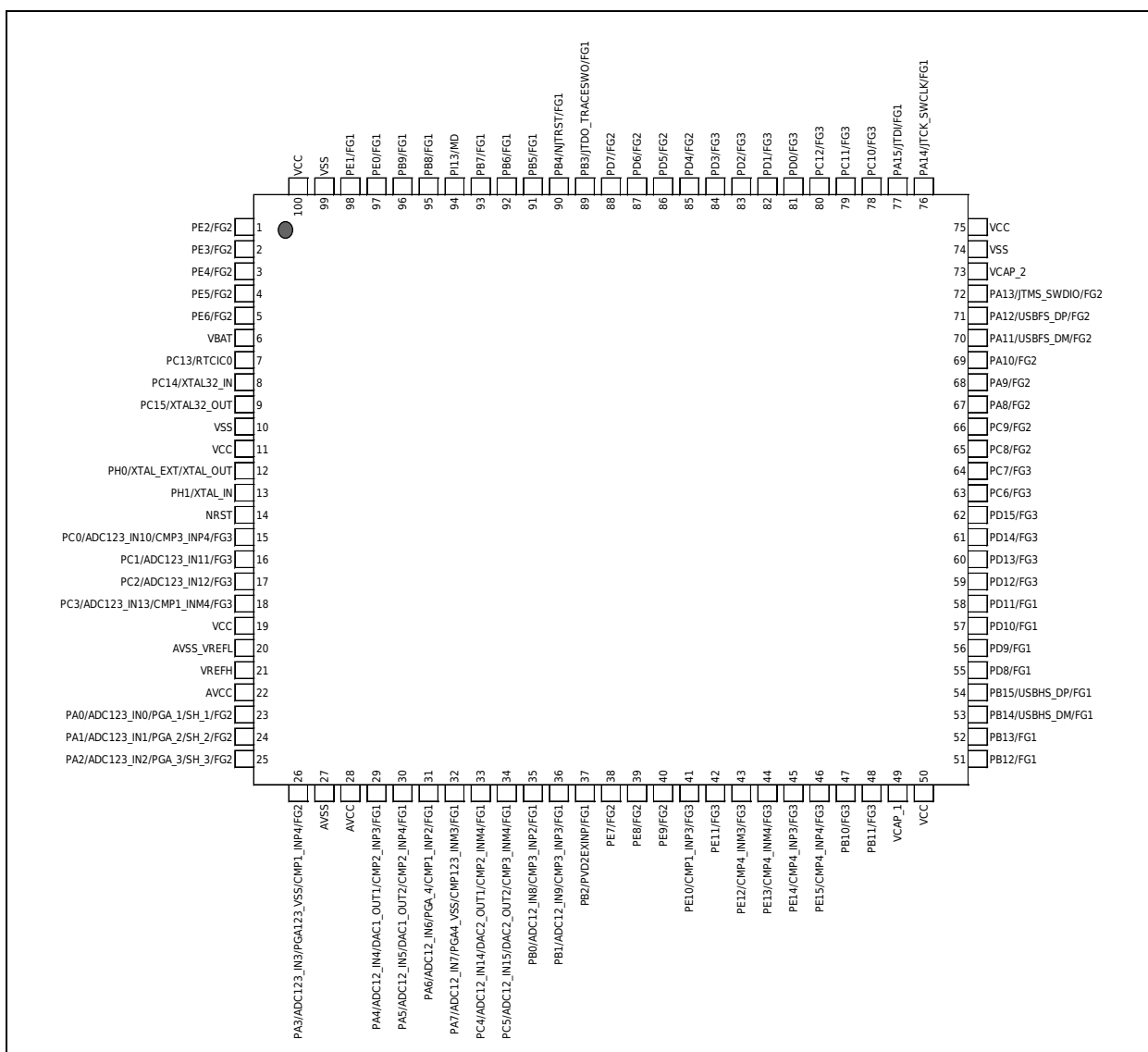
2 Pin Configuration and Functions (Pinouts)

2.1 Pin Configuration Diagram

LQFP144



LQPF100



LQPF64

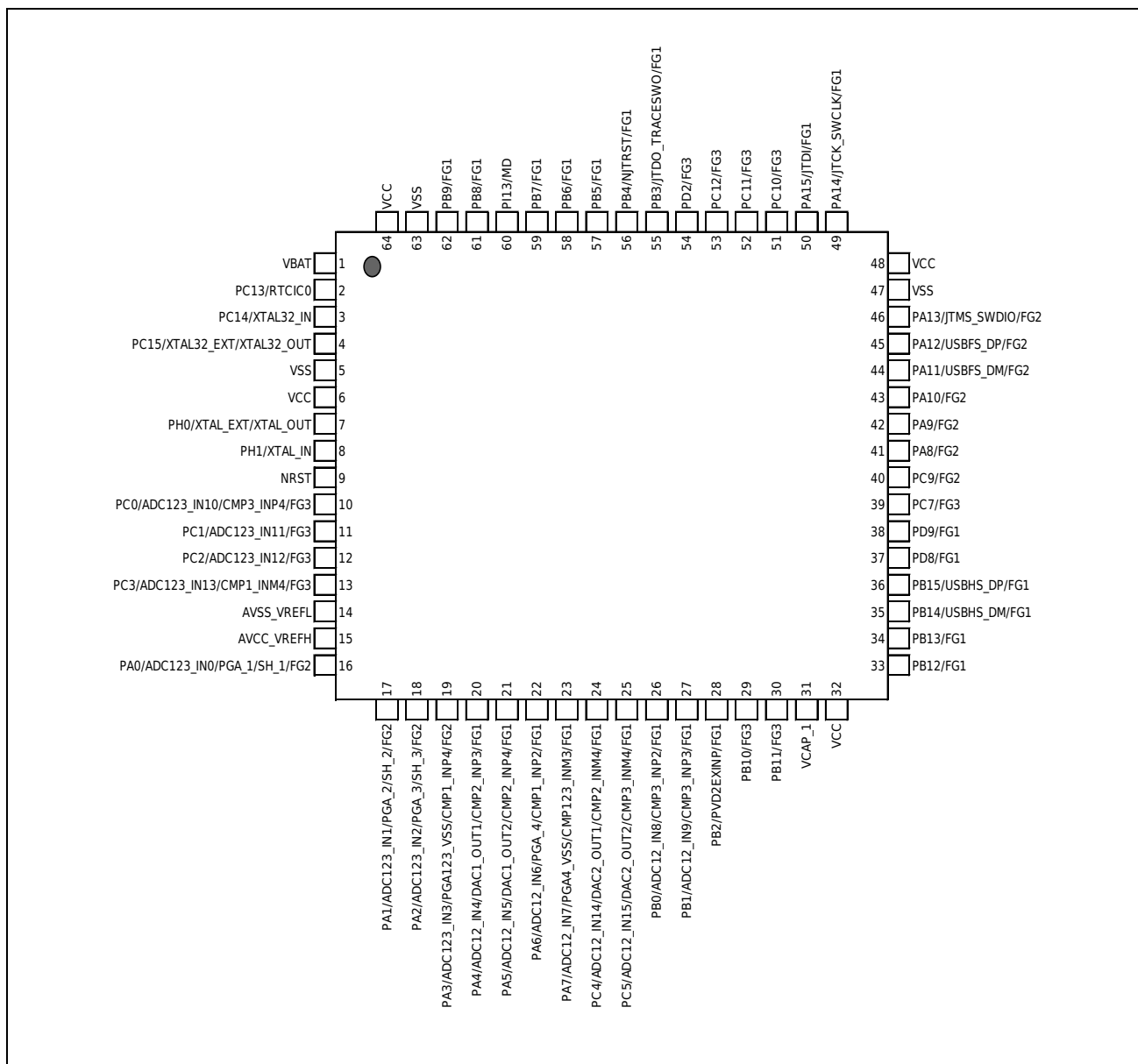


Figure 2-1 Pin configuration diagram

2.2 Pin Function Table

Table 2-1 Pin function table

LQFP 144	LQFP 100	LQFP 64	Pin Name	Analog	EIRQ /WKUP	TRACE /JTAG	Func0	Func1	Func2	Func3	Func4	Func5	Func6	Func7	Func8	Func9	Func10	Func11	Func12	Func13	Func14	Func15	Func16	Func17	Func18	Func19	Func20	Func21~31	Func32~63
							GPO		TIM4	TIM6	TIMA		EMB, TIM6, TIMA	USART	KEY	SDIO	USBFS, USBHS, TIM2	ETH	EXMC, USBHS	DVP	EVNTP31	EVENTOUT	TIM2, TIM4	I2S	SPI, QSPI	SPI	USART		Communication Function Group
1	1	-	PE2		EIRQ2	TRACE CLK	GPO	FCMRE F	TIM4_3_ADSM				TIMA_4_TRIG	USART 3_CK				ETH_MII_TXD3	EXMC_ADD 23			EVENTOUT		I2S3_MCK				FG2	
2	2	-	PE3		EIRQ3	TRACE D0	GPO					TIMA_4_PWM1/TIMA_4_CLKA		USART 6_CK				ETH_MII_RX_MII_TXEN	EXMC_ADD 19			EVENTOUT		I2S4_SD	SPI2_NSS0			FG2	
3	3	-	PE4		EIRQ4	TRACE D1	GPO					TIMA_4_PWM2/TIMA_4_CLKB		USART 6_CTS					EXMC_ADD 20	DVP_DATA 4		EVENTOUT				SPI4_NSS0		FG2	
4	4	-	PE5		EIRQ5	TRACE D2	GPO	CTCRE F				TIMA_4_PWM3		USART 6_RTS					EXMC_ADD 21	DVP_DATA 6		EVENTOUT						FG2	
5	5	-	PE6		EIRQ6	TRACE D3	GPO					TIMA_4_PWM4							EXMC_ADD 22	DVP_DATA 7		EVENTOUT						FG2	
6	6	1	VBAT																										
-	-	-	PI8	RTCIC1	EIRQ8		GPO															EVENTOUT							
7	7	2	PC13	RTCIC0	EIRQ13+WKUP3_1		GPO	RTC_OUT								SDIO2_CK						EVNTP31 3	EVENTOUT		I2S3_MCK				
8	8	3	PC14	XTAL32_IN	EIRQ14		GPO															EVNTP31 4	EVENTOUT						
9	9	4	PC15	XTAL32_EXT/XTAL32_OUT	EIRQ15		GPO															EVNTP31 5	EVENTOUT						
10	-	-	PF0		EIRQ0		GPO	MCO_1						USART 10_CK					EXMC_ADD 0			EVENTOUT				SPI3_NSS1			FG3
11	-	-	PF1		EIRQ1		GPO							USART 10_CTS					EXMC_ADD 1			EVENTOUT				SPI3_NSS2			FG3
12	-	-	PF2		EIRQ2		GPO							USART 10_RTS					EXMC_ADD 2			EVENTOUT				SPI3_NSS3			FG3
13	-	-	PF3	ADC3_IN9	EIRQ3		GPO												EXMC_ADD 3			EVENTOUT				SPI4_NSS1			FG3
14	-	-	PF4	ADC3_IN14	EIRQ4		GPO												EXMC_ADD 4			EVENTOUT				SPI4_NSS2			FG3
15	-	-	PF5	ADC3_IN15	EIRQ5		GPO												EXMC_ADD 5			EVENTOUT				SPI4_NSS3			FG3
16	10	5	VSS																										
17	11	6	VCC																										
18	-	-	PF6	ADC3_IN4	EIRQ6		GPO												EXMC_RB2			EVENTOUT				SPI5_NSS0	USART7_RX		FG3
19	-	-	PF7	ADC3_IN5	EIRQ7		GPO												EXMC_RB3			EVENTOUT		I2S4_MCK		SPI5_SCK	USART7_TX		FG3
20	-	-	PF8	ADC3_IN6	EIRQ8		GPO												EXMC_RB4			EVENTOUT				SPI5_MISO			FG3
21	-	-	PF9	ADC3_IN7	EIRQ9		GPO												EXMC_RB5	DVP_PIXCLK		EVENTOUT				SPI5_MOSI			FG3
22	-	-	PF10	ADC3_IN8	EIRQ10		GPO												EXMC_RB6	DVP_DATA 11		EVENTOUT							FG3
23	12	7	PH0	XTAL_EXT/XTAL_OUT	EIRQ0		GPO					TIMA_5_PWM3										EVENTOUT							
24	13	8	PH1	XTAL_IN	EIRQ1		GPO					TIMA_5_PWM4										EVENTOUT							
25	14	9	NRST																										
26	15	10	PC0	ADC123_I N10+CMP 3_INP4	EIRQ0		GPO				TIMA_8_PWM1/TIMA_8_CLKA		TIMA_1_TRIG			SDIO2_D5	USBHS_UL PI_STP		EXMC_WE			EVNTP30 0	EVENTOUT		I2S1_EXCK				FG3
27	16	11	PC1	ADC123_I N11	EIRQ1		GPO				TIMA_8_PWM2/TIMA_8_CLKB		TIMA_1_TRIG			SDIO2_D6		ETH_SMI_MDC				EVNTP30 1	EVENTOUT		I2S1_MCK				FG3
28	17	12	PC2	ADC123_I N12	EIRQ2		GPO		TIM4_2_ADSM		TIMA_8_PWM3		EMB_PORT3			SDIO2_D7	USBHS_UL PI_DIR	ETH_MII_TXD2	EXMC_CE0			EVNTP30 2	EVENTOUT		I2S1_SDIN		SPI2_MISO		FG3
29	18	13	PC3	ADC123_I N13+CMP 1_INM4	EIRQ3		GPO		TIM4_2_PCT		TIMA_8_PWM4					SDIO1_WP	USBHS_UL PI_NXT	ETH_MII_TXCLK	EXMC_ALE			EVNTP30 3	EVENTOUT				SPI2_MOSI		FG3
30	19	-	VCC																										
31	20	14	AVSS_VREFL																										
32	21	-	VREFH																										
-	-	15	AVCC_VREFH																										

LQFP 144	LQFP 100	LQFP 64	Pin Name	Analog	EIRQ /WKUP	TRACE /JTAG	Func0	Func1	Func2	Func3	Func4	Func5	Func6	Func7	Func8	Func9	Func10	Func11	Func12	Func13	Func14	Func15	Func16	Func17	Func18	Func19	Func20	Func21-31	Func32-63	
							GPO		TIM4	TIM6	TIMA	TIMA	EMB, TIM6, TIMA	USART	KEY	SDIO	USBFS, USBHS, TIM2	ETH	EXMC, USBHS	DVP	EVNTP1	EVENTOUT	TIM2, TIM4	I2S	SPI, QSPI	SPI	USART		Communication Function Group	
33	22	-	AVCC																											
34	23	16	PA0	ADC123_I N0+PGA_1	EIRQ0+WKUP0_0		GPO		TIM4_OUH	TIM6_T RIGC	TIMA_2_PWM1/TIMA_2_CLKA	TIMA_2_TRIG	TIMA_5_PWM1/TIMA_5_CLKA	USART_5_CTS		SDIO2_D4		ETH_MIL_C RS			EVNTP10_0	EVENTOUT	TIM4_2_CLK		SPI5_NSS1		USART2_C TS		FG2	
35	24	17	PA1	ADC123_I N1+PGA_2	EIRQ1		GPO		TIM4_2_OUL		TIMA_2_PWM2/TIMA_2_CLKB	TIMA_3_TRIG	TIMA_5_PWM2/TIMA_5_CLKB	USART_5_RTS		SDIO2_D5		ETH_MIL_R MII_RXCLK			EVNTP10_1	EVENTOUT			SPI5_NSS2		USART2_R TS		FG2	
36	25	18	PA2	ADC123_I N2	EIRQ2		GPO		TIM4_2_OVH		TIMA_2_PWM3	TIMA_5_PWM1/TIMA_5_CLKA	TIMA_5_PWM3			SDIO2_D6		ETH_SMI_MDI0			EVNTP10_2	EVENTOUT			SPI5_NSS3		USART2_T X		FG2	
-	-	-	PH2	ADC3_IN1_6	EIRQ2		GPO	FCMRE F	TIM4_2_CLK	TIM6_T RIGB						SDIO2_D4		ETH_MIL_C RS	EXMC_ALE					I2S3_EXCK					FG2	
-	-	-	PH3	ADC3_IN1_7	EIRQ3		GPO											ETH_MIL_C OL	EXMC_CE0										FG2	
-	-	-	PH4	ADC3_IN1_8	EIRQ4		GPO										USBHS_UL PI_NXT												FG2	
-	-	-	PH5	ADC3_IN1_9	EIRQ5		GPO												EXMC_WE							SPI5_NSS0			FG2	
37	26	19	PA3	ADC123_I N3+PGA1_2_VSS+CM P1_INP4	EIRQ3		GPO		TIM4_2_OVL		TIMA_2_PWM4	TIMA_5_PWM2/TIMA_5_CLKB	TIMA_5_PWM4			SDIO2_D7	USBHS_UL PI_D0	ETH_MIL_C OL			EVNTP10_3	EVENTOUT					USART2_R X		FG2	
38	27	-	AVSS																											
39	28	-	AVCC																											
40	29	20	PA4	ADC12_IN 4+DAC1_OUT1+CM P2_INP3	EIRQ4		GPO		TIM4_2_OWH				TIMA_8_TRIG	USART_5_CK	KEYOUT0				USBHS_SO F	DVP_HSYN C	EVNTP10_4	EVENTOUT		I2S1_EXCK		SPI1_NSS0	USART2_C K		FG1	
41	30	21	PA5	ADC12_IN 5+DAC1_OUT2+CM P2_INP4	EIRQ5		GPO		TIM4_2_OWL		TIMA_2_PWM1/TIMA_2_CLKA		TIMA_2_TRIG		KEYOUT1			USBHS_UL PI_CLK			EVNTP10_5	EVENTOUT	TIM4_2_OU L	I2S1_MCK					FG1	
42	31	22	PA6	ADC12_IN 6+CMP1_I NP2	EIRQ6		GPO					TIMA_3_PWM1/TIMA_3_CLKA	EMB_PORT2		KEYOUT2	SDIO1_CM D	TIM2_4_P WMA/TRIG A		EXMC_ADD 26	DVP_PIXCL K	EVNTP10_6	EVENTOUT							FG1	
43	32	23	PA7	ADC12_IN 7+CMP12_3_INM3	EIRQ7		GPO		TIM4_1_OUL	TIM6_1_PWMB	TIMA_7_PWM1/TIMA_7_CLKA	TIMA_3_PWM2/TIMA_3_CLKB	EMB_PORT3		KEYOUT3	SDIO2_WP	TIM2_4_P WMB/TRIG B	ETH_MIL_R MII_RXDV	EXMC_ADD 27		EVNTP10_7	EVENTOUT	TIM4_2_OU L						FG1	
44	33	24	PC4	ADC12_IN 14+CMP2_INM4	EIRQ4		GPO		TIM4_2_OUH					TIMA_7_TRIG	USART_1_CK			ETH_MIL_R MII_RXD0	EXMC_ADD 28		EVNTP30_4	EVENTOUT			SPI1_NSS1				FG1	
45	34	25	PC5	ADC12_IN 15+CMP3_INM4	EIRQ5		GPO		TIM4_2_OUL					EMB_PORT1				ETH_MIL_R MII_RXD1	EXMC_ADD 29		EVNTP30_5	EVENTOUT			SPI1_NSS2				FG1	
46	35	26	PB0	ADC12_IN 8+CMP3_I NP2	EIRQ0		GPO		TIM4_1_OVL	TIM6_2_PWMB	TIMA_7_PWM2/TIMA_7_CLKB	TIMA_3_PWM3		USART_4_CK	KEYOUT4	SDIO2_CM D	USBHS_UL PI_D1	ETH_MIL_R XD2			EVNTP20_0	EVENTOUT	TIM4_2_OV L		SPI1_NSS3				FG1	
47	36	27	PB1	ADC12_IN 9+CMP3_I NP3	EIRQ1+WKUP0_1		GPO		TIM4_1_OWL	TIM6_3_PWMB	TIMA_7_PWM3	TIMA_3_PWM4			KEYOUT5	SDIO2_D3	USBHS_UL PI_D2	ETH_MIL_R XD3			EVNTP20_1	EVENTOUT	TIM4_2_O WL	I2S2_EXCK	QSPI_NSS				FG1	
48	37	28	PB2	PVD2EXIN P	EIRQ2+WKUP0_2		GPO	VCOUT		TIM6_T RIGB	TIMA_7_PWM4			EMB_PORT1	USART_2_CK				EXMC_CLE	DVP_PIXCL K	EVNTP20_2	EVENTOUT		I2S2_MCK	QSPI_IO3				FG1	
49	-	-	PF11		EIRQ11		GPO		TIM4_2_PCT		TIMA_4_PWM1/TIMA_4_CLKA				USART_2_CTS				EXMC_OE	DVP_DATA 12						SPI5_MOSI			FG1	
50	-	-	PF12		EIRQ12		GPO		TIM4_2_ADSM		TIMA_4_PWM2/TIMA_4_CLKB				USART_2_RTS				EXMC_ADD 6										FG1	
51	-	-	VSS																											
52	-	-	VCC																											
53	-	-	PF13		EIRQ13		GPO			TIM6_1_PWM A	TIMA_4_PWM3								EXMC_ADD 7							SPI6_NSS3			FG2	
54	-	-	PF14		EIRQ14		GPO			TIM6_1_PWM B	TIMA_4_PWM4								EXMC_ADD 8								SPI6_NSS2			FG2
55	-	-	PF15		EIRQ15		GPO			TIM6_2_PWM A					USART_7_RTS				EXMC_ADD 9								SPI6_NSS1			FG2
56	-	-	PG0		EIRQ0		GPO			TIM6_2_PWM B					USART_7_CTS				EXMC_ADD 10											FG2
57	-	-	PG1		EIRQ1		GPO			TIM6_T RIGA					USART_7_CK				EXMC_ADD 11											FG2
58	38	-	PE7		EIRQ7		GPO	ADTRG 1	TIM4_1_CLK	TIM6_T RIGB	TIMA_1_TRIG	TIMA_3_PWM3			USART_1_CK				EXMC_DAT A4								SPI4_NSS1			FG2
59	39	-	PE8		EIRQ8		GPO	CTCRE F	TIM4_1_OUL	TIM6_1_PWMB	TIMA_7_PWM1/TIMA_7_CLKA	TIMA_3_PWM4							EXMC_DAT A5								SPI4_NSS2			FG2
60	40	-	PE9		EIRQ9		GPO	ADTRG 3	TIM4_1_OUH	TIM6_1_PWM A	TIMA_1_PWM1/TIMA_1_CLKA								EXMC_DAT A6								SPI4_NSS3			FG2
61	-	-	VSS																											
62	-	-	VCC																											
63	41	-	PE10	CMP1_INP 3	EIRQ10		GPO		TIM4_1_OVL	TIM6_2_PWMB	TIMA_7_PWM2/TIMA_7_CLKB								EXMC_DAT A7										FG3	
64	42	-	PE11		EIRQ11		GPO		TIM4_1_OVH	TIM6_2_PWM A	TIMA_1_PWM2/TIMA_1_CLKB	TIMA_3_PWM1/TIMA_3_CLKA					USBHS_UL PI_D7		EXMC_DAT A8										FG3	

LQFP 144	LQFP 100	LQFP 64	Pin Name	Analog	EIRQ /WKUP	TRACE /JTAG	Func0	Func1	Func2	Func3	Func4	Func5	Func6	Func7	Func8	Func9	Func10	Func11	Func12	Func13	Func14	Func15	Func16	Func17	Func18	Func19	Func20	Func21-31	Func32-63
							GPO		TIM4	TIM6	TIMA	TIMA	EMB, TIM6, TIMA	USART	KEY	SDIO	USBFS, USBHS, TIM2	ETH	EXMC, USBHS	DVP	EVNTP	EVENTOUT	TIM2, TIM4	I2S	SPI, QSPI	SPI	USART		Communication Function Group
65	43	-	PE12		EIRQ12		GPO		TIM4_1_OWL	TIM6_3_PWMB	TIMA_7_PWM3	TIMA_3_PWM2/TIMA_3_CLKB					USBHS_UL_P1_CLK		EXMC_DAT_A9			EVENTOUT			SPI1_NSS1			FG3	
66	44	-	PE13		EIRQ13		GPO		TIM4_1_OWH	TIM6_3_PWMA	TIMA_1_PWM3	TIMA_3_PWM3					USBHS_UL_P1_D0		EXMC_DAT_A10			EVENTOUT		I2S4_SDIN	SPI1_NSS2			FG3	
67	45	-	PE14		EIRQ14		GPO		TIM4_1_CLK		TIMA_1_PWM4	TIMA_3_PWM4				SDIO1_CD	USBHS_UL_P1_D1		EXMC_DAT_A11			EVENTOUT		I2S4_EXCK	SPI1_NSS3			FG3	
68	46	-	PE15		EIRQ15		GPO		TIM4_1_PCT	TIM6_T_RIGA	TIMA_7_PWM4	TIMA_5_TRIG	EMB_PORT2	USART10_CK		SDIO1_WP	USBHS_UL_P1_D2		EXMC_DAT_A12			EVENTOUT		I2S4_MCK				FG3	
69	47	29	PB10		EIRQ10		GPO	ADTRG2	TIM4_2_OVH		TIMA_2_PWM3					SDIO1_D7	USBHS_UL_P1_D3	ETH_MII_RXER			EVNTP21_0	EVENTOUT		I2S3_EXCK	QSPI_I02	SPI2_SCK		FG3	
70	48	30	PB11		EIRQ11		GPO		TIM4_1_ADSM		TIMA_2_PWM4		EMB_PORT2				USBHS_UL_P1_D4	ETH_MII_RXEN			EVNTP21_1	EVENTOUT						FG3	
71	49	31	VCAP_1																										
72	50	32	VCC																										
73	51	33	PB12		EIRQ12		GPO	VCOUT1	TIM4_2_OVL	TIM6_T_RIGB	TIMA_7_PWM4	TIMA_5_TRIG	EMB_PORT2	USART3_CK		SDIO2_D1	USBHS_UL_P1_D5	ETH_MII_RXER	USBHS_ID			EVNTP21_2	EVENTOUT		I2S3_MCK	QSPI_I01	SPI2_NSS0	FG1	
74	52	34	PB13		EIRQ13		GPO	VCOUT2	TIM4_1_OUL	TIM6_1_PWMB	TIMA_7_PWM1/TIMA_7_CLKA			USART3_CTS		SDIO2_D0	USBHS_UL_P1_D6	ETH_MII_RXEN	USBHS_VBUS			EVNTP21_3	EVENTOUT		QSPI_I00			FG1	
75	53	35	PB14	USBHS_DM	EIRQ14		GPO	VCOUT3	TIM4_1_OVL	TIM6_2_PWMB	TIMA_7_PWM2/TIMA_7_CLKB			USART3_RTS		SDIO1_D6	TIM2_2_PWM/TRIGA					EVNTP21_4	EVENTOUT	TIM4_2_OVL	I2S1_SDIN	QSPI_SCK		FG1	
76	54	36	PB15	USBHS_DP	EIRQ15		GPO	RTC_OUT	TIM4_1_OWL	TIM6_3_PWMB	TIMA_7_PWM3	TIMA_6_TRIG	EMB_PORT4	USART3_CK		SDIO1_CK	TIM2_2_PWM/TRIGB					EVNTP21_5	EVENTOUT	TIM4_2_OWL				FG1	
77	55	37	PD8		EIRQ8		GPO	VCOUT4	TIM4_3_OUL	TIM6_1_PWMB		TIMA_6_PWM1/TIMA_6_CLKA		USART1_CTS	KEYOUT7		USBHS_DR_VVBUS		EXMC_DAT_A13			EVNTP40_8	EVENTOUT		QSPI_I00			FG1	
78	56	38	PD9		EIRQ9		GPO	VCOUT3	TIM4_3_OVL	TIM6_2_PWMB	TIMA_2_PWM1/TIMA_2_CLKA	TIMA_6_PWM2/TIMA_6_CLKB	EMB_PORT3	USART1_RTS	KEYOUT6		USBHS_UL_P1_D4		EXMC_DAT_A14			EVNTP40_9	EVENTOUT		QSPI_I01			FG1	
79	57	-	PD10		EIRQ10		GPO	CAN2_TST_SAMPLE	TIM4_3_OVL	TIM6_3_PWMB	TIMA_2_PWM2/TIMA_2_CLKB	TIMA_6_PWM3		USART3_CK	KEYOUT5				EXMC_DAT_A15			EVNTP41_0	EVENTOUT		I2S2_EXCK	QSPI_I02		FG1	
80	58	-	PD11		EIRQ11		GPO	CAN2_TST_CLOCK	TIM4_3_CLK	TIM6_T_RIGB		TIMA_6_PWM4		USART3_CTS	KEYOUT4				EXMC_ADD_16			EVNTP41_1	EVENTOUT		I2S2_MCK	QSPI_I03		FG1	
81	59	-	PD12		EIRQ12		GPO		TIM4_1_ADSM		TIMA_4_PWM1/TIMA_4_CLKA			USART3_RTS					EXMC_ADD_17			EVNTP41_2	EVENTOUT					FG3	
82	60	-	PD13		EIRQ13		GPO		TIM4_1_PCT		TIMA_4_PWM2/TIMA_4_CLKB								EXMC_ADD_18			EVNTP41_3	EVENTOUT					FG3	
83	-	-	VSS																										
84	-	-	VCC																										
85	61	-	PD14		EIRQ14		GPO	ADTRG1			TIMA_4_PWM3								EXMC_DAT_A0			EVNTP41_4	EVENTOUT		I2S4_EXCK			FG3	
86	62	-	PD15		EIRQ15		GPO	ADTRG2			TIMA_4_PWM4								EXMC_DAT_A1			EVNTP41_5	EVENTOUT		I2S4_MCK			FG3	
87	-	-	PG2		EIRQ2		GPO	ADTRG3											EXMC_ADD_12									FG3	
88	-	-	PG3		EIRQ3		GPO												EXMC_ADD_13	DVP_DATA_10			EVENTOUT					FG3	
89	-	-	PG4		EIRQ4		GPO												EXMC_ADD_14	EXMC_ADD_16			EVENTOUT					FG3	
90	-	-	PG5		EIRQ5		GPO												EXMC_ADD_15	EXMC_ADD_17			EVENTOUT					FG3	
91	-	-	PG6		EIRQ6		GPO												EXMC_RB0	DVP_DATA_12			EVENTOUT					FG3	
92	-	-	PG7		EIRQ7		GPO												EXMC_RB1	DVP_DATA_13			EVENTOUT		I2S1_EXCK		USART6_CK	FG3	
93	-	-	PG8		EIRQ8		GPO											ETH_PPS_OUT	EXMC_CLK				EVENTOUT		I2S1_SDIN	SPI6_NSS0	USART6_RTS	FG3	
94	-	-	VSS																										
95	-	-	VCC																										
96	63	-	PC6		EIRQ6		GPO	CTCF	TIM4_2_OUH		TIMA_3_PWM1/TIMA_3_CLKA			KEYOUT3	SDIO1_D6					DVP_DATA_0	EVNTP30_6	EVENTOUT	TIM4_3_ADSM	I2S1_MCK	QSPI_SCK		USART6_TX	FG3	
97	64	39	PC7		EIRQ7		GPO		TIM4_2_OVH	TIM6_T_RIGD	TIMA_3_PWM2/TIMA_3_CLKB			KEYOUT2	SDIO1_D7				I2S2_EXCK	DVP_DATA_1	EVNTP30_7	EVENTOUT	TIM4_2_CLK	I2S2_MCK	QSPI_NSS		USART6_RX	FG3	
98	65	-	PC8		EIRQ8		GPO		TIM4_2_OWH		TIMA_3_PWM3			KEYOUT1	SDIO1_D0						DVP_DATA_2	EVNTP30_8	EVENTOUT		I2S2_MCK		USART6_CK	FG2	
99	66	40	PC9		EIRQ9		GPO	MCO_2	TIM4_2_OWL		TIMA_3_PWM4			KEYOUT0	SDIO1_D1	USBFS_DR_VVBUS		EXMC_CLE		DVP_DATA_3	EVNTP30_9	EVENTOUT		I2S3_EXCK				FG2	
100	67	41	PA8		EIRQ8+WKUP2_0		GPO	MCO_1	TIM4_1_OUH	TIM6_1_PWMA	TIMA_1_PWM1/TIMA_1_CLKA		TIMA_7_TRIG	USART4_CK		SDIO1_D1	USBFS_SF					EVNTP10_8	EVENTOUT		I2S3_MCK		USART1_CK	FG2	
101	68	42	PA9		EIRQ9+WKUP2_1		GPO		TIM4_1_OVH	TIM6_2_PWMA	TIMA_1_PWM2/TIMA_1_CLKB		TIMA_2_TRIG			SDIO1_D2	USBFS_VBUS				DVP_DATA_0	EVNTP10_9	EVENTOUT		I2S3_SDIN		USART1_TX	FG2	

LQFP 144	LQFP 100	LQFP 64	Pin Name	Analog	EIRQ /WKUP	TRACE /JTAG	Func0	Func1	Func2	Func3	Func4	Func5	Func6	Func7	Func8	Func9	Func10	Func11	Func12	Func13	Func14	Func15	Func16	Func17	Func18	Func19	Func20	Func21-31	Func32-63
							GPO		TIM4	TIM6	TIMA	TIMA	EMB, TIM6, TIMA	USART	KEY	SDIO	USBFS, USBHS, TIM2	ETH	EXMC, USBHS	DVP	EVNTP1	EVENTOUT	TIM2, TIM4	I2S	SPI, QSPI	SPI	USART		Communication Function Group
102	69	43	PA10		EIRQ10+WKUP2_2		GPO		TIM4_1_OVH	TIM6_3_PWMA	TIMA_1_PWM3	TIMA_5_TRIG				SDIO1_CD	USBFS_ID			DVP_DATA1	EVNTP110	EVENTOUT				USART1_RX		FG2	
103	70	44	PA11	USBFS_DM	EIRQ11+WKUP2_3		GPO		TIM4_1_CLK		TIMA_1_PWM4		EMB_PORT1	USART_4_CTS		SDIO2_CD					EVNTP111	EVENTOUT					USART1_CTS		FG2
104	71	45	PA12	USBFS_DP	EIRQ12+WKUP3_0		GPO		TIM4_3_OWL	TIM6_T_RIGA	TIMA_1_TRIG	TIMA_6_PWM1/TIMA_6_CLKA		USART_4_RTS		SDIO2_WP					EVNTP112	EVENTOUT	TIM4_1_CLK				USART1_RTS		FG2
105	72	46	PA13		EIRQ13	JTMS_WDIO	GPO			TIM6_T_RIGD	TIMA_8_PWM1/TIMA_8_CLKA	TIMA_6_PWM2/TIMA_6_CLKB				SDIO2_D3					EVNTP113	EVENTOUT			SPI2_NSS1			FG2	
106	73	-	VCAP_2																										
107	74	47	VSS																										
108	75	48	VCC																										
109	76	49	PA14		EIRQ14+WKUP3_2	JTCK_5_WCLK	GPO		TIM4_2_ADSM	TIM6_T_RIGC	TIMA_8_PWM2/TIMA_8_CLKB	TIMA_6_PWM3	TIMA_4_TRIG	USART_2_RTS		SDIO2_D2					EVNTP114	EVENTOUT		I2S1_EXCK	SPI2_NSS2			FG1	
110	77	50	PA15		EIRQ15+WKUP3_3	JTDI	GPO		TIM4_2_PCT	TIM6_T_RIGA	TIMA_2_PWM1/TIMA_2_CLKA	TIMA_6_PWM4	TIMA_2_TRIG	USART_2_CTS		SDIO2_D1					EVNTP115	EVENTOUT		I2S1_MCK	SPI2_NSS3	SPI1_NSS0		FG1	
111	78	51	PC10		EIRQ10		GPO	CAN1_TST_SAMPLE	TIM4_3_OUH		TIMA_8_PWM3	TIMA_5_PWM1/TIMA_5_CLKA		USART_2_CK		SDIO1_D2				DVP_DATA8	EVNTP310	EVENTOUT		I2S2_CK	SPI1_NSS1	SPI3_SCK	USART4_TX	FG3	
112	79	52	PC11		EIRQ11		GPO	CAN1_TST_CLOCK	TIM4_3_OVH		TIMA_8_PWM4	TIMA_5_PWM2/TIMA_5_CLKB			KEYOUT0	SDIO1_D3				DVP_DATA4	EVNTP311	EVENTOUT		I2S2_SDIN	SPI1_NSS2	SPI3_MISO	USART4_RX	FG3	
113	80	53	PC12		EIRQ12		GPO		TIM4_3_OVH		TIMA_4_TRIG	TIMA_5_PWM3		USART_3_CK	KEYOUT1	SDIO1_CK				DVP_DATA9	EVNTP312	EVENTOUT		I2S2_SD	SPI1_NSS3	SPI3_MOSI	USART5_TX	FG3	
114	81	-	PD0		EIRQ0		GPO	VCOUT	TIM4_3_OUL			TIMA_5_PWM4			KEYOUT2				EXMC_DAT_A2		EVNTP400	EVENTOUT							FG3
115	82	-	PD1		EIRQ1		GPO		TIM4_3_OVL		TIMA_3_TRIG				KEYOUT3				EXMC_DAT_A3		EVNTP401	EVENTOUT							FG3
116	83	54	PD2		EIRQ2		GPO	VCOUT_4	TIM4_3_OVL		TIMA_2_PWM4		TIMA_3_TRIG	USART_7_CTS	KEYOUT4	SDIO1_CM_D				DVP_DATA11	EVNTP402	EVENTOUT					USART5_RX	FG3	
117	84	-	PD3		EIRQ3		GPO	VCOUT_1					TIMA_6_TRIG	USART_5_CTS	KEYOUT5			EXMC_CLK	DVP_DATA5	EVNTP403	EVENTOUT				SPI2_SCK	USART2_CTS		FG3	
118	85	-	PD4		EIRQ4		GPO	VCOUT_2			TIMA_6_PWM1/TIMA_6_CLKA		EMB_PORT4	USART_5_RTS	KEYOUT6			EXMC_OE	DVP_DATA12	EVNTP404	EVENTOUT					USART2_RTS		FG2	
119	86	-	PD5		EIRQ5		GPO	VCOUT_3			TIMA_6_PWM2/TIMA_6_CLKB			USART_7_RTS	KEYOUT7			EXMC_WE		EVNTP405	EVENTOUT				SPI6_NSS1	USART2_TX		FG2	
120	-	-	VSS																										
121	-	-	VCC																										
122	87	-	PD6		EIRQ6		GPO	ADTRG_1	TIM4_2_CLK	TIM6_T_RIGC	TIMA_6_PWM3			USART_7_CK				EXMC_RB0	DVP_DATA10	EVNTP406	EVENTOUT			I2S2_SD	SPI6_NSS2	SPI3_MOSI	USART2_RX	FG2	
123	88	-	PD7		EIRQ7		GPO	ADTRG_2		TIM6_T_RIGD	TIMA_6_PWM4		EMB_PORT1	USART_5_CK				EXMC_CE0		EVNTP407	EVENTOUT				SPI6_NSS3	USART2_CK		FG2	
124	-	-	PG9		EIRQ9		GPO	ADTRG_3						USART_4_CK				EXMC_CE1	DVP_VSYN_C			EVENTOUT						FG2	
125	-	-	PG10		EIRQ10		GPO		TIM4_3_ADSM					USART_4_CTS				EXMC_CE2	DVP_DATA2			EVENTOUT						FG2	
126	-	-	PG11		EIRQ11		GPO		TIM4_3_PCT		TIMA_8_PWM1/TIMA_8_CLKA			USART_4_RTS				ETH_MII_R_MII_TXEN	EXMC_RB7	DVP_DATA3		EVENTOUT						FG2	
127	-	-	PG12		EIRQ12		GPO				TIMA_8_PWM2/TIMA_8_CLKB			USART_6_RTS				EXMC_CE3				EVENTOUT						FG2	
128	-	-	PG13		EIRQ13		GPO				TIMA_8_PWM3			USART_6_CTS				ETH_MII_R_MII_TXD0	EXMC_ADD24	DVP_VSYN_C		EVENTOUT						FG2	
129	-	-	PG14		EIRQ14		GPO		TIM4_3_ADSM		TIMA_8_PWM4							ETH_MII_R_MII_TXD1	EXMC_ADD25	DVP_DATA2		EVENTOUT		I2S3_EXCK				FG2	
130	-	-	VSS																										
131	-	-	VCC																										
132	-	-	PG15		EIRQ15		GPO		TIM4_3_PCT				TIMA_5_TRIG	USART_6_CTS				EXMC_BAA	DVP_DATA13			EVENTOUT		I2S3_MCK				FG1	
133	89	55	PB3		EIRQ3+WKUP0_3	JTDO_T_RACES_WO	GPO	FCMRE_F	TIM4_3_CLK	TIM6_T_RIGC	TIMA_2_PWM2/TIMA_2_CLKB					SDIO2_D0					EVNTP203	EVENTOUT						FG1	
134	90	56	PB4		EIRQ4+WKUP1_0	NJTRST	GPO		TIM4_3_OWL	TIM6_3_PWMB	TIMA_3_PWM1/TIMA_3_CLKA					SDIO1_D0				DVP_DATA13	EVNTP204	EVENTOUT		I2S2_SDIN				FG1	
135	91	57	PB5		EIRQ5+WKUP1_1		GPO	ADTRG_3	TIM4_3_OVH	TIM6_3_PWMA	TIMA_3_PWM2/TIMA_3_CLKB			SDIO1_D3	USBHS_ULPI_D7		ETH_PPS_OUT	EXMC_ALE	DVP_DATA10	EVNTP205	EVENTOUT		I2S4_EXCK	SPI3_NSS3			FG1		
136	92	58	PB6		EIRQ6+WKUP1_2		GPO	ADTRG_2	TIM4_3_OVL	TIM6_2_PWMB	TIMA_4_PWM1/TIMA_4_CLKA			SDIO2_CK			ETH_MII_T_XCLK	EXMC_CE1	DVP_DATA5	EVNTP206	EVENTOUT		I2S4_MCK	SPI3_NSS2			FG1		
137	93	59	PB7		EIRQ7+WKUP1_3		GPO	ADTRG_1	TIM4_3_OVH	TIM6_2_PWMA	TIMA_4_PWM2/TIMA_4_CLKB			SDIO1_D0			ETH_MII_T_XER	EXMC_ADV	DVP_VSYN_C	EVNTP207	EVENTOUT		I2S2_EXCK	SPI3_NSS1			FG1		
138	94	60	PI13/M_D				GPO							USART_3_TX															

LQFP 144	LQFP 100	LQFP 64	Pin Name	Analog	EIRQ /WKUP	TRACE /JTAG	Func0	Func1	Func2	Func3	Func4	Func5	Func6	Func7	Func8	Func9	Func10	Func11	Func12	Func13	Func14	Func15	Func16	Func17	Func18	Func19	Func20	Func21~31	Func32~63	
							GPO		TIM4	TIM6	TIMA	TIMA	EMB, TIM6, TIMA	USART	KEY	SDIO	USBFS, USBHS, TIM2	ETH	EXMC, USBHS	DVP	EVNTP20	EVENTOUT	TIM2, TIM4	I2S	SPI, QSPI	SPI	USART		Communication Function Group	
139	95	61	PB8		EIRQ8		GPO		TIM4_3_OUL	TIM6_1_PWMB	TIMA_4_PWM3			USART1_CK	KEYOUT7	SDIO1_D4	USBFS_DR VVBUS	ETH_MII_T XD3		DVP_DATA 6	EVNTP20 8	EVENTOUT		I2S2_MCK	SPI2_NSS0				FG1	
140	96	62	PB9		EIRQ9		GPO		TIM4_3_OUH	TIM6_1_PWMA	TIMA_4_PWM4	TIMA_6_TRIG		USART1_CTS	KEYOUT6	SDIO1_D5		ETH_MII_T XD2		DVP_DATA 7	EVNTP20 9	EVENTOUT		I2S2_SDIN	SPI2_NSS1	SPI2_NSS0			FG1	
141	97	-	PE0		EIRQ0		GPO	MCO_1	TIM4_3_PCT		TIMA_4_TRIG		TIMA_2_TRIG	USART1_RTS				ETH_MII_R MII_TXD1	EXMC_CE4	DVP_DATA 2		EVENTOUT			SPI2_NSS2				FG1	
142	98	-	PE1		EIRQ1		GPO	MCO_2	TIM4_3_CLK	TIM6_T RIGC								ETH_MII_R MII_TXD0	EXMC_CE5	DVP_DATA 3		EVENTOUT			SPI2_NSS3				FG1	
143	-	-	PI12		EIRQ12		GPO												EXMC_CLE											FG1
-	99	63	VSS																											
144	100	64	VCC																											

Note:

- In the above table, Func32~63 are mainly serial communication functions (including USART, SPI, I2C, I2S, CAN), which are divided into three groups of FunctionGroup, referred to as FG1, FG2, FG3. For details, please refer to Table 2-2 .

Table 2-2 Func32~63 table

	Func32	Func33	Func34	Func35	Func36	Func37	Func38	Func39	Func40	Func41	Func42	Func43	Func44	Func45	Func46	Func47
FG1	USART1_TX	USART1_RX	USART2_TX	USART2_RX	USART3_TX	USART3_RX	USART4_TX	USART4_RX	SPI1_SCK	SPI1_MOSI	SPI1_MISO	SPI2_SCK	SPI2_MOSI	SPI2_MISO	SPI3_SCK	SPI3_MOSI
FG2	USART4_TX	USART4_RX	USART5_TX	USART5_RX	USART6_TX	USART6_RX	USART7_TX	USART7_RX	SPI4_SCK	SPI4_MOSI	SPI4_MISO	SPI5_SCK	SPI5_MOSI	SPI5_MISO	SPI6_SCK	SPI6_MOSI
FG3	USART3_TX	USART3_RX					USART10_TX	USART10_RX	SPI1_SCK	SPI1_MOSI	SPI1_MISO	SPI4_SCK	SPI4_MOSI	SPI4_MISO	SPI4_NSS0	SPI1_NSS0

	Func48	Func49	Func50	Func51	Func52	Func53	Func54	Func55	Func56	Func57	Func58	Func59	Func60	Func61	Func62	Func63
FG1	SPI3_MISO	SPI3_NSS0	I2C1_SDA	I2C1_SCL	I2C3_SDA	I2C3_SCL	I2S1_CK	I2S1_WS	I2S1_SD	I2S2_CK	I2S2_WS	I2S2_SD	CAN1_TX	CAN1_RX	CAN2_TX	CAN2_RX
FG2	SPI6_MISO	SPI6_NSS0	I2C2_SDA	I2C2_SCL						I2S3_CK	I2S3_WS	I2S3_SD	CAN1_TX	CAN1_RX	CAN2_TX	CAN2_RX
FG3	I2C1_SDA	I2C1_SCL	I2C2_SDA	I2C2_SCL			I2S1_CK	I2S1_WS	I2S1_SD	I2S4_CK	I2S4_WS	I2S4_SD	CAN1_TX	CAN1_RX	CAN2_TX	CAN2_RX

Table 2-3 Port configuration

Package	Port Group	Bits																Pin Count	
		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	Total	
LQFP144	PortA	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	116
	PortB	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortC	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortD	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortF	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortG	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	
	PortH	-	-	-	-	-	-	-	-	-	-	-	-	-	-	0	0	2	
	PortI	-	-	0	0	-	-	-	-	-	-	-	-	-	-	-	-	2	
LQFP100	PortA	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	83	
	PortB	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16		
	PortC	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16		
	PortD	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16		
	PortE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16		
	PortH	-	-	-	-	-	-	-	-	-	-	-	-	-	-	0	0		2
	PortI	-	-	0	-	-	-	-	-	-	-	-	-	-	-	-	-		1
LQFP64	PortA	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16	52	
	PortB	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	16		
	PortC	0	0	0	0	0	0	0	-	0	-	0	0	0	0	0	14		
	PortD	-	-	-	-	-	-	0	0	-	-	-	-	-	0	-	3		
	PortH	-	-	-	-	-	-	-	-	-	-	-	-	-	-	0	0		2
	PortI	-	-	0	-	-	-	-	-	-	-	-	-	-	-	-	-		1
		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		

Table 2-4 General Functional Specifications

Port		Pull up	Open drain output	Drive capability	5V withstand voltage
PortA	PA3~PA5 PA7~PA10 PA13~PA15	Support	Support	Low, Medium, High	Support
	PA0, PA1, PA2, PA6, PA11, PA12	Support	Support	Low, Medium, High	not support
PortB	PB0~PB13	Support	Support	Low, Medium, High	Support
	PB14, PB15	Support	Support	Low, Medium, High	not support
PortC	PC0~PC15	Support	Support	Low, Medium, High	Support
PortD	PD0~PD15	Support	Support	Low, Medium, High	Support
PortE	PE0~PE15	Support	Support	Low, Medium, High	Support
PortF	PF0~PF15	Support	Support	Low, Medium, High	Support
PortG	PG0~PG15	Support	Support	Low, Medium, High	Support
PortH	PH0~PH1	Support	Support	Low, Medium, High	Support
PortI	PI13	Support	Support	Low, Medium, High	Support

Note:

- When used as an analog function, the input voltage must not be higher than VREFH/ AVCC.

2.3 Pin Function Description

Table 2-5 Pin function description

Categories	Functional name	I/O	Note
Power	VCC	I	Power supply
	VSS	I	Source ground
	VCAP_x (x=1~2)	-	Core voltage
	AVCC	I	Analog power
	VREFH	I	Analog reference voltage
	AVCC_VREFH	I	Analog reference voltage
	AVSS	I	analog power ground
	VREFL	I	Analog reference voltage
	AVSS_VREFL	I	Analog power ground, reference ground shared pin
	VBAT	I	Backup battery power
System	NRST	I	Reset terminal, low effective
	MD	I	Mode terminal
PVD	PVD2EXINP	I	PVD2 external input compare voltage
Clock	XTAL_IN	I	External high-speed oscillator interface
	XTAL_EXT/ XTAL_OUT	IO	External high-speed clock input/external high-speed oscillator interface
	XTAL32_IN	I	External low-speed clock input/external low-speed oscillator interface
	XTAL32_EXT/ XTAL32_OUT	IO	
	MCO_x (x=1~2)	O	Internal clock output
GPIO	GPIOxy (x=A~I y=0~15)	IO	General input/output
EVENTOUT	EVENTOUT	O	Cortex-M4 CPU event output
EIRQ	EIRQx (x=0~15)	I	Shielded external interrupt
	WKUPx_y (x=0~3 y=0~3)	I	PowerDown mode external wake-up input
Event Port	EVNTPxy (x=1~4 y=0~15)	IO	Event port input and output function
Key	KEYOUTx(x=0~7)	O	KEYSCAN scan output signal
JTAG/SWD	JTCK_SWCLK	I	Online debugging interface
	JTMS_SWDIO	IO	
	JTDO_TRACESWO	O	
	JTDI	I	
	NJTRST	I	
TRACE	TRACECLK	O	Trace debug sync clock output
	TRACEDx (x=0~3)	O	Trace debug data output
FCM	FCMREF	I	External reference clock input for clock frequency measurement
RTC	RTC_OUT	O	1Hz clock output
	RTCICx (x=0~1)	I	Timestamp event input
Timer4	TIM4_x_CLK	I	Counting clock port input

Categories	Functional name	I/O	Note
(x=1~3)	TIM4_x_OUH	IO	PWM port U-phase output
	TIM4_x_OUL	IO	PWM port U-phase output
	TIM4_x_OVH	IO	PWM port V-phase output
	TIM4_x_OVL	IO	PWM port V-phase output
	TIM4_x_OWH	IO	PWM port W-phase output
	TIM4_x_OWL	IO	PWM port W-phase output
	TIM4_x_ADSM	O	Dedicated event output monitoring
	TIM4_x_PCT	O	PWM period output monitoring
Timer6 (x=1~3)	TIM6_TRIGA	I	External event trigger A input
	TIM6_TRIGB	I	External event trigger B input
	TIM6_TRIGC	I	External event trigger C input
	TIM6_TRIGD	I	External event trigger D input
	TIM6_x_PWMA	IO	External Event Trigger Input or PWM Port Output
	TIM6_x_PWMB	IO	External Event Trigger Input or PWM Port Output
TimerA (x=1~8)	TIMA_x_TRIG	I	External event trigger input
	TIMA_x_PWM1/TIMA_x_CLKA	IO	External event trigger input or PWM port output or count clock port input
	TIMA_x_PWM2/TIMA_x_CLKB	IO	External event trigger input or PWM port output or count clock port input
	TIMA_x_PWM _y (y=3~4)	IO	External Event Trigger Input or PWM Port Output
EMB	EMB_PORT _x (x=1~4)	I	Port input control signal
USART _x (x=1~7,10)	USART _x _TX	IO	Send data
	USART _x _RX	IO	Receiving data
	USART _x _CK	IO	Communication clock
	USART _x _RTS	O	request to send signal
	USART _x _CTS	I	clear to send signal
SPI _x (x=1~6)	SPI _x _MISO	IO	Primary input/secondary output data transfer pin
	SPI _x _MOSI	IO	Primary output/slave input data transfer pin
	SPI _x _SCK	IO	Transmission clock
	SPI _x _NSS0	IO	Select input/output pin from machine
	SPI _x _NSS _y (y=1~3)	O	Slave select output pin
QSPI	QSPI_IO _x (x=0~3)	IO	Data line
	QSPI_SCK	O	clock output
	QSPI_NSS	O	Slave selection
I2C _x (x=1~3)	I2C _x _SCL	IO	Clock line
	I2C _x _SDA	IO	Data line
I2S _x (x=1~4)	I2S _x _SD	IO	Serial data
	I2S _x _SDIN	I	Full-duplex serial data input
	I2S _x _WS	IO	word choice
	I2S _x _CK	IO	Serial clock

Categories	Functional name	I/O	Note
	I2Sx_EXCK	I	External timer
	I2Sx_MCK	O	master clock
CANx (x=1~2)	CANx_TX	O	Send data
	CANx_RX	I	Receiving data
SDIOx (x=1~2)	SDIOx_Dy (y=0~7)	IO	SD data signal
	SDIOx_CK	O	SD clock output signal
	SDIOx_CMD	IO	SD command and reply signal
	SDIOx_CD	I	SD card identification status signal
	SDIOx_WP	I	SD card write protection status signal
USB_FS	USBFS_DM	IO	USBFS on-chip full-speed PHY D-signal
	USBFS_DP	IO	USBFS on-chip full-speed PHY D+ signal
	USBFS_VBUS	I	USBFS VBUS signal
	USBFS_ID	I	USBFS ID signal
	USBFS_SOF	O	USBFS SOF pulse output signal
	USBFS_DRVVBUS	O	USBFS VBUS driver permission signal
USB_HS	USBHS_DP	IO	USBHS on-chip full-speed PHY D+ signal
	USBHS_DM	IO	USBHS on-chip full-speed PHY D-signal
	USBHS_VBUS	I	USBHS VBUS signal
	USBHS_ID	I	USBHS ID signal
	USBHS_SOF	O	USBHS SOF pulse output signal
	USBHS_DRVVBUS	O	USBHS VBUS drive enable signal
	USBHS_ULPI_CLK	I	ULPI interface clock signal
	USBHS_ULPI_DIR	I	ULPI interface dir signal
	USBHS_ULPI_STP	O	ULPI interface stp signal
	USBHS_ULPI_NXT	I	ULPI interface nxt signal
	USBHS_ULPI_Dx (x=0~7)	IO	ULPI interface data signal
ETHMAC	ETH_SMI_MDC	O	SMI interface clock
	ETH_SMI_MDIO	IO	SMI interface data
	ETH_PPS_OUT	IO	PPS output
	ETH_MII_RMII_RXCLK	I	MII receive action clock or RMII reference clock
	ETH_MII_RMII_RXDV	I	MII receive data valid or RMII receive data valid
	ETH_MII_RMII_RXD0	I	MII receive data 0 or RMII receive data 0
	ETH_MII_RMII_RXD1	I	MII receive data 1 or RMII receive data 1
	ETH_MII_RMII_TXEN	O	MII transmit data enable or RMII transmit data enable
	ETH_MII_RMII_TXD0	O	MII sends data 0 or RMII sends data 0
	ETH_MII_RMII_TXD1	O	MII send data 1 or RMII send data 1
	ETH_MII_RXD2	I	MII receive data 2
	ETH_MII_RXD3	I	MII receive data 3

Categories	Functional name	I/O	Note
	ETH_MII_RXER	I	MII receive data error
	ETH_MII_TXCLK	I	MII send action clock
	ETH_MII_TXD2	O	MII send data 2
	ETH_MII_TXD3	O	MII send data 3
	ETH_MII_TXER	O	MII send data error
	ETH_MII_COL	I	MII carrier sense
	ETH_MII_CRS	I	MII collision detection
CMP	VCOUT1	O	CMP1 result output
	VCOUT2	O	CMP2 result output
	VCOUT3	O	CMP3 result output
	VCOUT	O	CMP1~3 result OR output
	CMPx_INPy (x=1~3 y=2~4)	I	CMPx positive analog input
	CMPx_INM4 (x=1~3)	I	CMPx negative terminal analog input
	CMP123_INM3	I	CMP1,2,3 negative terminal analog input
ADC	ADTRG1	I	ADC1 AD conversion external startup source
	ADTRG2	I	ADC2 AD conversion external startup source
	ADTRG3	I	ADC3 AD conversion external startup source
	ADC123_INx (x=0~3,10~13)	I	ADC1,2,3 share external analog input port
	ADC12_INx (x=4~9,14,15)	I	ADC1,2 share external analog input port
	ADC3_INx (x=4~9,14,15)	I	ADC3 external analog input port
	PGA1/2_VSS	I	PGA1~2 Ground input
DAC	DACx_OUTy (x=1 y=1,2)	O	DAC analog output
DVP	DVP_HSYNC	I	Line sync input port
	DVP_VSYNC	I	Frame sync input port
	DVP_PIXCLK	I	clock input port
	DVP_DATAx (x=0~13)	I	data input port
EXMC	EXMC_CLK	IO	For details, please refer to the EXMC Port Function Assignment Table in the External Memory Controller chapter of the reference manual.
	EXMC_OE	O	
	EXMC_WE	O	
	EXMC_CLE	O	
	EXMC_ALE	O	
	EXMC_BAA	O	
	EXMC_ADV	O	
	EXMC_CEx (x=0~7)	O	
	EXMC_RBx(x=0~7)	I	
	EXMC_ADDx (x=0~29)	O	
	EXMC_DATAx (x=0~31)	IO	

2.4 Pin Instruction

Table 2-6 Pin instructions

Pin name	Usage notes
VCC	Power supply, connect to 1.8 V~3.6 V voltage, and connect a decoupling capacitor to the VSS pin nearby (refer to [Electrical Characteristics (ECs)])
VSS	Source ground, connected to 0V
VBAT	Backup power, connected to battery or other powered device Short-circuit with VCC when not in use, and connect an external 100nF decoupling capacitor
VCAP_x (x=1~2)	Core voltage, connected to VSS pin to stabilize core voltage (refer to [Electrical Characteristics (ECs)])
AVCC	Analog power supply, supply power to the analog module, connect to the same voltage as VCC (refer to [Electrical Characteristics (ECs)]) When not using the analog module, please short-circuit with VCC
AVSS	Analog power ground, supply power to the analog module, connect to the same voltage as VSS (refer to [Electrical Characteristics (ECs)]) When not using analog module, please short circuit with VSS
VREFL	Analog reference voltage, connected to the same voltage as AVSS (refer to [Electrical Characteristics (ECs)]) When not using analog module, please short circuit with AVSS
VREFH	Analog reference voltage, connected to a voltage not higher than AVCC When not using ADC, please short to AVCC
PI13/MD	mode input. When the reset pin (NRST) is released (from low level to high level), this pin must be fixed to low level. It is recommended to connect a resistor (4.7kΩ) to VSS (pull down)
NRST	Reset pin, low effective. Connect a resistor to VCC when not in use (pull-up)
Pxy (x=A~I y=0~15)	General pin. When used as an input function, the input voltage of pins that support 5 V withstand voltage should not exceed 5V, internal pull-up is forbidden when the input voltage exceeds VCC, and the input voltage of pins that do not support 5 V withstand voltage should not exceed VCC. When used as an analog input, the analog voltage should not exceed VREFH/AVCC Float when not in use, or connect a resistor to VCC (pull-up)/VSS (pull-down)

3 Electrical Characteristics (ECs)

3.1 Parameter Conditions

All voltages are V_{SS} -based unless otherwise specified.

3.1.1 Minimum and Maximum

Unless otherwise specified, the minimum and maximum values of all devices are guaranteed by design or performance tests at worst ambient temperature, supply voltage and clock frequency.

3.1.2 Typical Value

Unless otherwise specified, typical data are analyzed by design or characterization at $T_A = 25\text{ }^\circ\text{C}$, $V_{CC} = 3.3\text{ V}$.

3.1.3 Typical Curve

Unless otherwise specified, all typical curves are not tested for design reference only.

3.1.4 Load Capacitance

The load conditions used to measure the pin parameters are shown in Figure 3-1 (left).

3.1.5 Pin Input Voltage

The measurement method for the input voltage at the device pins is shown in Figure 3-1 (right).

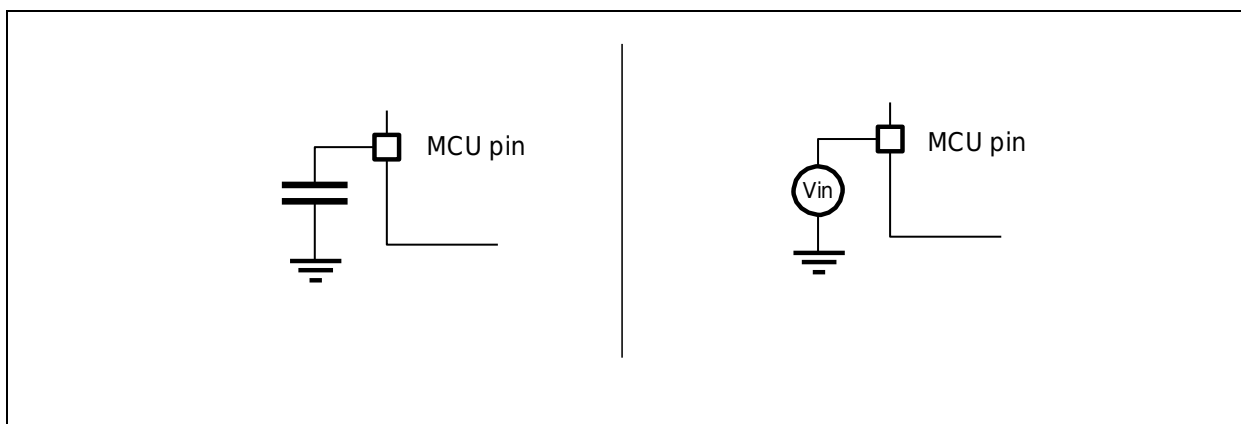


Figure 3-1 Pin Load Condition (Left) vs Input Voltage Measurement (right)

3.1.6 Power Supply Scheme

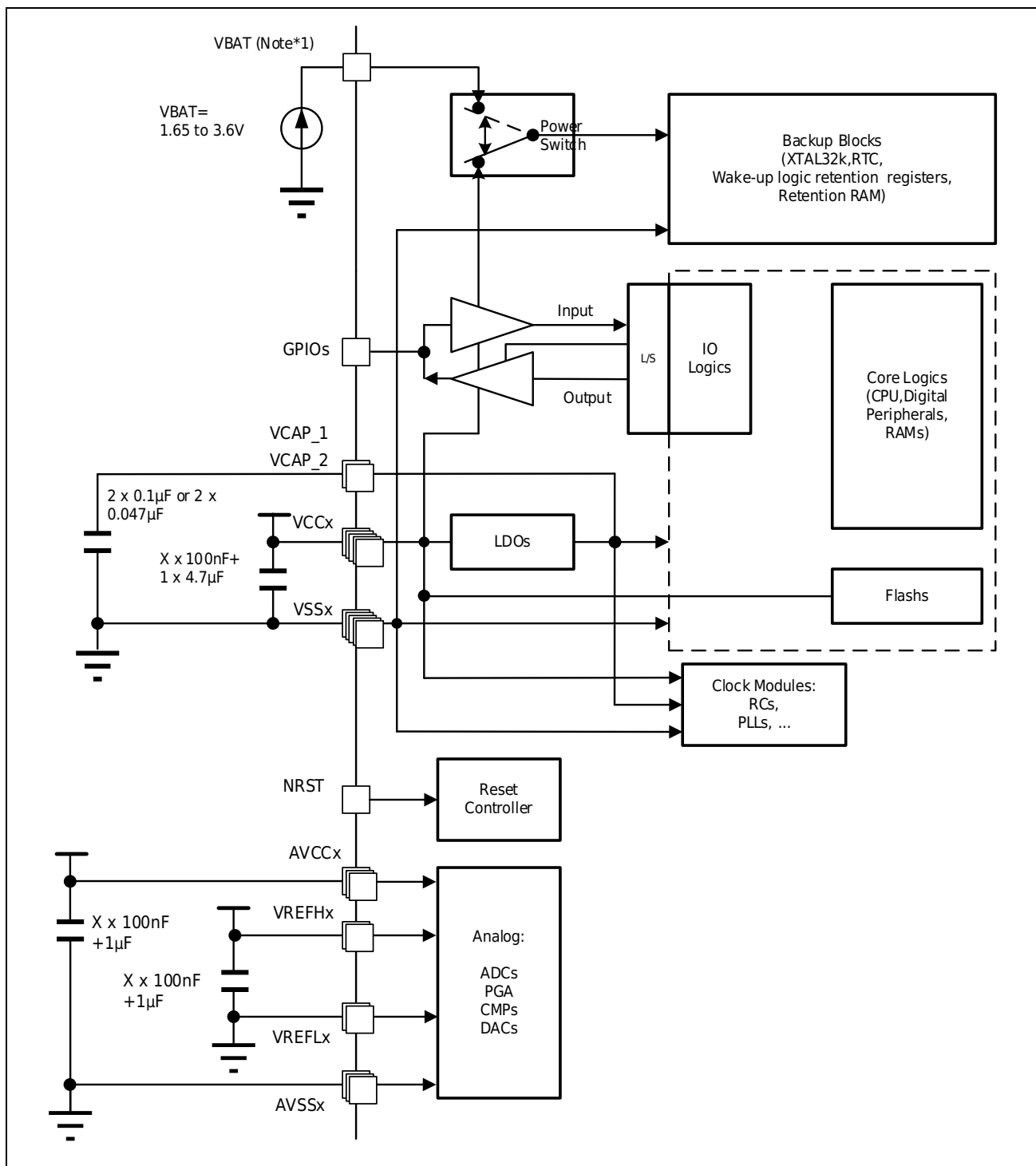


Figure 3-2 Power scheme

Note *1: For non-rechargeable batteries, it is strongly recommended to connect a low drop diode between the battery and the VBAT pin.

1. A 4.7 μF ceramic capacitor must be connected to one of the VCC pins.
2. AVSS=VSS.
3. Each power supply pair (eg VCC/ VSS, AVCC/ AVSS...) Decoupling with filter ceramic capacitors as described above must be used. These capacitors must be as close to or below the appropriate pins as possible under the PCB to ensure proper device operation. Filtering capacitors are not recommended to reduce PCB size or cost. This may result in abnormal operation of the device.
4. The capacitors used by the VCAP_1/ VCAP_2 pins of the chip are as follows: 1) For chips with both VCAP_1 and VCAP_2 pins, each pin can use a 0.047 μF or 0.1 μF capacitor (the total capacity is 0.094 μF or 0.2 μF). 2) For chips with only VCAP_1 pin, 0.1 μF or 0.22 μF capacitors can be used. When waking up from power-down mode, VCAP_1/ VCAP_2 needs to be charged during core voltage establishment. On the one hand, the smaller VCAP_1/ VCAP_2 total capacity can shorten the charging time and bring fast response capability to the application; on the other hand, the larger VCAP_1/ VCAP_2 total capacity will prolong the charging time, but also provide stronger electromagnetic compatibility (EMC). Users can choose a larger or smaller capacitance value according to the requirements of electromagnetic compatibility and system response speed. The total VCAP_1/ VCAP_2 capacity of the chip must match the assignment of the PWC_PWRC3.PDTS bits. When the total capacity of VCAP_1/ VCAP_2 is 0.2 μF or 0.22 μF , it is necessary to ensure that the PWC_PWRC3.PDTS bit is cleared before entering the power-down mode. When the total capacity of VCAP_1/ VCAP_2 is 0.094 μF or 0.1 μF , it is necessary to ensure that the PWC_PWRC3.PDTS bit is set before entering the power-down mode.
5. The stability of the main regulator is achieved by connecting an external capacitor to the VCAP_1 (or VCAP_1/ VCAP_2) pin with a value of C_{EXT} Determined according to the stability requirements of the system. Capacitance value C_{EXT} and ESR requirements are as follows:

Table 3-1 VCAP_1/ VCAP_2 working conditions

Symbol	Parameter	Conditions
C_{EXT}	Capacitance value of external capacitance	0.047 μF / 0.1 μF
ESR	Equivalent Series Resistance ESR of External Capacitor	< 0.3 Ω

3.1.7 Current Consumption Measurement

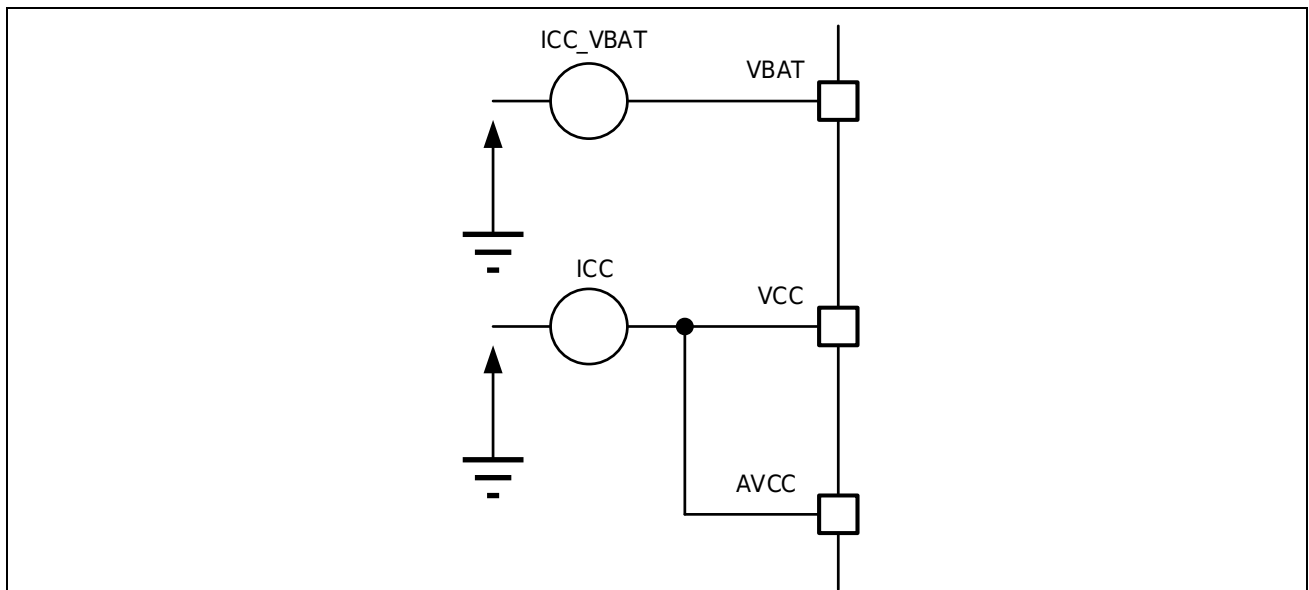


Figure 3-3 Current consumption measurement scheme

3.2 Absolute Maximum Ratings

Loads applied to the device in excess of the absolute maximum ratings listed in Table 3-2, Table 3-3, and Table 3-4 may cause permanent damage to the device. These values are just rated stresses and do not mean that the device works properly under these conditions. Long-term operation may affect the reliability.

Table 3-2 Voltage characteristics

Symbol	Item	Minimum value	Maximum value	Unit
V _{CC} -V _{SS}	External mains voltage (including AVCC, VCC, and VBAT) ⁽¹⁾	-0.3	4.0	V
V _{IN}	Input voltage on pins other than PA11/USBFS_DM, PA12/USBFS_DP, PB14_USBHS_DM, PB15_USBHS_DP, PA0, PA1, PA2, PA6 ⁽²⁾	V _{SS} -0.3	V _{CC} +4.0 (Max 5.8 V)	
	PA11/USBFS_DM, PA12/USBFS_DP Input voltage on pins PB14/USBHS_DM, PB15/USBHS_DP, PA0, PA1, PA2, PA6	V _{SS} -0.3	V _{CC} +0.7(Max 4.0 V)	
V _{ESD(HBM)}	Electrostatic discharge voltage	Please refer to [Electrical sensitivity]		-

1. All mains (VCC, AVCC, VBAT) and ground (VSS, AVSS) pins must always be connected to an external power supply within the allowable range.
2. The maximum value of V_{IN} must always be followed. Information about the maximum allowable current value, see Table 3-3.

Table 3-3 Current characteristics

Symbol	Item	Maximum value	Unit
ΣI _{VCC}	Total current flowing into all VCC x power lines (sourced) ⁽¹⁾	240	mA
ΣI _{VSS}	Total current flowing out of all VSS x ground wires (sinking current) ⁽¹⁾	-240	
I _{VCC}	Maximum current flowing into each VCC x power line (source current) ⁽¹⁾	100	
I _{VSS}	Maximum current flowing out of each VSS x ground wire (sink current) ⁽¹⁾	-100	
I _{IO}	Arbitrary I/O and control pin output current	20	
	Output pull current of any I/O and control pin	-20	
ΣI _{IO}	Total output sink current on all I/O and control pins	120	
	Total output source current on all I/O and control pins	-120	

1. All mains (VCC, AVCC, VBAT) and ground (VSS, AVSS) pins must always be connected to an external power supply within the allowable range.

Table 3-4 Thermal characteristics

Symbol	Item	Numerical value	Unit
T _{STG}	Storage temperature range	-65~150	°C
T _J	Maximum Junction Temperature Range	-40~125	°C

3.3 Operating Conditions

3.3.1 General Operating Conditions

Table 3-5 General working conditions

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
f _{HCLK}	Internal AHB clock frequency	High Speed Mode ⁽¹⁾ PWRC2.DVS=11 PWRC2.DDAS=1111 PWRC3.DDAS=0xff	-	-	240	MHz
		Super low speed mode PWRC2.DVS=10 PWRC2.DDAS= 0000 PWRC3.DDAS=0x00	-	-	8	
V _{CC}	Standard operating voltage	-	1.8	-	3.6	V
V _{AVCC} ⁽²⁾	Analog working voltage	-	1.8	-	3.6	
V _{BAT}	Backup working voltage	-	1.65	-	3.6	
V _{IN}	Input Voltage on 5V Tolerant Pin ⁽³⁾	2 V ≤ V _{CC} ≤ 3.6 V 2 V ≤ AV _{CC} ≤ 3.6 V	-0.3	-	5.5	
		V _{CC} < 2 V AV _{CC} < 2 V	-0.3	-	5.2	
	PA11/USBFS_DM, PA12/USBFS_DP, PB14/USBHS_DM, PB15/USBHS_DP, Input voltage on pins PA0, PA1, PA2, PA6	-	-0.3	-	V _{CC} +0.3	
T _J	Junction Temperature Range	-	-40	-	125	°C
P _D	Power Dissipation T _A =105 °C	LQFP144	-	-	500	mW
		LQFP100	-	-	469	
		LQFP64	-	-	363	
T _A	Operating Temperature Range	-	-40	-	105	°C

1. Guarantee of mass production test.
2. If the VREFH pin is present, the following conditions must be considered: 0 ≤ V_{AVCC} - V_{REFH} ≤ 1.2 V.
3. To keep the voltage above V_{CC} +0.3, the internal pull-up/pull-down resistors must be disabled.
4. After ensuring that the power supply (V_{CC}, AV_{CC}) of the device is stable, apply this voltage to the 5V withstand voltage pin of the device.
5. Such pins must not be directly connected to the power/ground of a non-own chip. It is recommended to use a resistor with a value of 1KΩ or higher for pulling up to the power supply or pulling down to the ground.
6. If T_A is lower, a higher P_D value is allowed as long as T_J does not exceed T_{Jmax}.

3.3.2 Operating Conditions in Case of Power-On/Power-Off

TA obeys general operating conditions.

Table 3-6 Operating Conditions at Power-Up/Power-Down

Symbol	Parameter	Minimum value	Maximum value	Unit
tvcc	VCC rise time rate	20	20000	μs/V
	VCC fall time rate	20	20000	

3.3.3 Reset and Power Control Module Characteristics

Table 3-7 Reset and Power Control Module Features

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{BOR}	Monitoring voltage of BOR	ICG1.BOR_LEV [1:0] =00	1.85 ⁽¹⁾	2.00	2.10	V
		ICG1.BOR_LEV [1:0] =01	1.96	2.10	2.20	V
		ICG1.BOR_LEV [1:0] =10	2.06	2.20	2.30	V
		ICG1.BOR_LEV [1:0] =11	2.27 ⁽¹⁾	2.40	2.50	V
V _{PVD1}	PVD1 monitoring voltage ⁽³⁾	PVD1LVL [2:0] =000	1.96 ⁽¹⁾	2.10	2.20	V
		PVD1LVL [2:0] =001	2.06	2.20	2.30	V
		PVD1LVL [2:0] =010	2.27	2.40	2.52	V
		PVD1LVL [2:0] =011	2.48	2.60	2.72	V
		PVD1LVL [2:0] =100	2.58	2.70	2.82	V
		PVD1LVL [2:0] =101	2.69	2.80	2.92	V
		PVD1LVL [2:0] =110	2.79	2.95	3.07	V
		PVD1LVL [2:0] =111	2.90 ⁽¹⁾	3.05	3.17	V
V _{PVD2}	PVD2 monitoring voltage ⁽³⁾	PVD2LVL [2:0] =000	2.06 ⁽¹⁾	2.20	2.30	V
		PVD2LVL [2:0] =001	2.27	2.40	2.50	V
		PVD2LVL [2:0] =010	2.48	2.60	2.72	V
		PVD2LVL [2:0] =011	2.58	2.70	2.82	V
		PVD2LVL [2:0] =100	2.69	2.85	2.94	V
		PVD2LVL [2:0] =101	2.79	2.95	3.07	V
		PVD2LVL [2:0] =110 ⁽¹⁾	2.90 ⁽¹⁾	3.05	3.17	V
		PVD2LVL [2:0] =111 ⁽²⁾	1.05 ⁽¹⁾	1.15	1.25	V
V _{pvdhyst}	Hysteresis of PVD1,2 ⁽⁴⁾	-	-	100	-	mV
V _{POR} ⁽¹⁾	Power-on/power-off reset threshold	Rising edge VPOR	1.60	1.68	1.80	V
		Falling edge VPDR	1.56	1.64	1.76	V
V _{PORhyst}	POR hysteresis	-	-	40	-	mV
I _{RUSH}	Surge current when the voltage regulator is powered on (POR or awakens from power down)	-	-	160	200	mA
T _{NRST}	NRST reset minimum width	-	10	-	-	μs

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
T _{IPVD1}	PVD1 reset release time	-	300	380	460	μs
T _{IPVD2}	PVD2 reset release time	-	300	380	460	μs
T _{INRST}	NRST reset release time	-	25	35	50	μs
T _{RIPT}	Internal reset time	-	140	160	200	μs
T _{RSTBOR}	BOR reset release time	-	440	520	610	μs
T _{RSTPOR}	Power-on reset release time	-	-	2500	3000	μs

1. Guarantee of mass production test.
2. When PVD2LVLDL [2:0] = 111, the compare voltage is External input compare voltage of PVD2EXINP pin
3. The PVD1 monitoring voltage is the monitoring voltage when the VCC voltage drops; when the PVD2LVL [2:0] is set to 111, the PVD2 monitoring voltage is the monitoring voltage when the PVDEXINP voltage drops, when the PVD2LVD [2:0] is set to a value other than 111 The PVD2 monitoring voltage is the monitoring voltage when the VCC voltage drops.
4. The hysteresis of PVD1,2 is the difference between the monitoring voltage when VCC is rising and the monitoring voltage when VCC is falling.
 PVD1 monitoring voltage when VCC rises = Vpvd1+Vpvdhyst;
 PVD2 monitoring voltage when VCC rises = Vpvd2 + Vpvdhyst.

3.3.4 Supply Current Characteristics

The current consumption is affected by several parameters and factors, including operating voltage, ambient temperature, I/O pin load, device software configuration, operating frequency, I/O pin switch rate, program position in memory and running code.

The measurement method for current consumption is described in Figure 3-3. The current consumption measurements in the various modes described in this section are derived from a set of test code running in FLASH under laboratory conditions.

The specific conditions are as follows:

- 1) All I/O pins are in high impedance mode (no load).
- 2) The clock frequency selects high speed mode $f_{HCLK} = 240 \text{ MHz}/ 120 \text{ MHz}/ 24 \text{ MHz}$ and ultra low speed mode $f_{HCLK} = 8 \text{ MHz}/ 1 \text{ MHz}$.
- 3) The power modes are divided into: Normal working mode ICC_RUN, sleep mode ICC_SLEEP, stop mode ICC_STP, power-down mode ICC_PD, Dhrystone working mode ICC_DHRYSTONE and VBAT power supply mode ICC_VBAT.
- 4) Please refer to the description of specific current conditions for peripheral clock ON/OFF.
- 5) In high speed mode $f_{HCLK} = 240 \text{ MHz}/ 120 \text{ MHz}$ PLL is on.

Table 3-8 High-speed mode current consumption 1

Pattern	Parameter	Symbol	Conditions	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
high speed mode	f _{HCLK} = 240 MHz	ICC_RUN	While (1), full-module clock OFF	-40	-	33	-	mA
			While (1), full module clock ON	-40	-	73	-	mA
		ICC_DHRYSTONE	CACHE OFF	-40	-	37	-	mA
			CACHE ON	-40	-	38	-	mA
		ICC_SLEEP	Full module clock OFF	-40	-	26	-	mA
			Full module clock ON	-40	-	66	-	mA
		ICC_RUN	While (1), full-module clock OFF	25	-	33	-	mA
			While (1), full module clock ON	25	-	74	-	mA
		ICC_DHRYSTONE	CACHE OFF	25	-	38	-	mA
			CACHE ON	25	-	39	-	mA
		ICC_SLEEP	Full module clock OFF	25	-	26	-	mA
			Full module clock ON	25	-	67	-	mA
		ICC_RUN	While (1), full-module clock OFF	85	-	-	70	mA
			While (1), full module clock ON	85	-	-	120	mA
		ICC_DHRYSTONE	CACHE OFF	85	-	-	77	mA
			CACHE ON	85	-	-	78	mA
		ICC_SLEEP	Full module clock OFF	85	-	-	60	mA
			Full module clock ON	85	-	-	110	mA
		ICC_RUN	While (1), full-module clock OFF	105	-	-	110 ⁽³⁾	mA
			While (1), full module clock ON	105	-	-	160 ⁽³⁾	mA
ICC_DHRYSTONE	CACHE OFF	105	-	-	120	mA		
	CACHE ON	105	-	-	121	mA		
ICC_SLEEP	Full module clock OFF	105	-	-	100 ⁽³⁾	mA		
	Full module clock ON	105	-	-	150 ⁽³⁾	mA		

1. Typ voltage condition V_{CC} = 3.3 V
2. Max voltage condition V_{CC} = 1.8~3.6 V
3. Mass production guarantee

Table 3-9 High Speed Mode Current Consumption 2

Pattern	Parameter	Symbol	Conditions	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
high speed mode	f _{HCLK} = 120 MHz	ICC_RUN	While (1), full-module clock OFF	-40	-	21	-	mA
			While (1), full module clock ON	-40	-	42	-	mA
		ICC_DHRYSTONE	CACHE OFF	-40	-	21	-	mA
			CACHE ON	-40	-	22	-	mA
		ICC_SLEEP	Full module clock OFF	-40	-	16	-	mA
			Full module clock ON	-40	-	37	-	mA
		ICC_RUN	While (1), full-module clock OFF	25	-	22	-	mA
			While (1), full module clock ON	25	-	43	-	mA
		ICC_DHRYSTONE	CACHE OFF	25	-	22	-	mA
			CACHE ON	25	-	23	-	mA
		ICC_SLEEP	Full module clock OFF	25	-	16	-	mA
			Full module clock ON	25	-	38	-	mA
		ICC_RUN	While (1), full-module clock OFF	85	-	-	52	mA
			While (1), full module clock ON	85	-	-	78	mA
		ICC_DHRYSTONE	CACHE OFF	85	-	-	53	mA
			CACHE ON	85	-	-	54	mA
		ICC_SLEEP	Full module clock OFF	85	-	-	44	mA
			Full module clock ON	85	-	-	71	mA
		ICC_RUN	While (1), full-module clock OFF	105	-	-	84	mA
			While (1), full module clock ON	105	-	-	108	mA
		ICC_DHRYSTONE	CACHE OFF	105	-	-	88	mA
			CACHE ON	105	-	-	89	mA
		ICC_SLEEP	Full module clock OFF	105	-	-	77	mA
			Full module clock ON	105	-	-	101	mA

1. Typ voltage condition V_{CC} = 3.3 V
2. Max voltage condition V_{CC} = 1.8~3.6 V
3. Mass production guarantee

Table 3-10 High-speed mode current consumption 3

Pattern	Parameter	Symbol	Conditions	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
high speed mode	f _{HCLK} = 24 MHz	ICC_RUN	While (1), full-module clock OFF	-40	-	6	-	mA
			While (1), full module clock ON	-40	-	13	-	mA
		ICC_DHRystone	CACHE OFF	-40	-	6	-	mA
			ICC_SLEEP	Full module clock OFF	-40	-	4	-
		Full module clock ON		-40	-	12	-	mA
		ICC_RUN	While (1), full-module clock OFF	25	-	6	-	mA
			While (1), full module clock ON	25	-	14	-	mA
		ICC_DHRystone	CACHE OFF	25	-	7	-	mA
			ICC_SLEEP	Full module clock OFF	25	-	4	-
		Full module clock ON		25	-	13	-	mA
		ICC_RUN	While (1), full-module clock OFF	85	-	-	27	mA
			While (1), full module clock ON	85	-	-	36	mA
		ICC_DHRystone	CACHE OFF	85	-	-	29	mA
			ICC_SLEEP	Full module clock OFF	85	-	-	24
		Full module clock ON		85	-	-	33	mA
		ICC_RUN	While (1), full-module clock OFF	105	-	-	54	mA
			While (1), full module clock ON	105	-	-	61	mA
		ICC_DHRystone	CACHE OFF	105	-	-	59	mA
			ICC_SLEEP	Full module clock OFF	105	-	-	52
		Full module clock ON		105	-	-	59	mA

1. Typ voltage condition V_{CC} = 3.3 V
2. Max voltage condition V_{CC} = 1.8~3.6 V
3. Mass production test guarantee

Table 3-11 Ultra-low speed mode current consumption 1

Pattern	Parameter	Symbol	Conditions	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
Super low speed mode	f _{HCLK} = 8 MHz	ICC_RUN	While (1), full-module clock OFF	-40	-	3	-	mA
			While (1), full module clock ON	-40	-	6	-	mA
		ICC_DHRYSTONE	CACHE OFF	-40	-	3	-	mA
			ICC_SLEEP	Full module clock OFF	-40	-	2	-
		Full module clock ON		-40	-	6	-	mA
		ICC_RUN	While (1), full-module clock OFF	25	-	3	-	mA
			While (1), full module clock ON	25	-	7	-	mA
		ICC_DHRYSTONE	CACHE OFF	25	-	3	-	mA
			ICC_SLEEP	Full module clock OFF	25	-	3	-
		Full module clock ON		25	-	7	-	mA
		ICC_RUN	While (1), full-module clock OFF	85	-	-	22	mA
			While (1), full module clock ON	85	-	-	28	mA
		ICC_DHRYSTONE	CACHE OFF	85	-	-	25	mA
			ICC_SLEEP	Full module clock OFF	85	-	-	22
		Full module clock ON		85	-	-	27	mA
		ICC_RUN	While (1), full-module clock OFF	105	-	-	48	mA
			While (1), full module clock ON	105	-	-	50	mA
		ICC_DHRYSTONE	CACHE OFF	105	-	-	49	mA
			ICC_SLEEP	Full module clock OFF	105	-	-	48
		Full module clock ON		105	-	-	50	mA

1. Typ voltage condition V_{CC} = 3.3 V
2. Max voltage condition V_{CC} = 1.8~3.6 V
3. Mass production test guarantee

Table 3-12 Ultra-low speed mode current consumption2

Pattern	Parameter	Symbol	Conditions	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
ultra low speed Pattern	f _{HCLK} = 1 MHz	ICC_RUN	While (1), full-module clock OFF	-40	-	1	-	mA
			While (1), full module clock ON	-40	-	4	-	mA
		ICC_DHRYSTONE	CACHE OFF	-40	-	2	-	mA
		ICC_SLEEP	Full module clock OFF	-40	-	1	-	mA
			Full module clock ON	-40	-	3	-	mA
		ICC_RUN	While (1), full-module clock OFF	25	-	2	-	mA
			While (1), full module clock ON	25	-	4	-	mA
		ICC_DHRYSTONE	CACHE OFF	25	-	2	-	mA
		ICC_SLEEP	Full module clock OFF	25	-	2	-	mA
			Full module clock ON	25	-	4	-	mA
		ICC_RUN	While (1), full-module clock OFF	85	-	-	20	mA
			While (1), full module clock ON	85	-	-	24	mA
		ICC_DHRYSTONE	CACHE OFF	85	-	-	23	mA
		ICC_SLEEP	Full module clock OFF	85	-	-	20	mA
			Full module clock ON	85	-	-	24	mA
		ICC_RUN	While (1), full-module clock OFF	105	-	-	46	mA
			While (1), full module clock ON	105	-	-	47	mA
		ICC_DHRYSTONE	CACHE OFF	105	-	-	47	mA
		ICC_SLEEP	Full module clock OFF	105	-	-	46	mA
			Full module clock ON	105	-	-	47	mA

1. Typ voltage condition V_{CC} = 3.3 V
2. Max voltage condition V_{CC} = 1.8~3.6 V
3. Mass production test guarantee

Table 3-13 Low Power Mode Current Consumption

Pattern	Parameter	Symbol	Condition (VCC=3.3 V)	Ta (°C)	Product Specifications			Unit
					Min	Typ ⁽¹⁾	Max ⁽²⁾	
Stop mode	-	ICC_STP	PWC_PWRC1.STPDAS=00	-40	-	191	-	μA
			PWC_PWRC1.STPDAS=11	-40	-	56	-	μA
			PWC_PWRC1.STPDAS=00	25	-	396	-	μA
			PWC_PWRC1.STPDAS=11	25	-	248	-	μA
			PWC_PWRC1.STPDAS=00	85	-	-	15	mA
			PWC_PWRC1.STPDAS=11	85	-	-	16	mA
			PWC_PWRC1.STPDAS=00	105	-	-	40 ⁽³⁾	mA
			PWC_PWRC1.STPDAS=11 ⁽³⁾	105	-	-	41 ⁽³⁾	mA
Power-down mode	-	ICC_PD	Power Down Mode 1	-40	-	9.1	-	μA
			Power Down Mode 2	-40	-	3.8	-	μA
			Power Down Mode 3	-40	-	1.6	-	μA
			Power Down Mode 4	-40	-	1.6	-	μA
			Power-down mode 2 +XTAL32+RTC	-40	-	5.1	-	μA
			Power-down mode 2 +LRC+RTC	-40	-	7.5	-	μA
			Power-down mode 2 +XTAL32+RTC+Backup SRAM	-40	-	5.5	-	μA
			Power Down Mode 1	25	-	10.5	-	μA
			Power Down Mode 2	25	-	4.3	-	μA
			Power Down Mode 3	25	-	2	-	μA
			Power Down Mode 4	25	-	2	-	μA
			Power-down mode 2 +XTAL32+RTC	25	-	5.8	-	μA
			Power-down mode 2 +LRC+RTC	25	-	8.1	-	μA
			Power-down mode 2 +XTAL32+RTC+Backup SRAM	25	-	6.3	-	μA
			Power-down mode 1	85	-	-	24	μA
			Power-down mode 2	85	-	-	17	μA
			Power-down mode 3	85	-	-	14	μA
			Power-down mode 4	85	-	-	14	μA
			Power-down mode 2 +XTAL32+RTC	85	-	-	18	μA
			Power-down mode 2 +LRC+RTC	85	-	-	19	μA
			Power-down mode 2 +XTAL32+RTC+Backup SRAM	85	-	-	23	μA
			Power Down Mode 1	105	-	-	75 ⁽³⁾	μA
			Power Down Mode 2	105	-	-	68 ⁽³⁾	μA
			Power Down Mode 3	105	-	-	65 ⁽³⁾	μA
Power Down Mode 4 ⁽³⁾	105	-	-	65 ⁽³⁾	μA			
Power-down mode 2 +XTAL32+RTC	105	-	-	69	μA			
Power-down mode 2 +LRC+RTC	105	-	-	70 ⁽³⁾	μA			
Power-down mode 2 +XTAL32+RTC+Backup SRAM	105	-	-	87 ⁽³⁾	μA			

1. Typ voltage condition $V_{CC} = 3.3\text{ V}$
2. Max voltage condition $V_{CC} = 1.8\sim 3.6\text{ V}$
3. Guarantee of mass production test.

Table 3-14 Backup domain current consumption

Item	Parameter	Symbol	Condition (VBAT=3.3 V) ⁽¹⁾	Ta (°C)	Product Specifications			Unit
					Min	Typ	Max	
VBAT powered by	-	ICC_VBAT	VBAT area module fully closed	-40	-	0.05	-	μA
			XTAL32 ON	-40	-	1.0	-	μA
			XTAL32 ON+ XTAL32 filter ON	-40	-	1.4	-	μA
			XTAL32 ON+ XTAL32 filter ON+RTC count	-40	-	1.5	-	μA
			Backup SRAM ON	-40	-	0.6	-	μA
			RTCLRC ON	-40	-	3.8	-	μA
			RTCLRC ON + WKTM count	-40	-	3.9	-	μA
			VBAT area module fully closed	25	-	0.1	-	μA
			XTAL32 ON	25	-	1.2	-	μA
			XTAL32 ON+ XTAL32 filter ON	25	-	1.5	-	μA
			XTAL32 ON+ XTAL32 filter ON+RTC count	25	-	1.6	-	μA
			Backup SRAM ON	25	-	0.9	-	μA
			RTCLRC ON	25	-	3.8	-	μA
			RTCLRC ON + WKTM count	25	-	3.9	-	μA
			VBAT area module is fully closed	85	-	-	1.4	μA
			XTAL32 ON	85	-	-	3.3	μA
			XTAL32 ON+ XTAL32 filter ON	85	-	-	3.8	μA
			XTAL32 ON+ XTAL32 filter ON+RTC count	85	-	-	3.9	μA
			Backup SRAM on	85	-	-	6.3	μA
			RTCLRC on	85	-	-	7.6	μA
			RTCLRC ON + WKTM count	85	-	-	7.8	μA
			VBAT area module fully closed	105	-	-	3.6	μA
			XTAL32 ON	105	-	-	5.6	μA
			XTAL32 ON+ XTAL32 filter ON	105	-	-	6.2	μA
XTAL32 ON+ XTAL32 filter ON+RTC count	105	-	-	6.3	μA			
Backup SRAM ON	105	-	-	15.2	μA			
RTCLRC ON	105	-	-	9.8	μA			
RTCLRC ON + WKTM count	105	-	-	9.9	μA			

1. In the condition description, the unlisted VBAT power supply modules are turned off.

Table 3-15 Analog Module Current Consumption

Item	Parameter	Symbol	Condition (VCC=AVCC=3.3 V)	Ta (°C)	Product Specifications			Unit
					Min	Typ	Max	
Modules Current	-	ICC_MODULE	XTAL Oscillation Mode Maximum Drive 24 MHz	25	-	1.8	-	mA
			Drive 16 MHz in Oscillation Mode	25	-	1.0	-	mA
			Oscillation mode small drive 10 MHz	25	-	0.8	-	mA
			Oscillation mode ultra-small drive 8 MHz	25	-	0.6	-	mA
			XTAL 32.768 kHz	25	-	1.1	-	µA
			HRC	25	-	0.3	-	mA
			PLLH (VCO=1200 MHz)	25	-	4	-	mA
			PLLH (VCO=600 MHz)	25	-	2.4	-	mA
			PLLA (VCO=480 MHz)	25	-	2.8	-	mA
			PLLA (VCO=240 MHz)	25	-	1.6	-	mA
			ADC	25	-	1.2	-	mA
			DAC	25	-	0.2	-	mA
			CMP	25	-	0.4	-	mA
			PGA	25	-	0.7	-	mA
			USBFS ⁽¹⁾	25	-	6	-	mA

1. Including the current when the control part communicates with the USBPHY, the load is 50pf.

3.3.5 Low Power Mode Wake-Up Timing

The wake-up time measurement method is from the wake-up event triggering to the CPU execution of the first instruction:

- For stop or sleep mode: The wakeup event is WFE.
- WKUP pins are used to wake up from power down, stop, and sleep modes. All timings are tested at ambient temperature and VCC=3.3V.

Table 3-16 Low power mode wake-up time

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
T _{STOP1}	Wakeup from stop mode	PWC_PWRC1.VHRCSD=1 and PWC_PWRC1.VPLLS=1, the system clock is MRC, and the program is executed on RAM	2	5	μs
T _{STOP2}	Wakeup from stop mode	The system clock is MRC, and the program is executed on the Flash	8	15	
T _{PD1} (1)	Wake-up from Power-down Mode 1	The total capacity of VCAP_1/VCAP_2 is 0.094 μF or 0.1 μF	25	35	
		The total capacity of VCAP_1/VCAP_2 is 0.2 μF or 0.22 μF	30	40	
T _{PD2} (1)	Wake-up from Power-down Mode 2	The total capacity of VCAP_1/VCAP_2 is 0.094 μF or 0.1 μF	70	80	
		The total capacity of VCAP_1/VCAP_2 is 0.2 μF or 0.22 μF	75	85	
T _{PD3} (1)	Wake-up from Power-down Mode 3	The total capacity of VCAP_1/VCAP_2 is 0.094 μF or 0.1 μF	2500	3000	
		The total capacity of VCAP_1/VCAP_2 is 0.2 μF or 0.22 μF	2500	3000	
T _{PD4} (1)	Wake-up from Power-down Mode 4	The total capacity of VCAP_1/VCAP_2 is 0.094 μF or 0.1 μF	130	140	
		The total capacity of VCAP_1/VCAP_2 is 0.2 μF or 0.22 μF	140	150	

1. The total VCAP_1/VCAP_2 capacity of the chip must match the assignment of the PWC_PWRC3.PDTS bits. When the total capacity of VCAP_1/VCAP_2 is 0.2 μF or 0.22 μF, it is necessary to ensure that the PWC_PWRC3.PDTS bit is cleared before entering the power-down mode. When the total capacity of VCAP_1/VCAP_2 is 0.094 μF or 0.1 μF, it is necessary to ensure that the PWC_PWRC3.PDTS bit is set before entering the power-down mode.

3.3.6 External Timer Characteristic

3.3.6.1 High-speed External Subscriber Clock Generated by External Source

In bypass mode, XTAL oscillator is off and the input pin is standard I/O. External clock signals must take into account I/O static characteristics.

Table 3-17 High-speed external user clock features

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
f_{XTAL_EXT}	User external timer frequency ⁽¹⁾	-	1	-	25	MHz
V_{IH_XTAL}	XTAL_EXT input pin high level voltage ⁽¹⁾		$0.8 \cdot V_{CC}$	-	V_{CC}	V
V_{IL_XTAL}	XTAL_EXT input pin low level voltage ⁽¹⁾		V_{SS}	-	$0.2 \cdot V_{CC}$	
$t_{r(XTAL)}$ $t_{f(XTAL)}$	XTAL_EXT rise or fall time		-	-	5	ns
Duty _(XTAL)	Duty ratio		-	40	-	60

1. Guarantee of mass production test.

3.3.6.2 High-speed External Clock Produced by Crystal Oscillator/Ceramic Resonator

High-speed external (XTAL) clocks can be produced using a 4 to 25 MHz crystal oscillator/ceramic resonator oscillator. In applications, the resonator and load capacitance must be as close to the oscillator pin as possible to minimize output distortion and vibration stabilization time. For more information on the resonator characteristics (frequency, encapsulation, accuracy, etc.), please consult the crystal resonator manufacturer.

Table 3-18 XTAL 4-25 MHz Oscillator Features

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
f_{XTAL_IN}	Oscillator frequency		4	-	25	MHz
R_F ⁽¹⁾	Feedback resistance		-	300	-	kΩ
A_{XTAL} ⁽²⁾	XTAL accuracy	-	-500	-	500	ppm
G_{mmmax}	-	Wake up	4	-	-	mA/V
$t_{SU(XTAL)}$ ⁽³⁾	Start time	VCC is stable, crystal oscillator=8MHz	-	-	2.0	ms
		VCC is stable, crystal oscillator=4MHz	-	-	4.0	ms

1. Guarantee of mass production test.
2. This parameter depends on the resonator used on the application system.
3. $t_{SU(XTAL)}$ is the start-up time, that is, the time between the software enabling the XTAL to measure until the stable 8MHz oscillation frequency is obtained. This value is measured based on the standard crystal resonator and may vary significantly with the crystal resonator manufacturer.

For C_{L1} and C_{L2} , it is recommended to use high-quality external ceramic capacitors between 5 pF and 25 pF (typ.) designed for high frequency applications that meet the requirements of a crystal or resonator (see diagram below). C_{L1} and C_{L2} are usually the same size. The load capacitance specified by the crystal oscillator manufacturer is usually a product family combination of C_{L1} and C_{L2} . In determining the specifications of C_{L1} and C_{L2} , the capacitance of the PCB and MCU pins must be taken into account (the capacitance of the pin and the circuit board can be roughly estimated to be 10 pF).

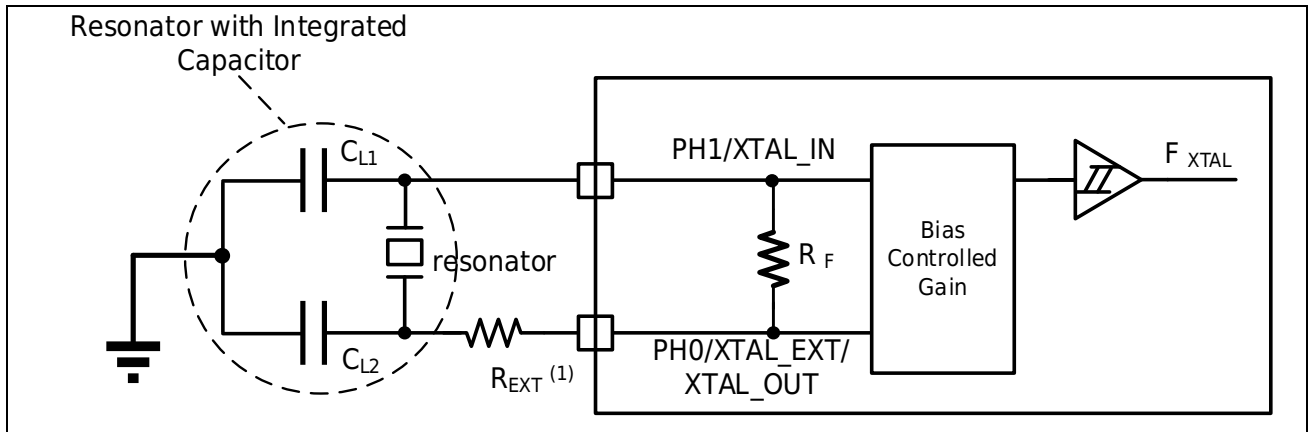


Figure 3-4 Typical Application Using an 8 MHz Crystal

1. The value of R_{EXT} depends on the crystal oscillator characteristics.

3.3.6.3 Low-speed External Clock Generated by Crystal Oscillator/Ceramic Resonator

A low-speed external clock can be generated using an oscillator consisting of a 32.768 kHz crystal/ceramic resonator. In applications, the resonator and load capacitance must be as close to the oscillator pin as possible to minimize output distortion and vibration stabilization time. For more information on the resonator characteristics (frequency, encapsulation, accuracy, etc.), please consult the crystal resonator manufacturer.

Table 3-19 XTAL32 Oscillator Features

Symbol	Parameter	Conditions	Specifications			Unit
			Min	Typ	Max	
F_{XTAL32}	Frequency	-	-	32.768	-	kHz
$R_F^{(1)}$	Feedback resistance	-	-	15	-	MΩ
I_{DD_XTAL32}	Power consumption	XTAL32DRV [2:0] =000	-	0.8	-	μA
$A_{XTAL32}^{(2)}$	XTAL32 precision	-	-500	-	500	ppm
G_{mmax}	G_m	-	-	-	5.6	μA/V
$T_{SUXTAL32}$	Start Time ⁽³⁾	VCC steady state	-	2	-	s

1. Guarantee of mass production test.
2. This parameter depends on the resonator used on the application system.
3. $T_{SUXTAL32}$ is the start-up time, which starts with the software enabling XTAL 32 to measure until a stable oscillation frequency of 32.768 kHz is obtained. This value is measured based

on the standard crystal resonator and may vary significantly with the crystal resonator manufacturer.

For C_{L1} and C_{L2} , a high-quality external ceramic capacitor between 5 pF and 18 pF (typ) is recommended (see figure below). C_{L1} and C_{L2} are usually the same size. The load capacitance specified by the crystal oscillator manufacturer is usually a product family combination of C_{L1} and C_{L2} . When sizing C_{L1} and C_{L2} , the capacitance of the PCB and MCU pins must be taken into account (the pin capacitance can be roughly estimated as 5 pF). If C_{L1} and C_{L2} are greater than 18pF, it is recommended to set XTAL32DRV [2:0] =001 (large drive, typical power consumption increases by 0.2 μ A).

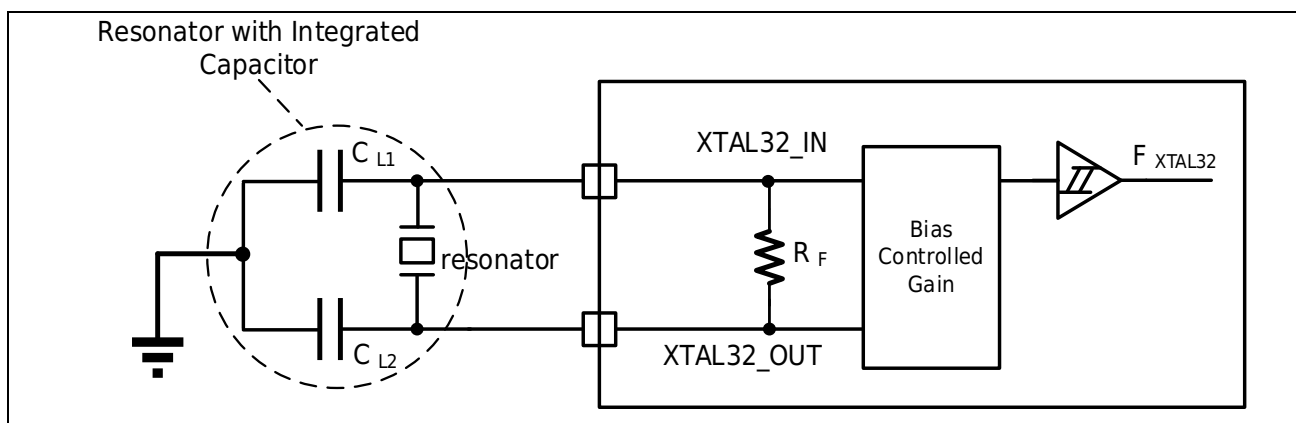


Figure 3-5 Typical Application Using a 32.768 kHz Crystal

3.3.7 Internal Timer Characteristics

3.3.7.1 Internal High Speed (HRC) Oscillator

Table 3-20 HRC Oscillator Characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
f _{HRC}	Frequency ⁽¹⁾	Pattern 1	-	16	-	MHz
		Pattern 2	-	20	-	
	User adjust scale	-	-	-	0.2	%
	Frequency Accuracy ⁽¹⁾	TA = -40 to 105 °C	-3 ⁽¹⁾	-	3 ⁽¹⁾	%
		TA = -20 to 105 °C	-2.5	-	2.5	%
TA = 25°C		-1.5 ⁽¹⁾	-	1.5 ⁽¹⁾	%	
t _{st(HRC)}	HRC oscillator oscillation stabilization time	-	-	-	15	μs

1. Guarantee of mass production test.

3.3.7.2 Internal Medium Speed (MRC) Oscillator

Table 3-21 MRC oscillator characteristics

Symbol	Parameter	Minimum value	Typical value	Maximum value	Unit
f _{MRC} ⁽¹⁾	Frequency	7.2 ⁽¹⁾	8	8.8 ⁽¹⁾	MHz
t _{st(MRC)}	MRC oscillator stabilization time	-	-	3	μs

1. Guarantee of mass production test.

3.3.7.3 Internal Low Speed (LRC) Oscillator

Table 3-22 LRC oscillator characteristics

Symbol	Parameter	Minimum value	Typical value	Maximum value	Unit
f _{LRC} ⁽¹⁾	Frequency	27.853 ⁽¹⁾	32.768	37.683 ⁽¹⁾	kHz
t _{st(LRC)}	LRCoscillator Stabilization Time	-	-	36	μs

1. Guarantee of mass production test.

3.3.7.4 SWDT Dedicated Internal Low Speed (SWDTLRC) Oscillator

Table 3-23 SWDTLRC oscillator characteristics

Symbol	Parameter	Minimum value	Typical value	Maximum value	Unit
f _{SWDTLRC} ⁽¹⁾	Frequency	9 ⁽¹⁾	10	11 ⁽¹⁾	kHz
t _{st(SWDTLRC)}	SWDTLRC oscillator stabilization time	-	-	57.1	μs

1. Guarantee of mass production test.

3.3.7.5 RTC Dedicated Internal Low Speed (RTCRC) Oscillator

Table 3-24 RTCRC Oscillator Characteristics

Symbol	Parameter	Minimum value	Typical value	Maximum value	Unit
$f_{RRC}^{(1)}$	Frequency	29.5 ⁽¹⁾	32.768	36 ⁽¹⁾	kHz
tst(RRC)	RTCRC oscillator stabilization time	-	-	36	μs

1. Guarantee of mass production test.

3.3.8 PLL Characteristics

Table 3-25 I2S-PLL (PLLA) main performance indicators

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f _{PLL_IN}	PLL PFD (Phase Frequency Detector) input clock ⁽¹⁾	-	1	-	25	MHz
f _{PLL_OUT}	PLL multiplier output clock	-	15	-	240	MHz
f _{VCO_OUT}	PLL VCO output	-	240	-	480	MHz
Jitter _{PLL}	Period Jitter	PLL PFD input clock=8MHz, System clock=120MHz, Peak-to-Peak	-	±100	-	ps
	Cycle-to-Cycle Jitter	PLL PFD input clock=8MHz, System clock=120MHz, Peak-to-Peak	-	±150	-	
t _{LOCK}	PLL lock time	-	-	80	120	μs

Table 3-26 System PLL (PLLH) main performance indicators

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f _{PLL_IN}	PLL PFD (Phase Frequency Detector) input clock ⁽¹⁾	-	8	-	25	MHz
f _{PLL_OUT}	PLL multiplier output clock	-	37.5	-	600	MHz
f _{VCO_OUT}	PLL VCO output	-	600	-	1200	MHz
Jitter _{PLL}	Period Jitter	PLL PFD input clock=8MHz, System clock=120MHz, Peak-to-Peak	-	±70	-	ps
	Cycle-to-Cycle Jitter	PLL PFD input clock=8MHz, System clock=120MHz, Peak-to-Peak	-	±100	-	
t _{LOCK}	PLL lock time	-	-	80	120	μs

1. A higher input clock is recommended for good jitter characteristics.

3.3.9 Memory (Flash) Characteristics

Flash memory was erased when the device was delivered to the customer.

Table 3-27 Flash Features

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
I _{vcc}	Supply current	Read mode, V _{CC} =1.8 V~3.6 V	-	-	5	mA
		Programming mode, V _{CC} =1.8 V~3.6 V	-	-	10	
		Block erase mode, V _{CC} =1.8 V~3.6 V	-	-	10	
		Full erase mode, V _{CC} =1.8 V~3.6 V	-	-	10	

Table 3-28 Flash Program Erase Time

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
T _{prog} ⁽¹⁾	Word programming time	Single programming mode	43+2* T _{hclk} ⁽²⁾	48+4* T _{hclk} ⁽²⁾	53+6* T _{hclk} ⁽²⁾	μs
	Word programming time	Continuous programming mode	12+2* T _{hclk} ⁽²⁾	14+4* T _{hclk} ⁽²⁾	16+6* T _{hclk} ⁽²⁾	μs
T _{erase} ⁽¹⁾	Block erase time	-	16+2* T _{hclk} ⁽²⁾	18+4* T _{hclk} ⁽²⁾	20+6* T _{hclk} ⁽²⁾	ms
T _{mas} ⁽¹⁾	Full erase time	-	16+2* T _{hclk} ⁽²⁾	18+4* T _{hclk} ⁽²⁾	20+6* T _{hclk} ⁽²⁾	ms

1. Guarantee of mass production test.
2. T_{hclk} is one cycle of CPU clock.

Table 3-29 Flash Erasable Times and Data Retention Period

Symbol	Parameter	Conditions	Minimum value	Typical value	Unit	
N _{end}	Program, block erase times	Program, block erase T _A = -40°C~ 85°C	Data Storage Period (T _{ret}): Storage data for 10 years, T _A =85°C	-	100000	times
			Data Storage Period (T _{ret}): Storage data for 20 years, T _A =85°C	10000	-	times

3.3.10 Electrical Sensitivity

The chip is tested differently (ESD, LU) using specific measurements to determine its electrical sensitivity performance.

3.3.10.1 Electrostatic Discharge (ESD)

Electrostatic discharge is applied to the pins of each sample according to each pin combination. This test complies with JESD22-A114/C101 standard.

Table 3-30 ESD characteristics

Symbol	Parameter	Conditions	Maximum value	Unit
V _{ESD(HBM)}	Electrostatic discharge voltage (human body model)	T _A = + 25 °C, compliant with JESD22-A114	2000	V
V _{ESD(CDM)}	Electrostatic discharge voltage (charging equipment model)	T _A = + 25 °C, JESD22-C101 compliant	500	

3.3.10.2 Static Latch-up

To assess static Latch-up performance, two complementary static Latch-up tests are required on the chip:

- Over-voltage applied to each power supply and analog input pin
- Apply current injection to other input, output and configurable I/O pins

These tests met the EIA/JESD 78 IC Latch-up standard.

Table 3-31 Static Latch-up feature

Symbol	Parameter	Conditions	Maximum value	Unit
LU	Static Latch-up	T _A = +105 °C per JESD78	200	mA

3.3.11 I/O Port Characteristics

General input/output characteristics

Table 3-32 I/O static characteristics

Symbol	Parameter		Conditions	Minimum value	Typical value	Max.	Unit
V _{IL} ⁽¹⁾	Schmitt input low		1.8≤V _{CC} ≤3.6	-	-	0.2V _{CC}	V
V _{IH} ⁽¹⁾	Schmitt input high		1.8≤V _{CC} ≤3.6	0.8V _{CC}	-	-	V
V _{HYS}	Schmitt Input Hysteresis		1.8≤V _{CC} ≤3.6	-	0.2	-	V
V _{IL} ⁽¹⁾	CMOS input low level		1.8≤V _{CC} ≤3.6	-	-	0.3V _{CC}	V
V _{IH} ⁽¹⁾	CMOS input high level		1.8≤V _{CC} ≤3.6	0.7V _{CC}	-	-	V
I _{LKG} ⁽¹⁾	I/O input leakage current		V _{SS} ≤V _{IN} ≤V _{CC}	-1	-	1	μA
			V _{IN} = 5.5 V ⁽²⁾	-	-	10	μA
R _{PU} ⁽¹⁾⁽²⁾⁽³⁾	weak pull-up Equivalent resistance	-	V _{IN} = V _{SS}	-	30	-	kΩ
R _{PD} ⁽²⁾⁽⁴⁾	Weak pulldown Equivalent resistance	PA11/USBFS_DM PA12/USBFS_DP PB14/USBHS_DM PB15/USBHS_DP	V _{IN} = V _{CC}	-	500	-	kΩ
C _{IO}	I/O pin capacitance	PA11/USBFS_DM PA12/USBFS_DP PB14/USBHS_DM PB15/USBHS_DP	-	-	10	-	pF
		Other input pins except for PA11/USBFS_DM PA12/USBFS_DP PB14/USBHS_DM PB15/USBHS_DP	-	-	5	-	pF

1. Guarantee of mass production test.
2. To keep the voltage above V_{CC} +0.3 V, the internal pull-up/pull-down resistors must be disabled.
3. For PA11/USBFS_DM, PA12/USBFS_DP, PB14/USBHS_DM, PB15/USBHS_DP, it indicates the weak pull-up equivalent resistance value of GPIO when the USB function is turned off. For the pull-up/pull-down resistors for the USB function, please refer to the [USB interface features] chapter.
4. Only PA11/USBFS_DM, PA12/USBFS_DP, PB14/USBHS_DM, PB15/USBHS_DP have weak pull-down resistors, which are always valid.

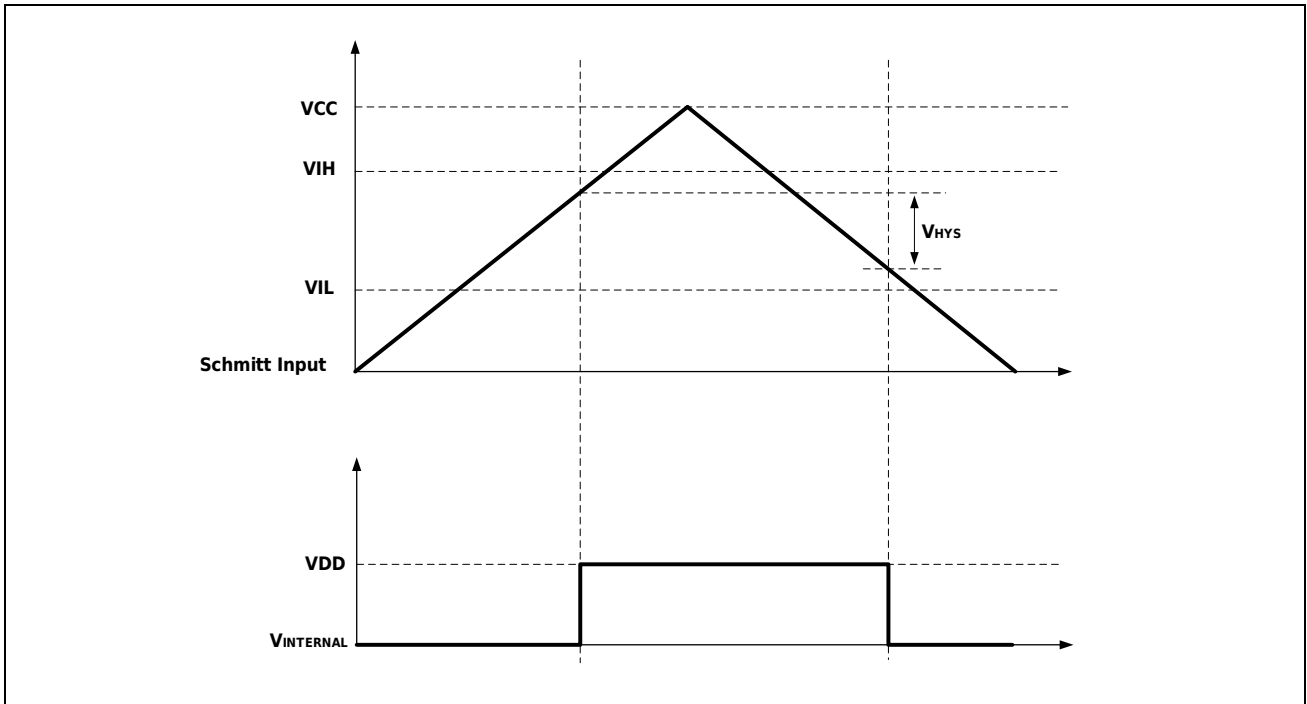


Figure 3-6 Schmitt input DC electrical characteristics definition

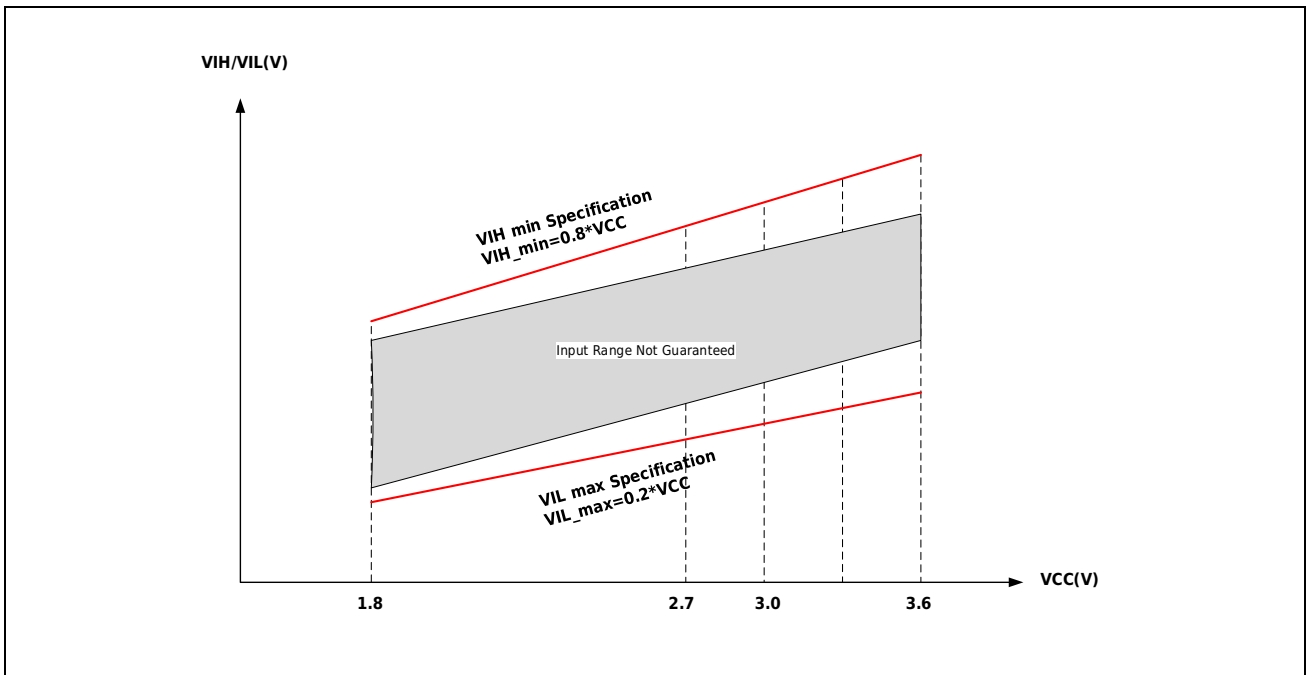


Figure 3-7 V_{IH}/V_{IL} versus V_{CC} (Schmitt Input)

Output current

GPIO (General Purpose Input/Output) provides maximum ± 20 mA source or sink current.

The source or sink current of PC13, PC14, PC15, and PI8 must meet the following restrictions: $\sum I_{IO}$ (PC13, PC14, PC14, PI8) ≤ 20 mA.

Output voltage

Table 3-33 Output Voltage Characteristics

Drive settings	Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
Low drive	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 1.5$ mA, $1.8\leq V_{CC}<2.7$	-	-	0.6	V
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.6$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 3$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	0.6	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.6$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 6$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	1.3	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-1.3$	-	-	
middle drive	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 3$ mA, $1.8\leq V_{CC}<2.7$	-	-	0.4	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.4$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 5$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	0.4	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.4$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 12$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	1.3	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-1.3$	-	-	
High drive	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 6$ mA, $1.8\leq V_{CC}<2.7$	-	-	0.4	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.4$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 8$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	0.4	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-0.4$	-	-	
	$V_{OL}^{(1)(2)}$	Low level output	$I_{IO}=\pm 20$ mA, $2.7\leq V_{CC}\leq 3.6$	-	-	1.3	
	$V_{OH}^{(1)(3)}$	High level output		$V_{CC}-1.3$	-	-	

1. Guarantee of mass production test.
2. The device's I_{IO} sink current must always consider the absolute maximum ratings specified in Table 3-3. The sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS} .
3. The device's I_{IO} sourcing current must always adhere to the absolute maximum ratings listed in Table 3-3, and the sum of the I_{IO} (I/O ports and control pins) must not exceed I_{VCC} .

Input/output AC characteristics

Table 3-34 I/O AC Characteristics

Drive settings	Symbol	Parameter	Condition ⁽³⁾	Minimum value	Typical value	Maximum value	Unit
Low drive	f _{max} (IO) _{out}	Maximum frequency (1)	C _L =30 pF, V _{CC} ≥ 2.7 V	-	-	20	MHz
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	10	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	40	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	20	
	t _r (IO) _{out} t _r (IO) _{out}	Output high to low level drop time and output low to high level rise time	C _L =30 pF, V _{CC} ≥2.7 V	-	-	15	ns
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	25	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	7.5	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	15	
Middle drive	f _{max} (IO) _{out}	Maximum frequency (1)	C _L =30 pF, V _{CC} ≥ 2.7 V	-	-	45	MHz
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	22.5	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	90	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	45	
	t _r (IO) _{out} t _r (IO) _{out}	Output high to low level drop time and output low to high level rise time	C _L =30 pF, V _{CC} ≥2.7 V	-	-	6	ns
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	10	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	4	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	6	
High drive	f _{max} (IO) _{out}	Maximum frequency (1)	C _L =30 pF, V _{CC} ≥2.7 V	-	-	100	MHz
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	50	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	180	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	100	
	t _r (IO) _{out} t _r (IO) _{out}	Output high to low level drop time and output low to high level rise time	C _L =30 pF, V _{CC} ≥2.7 V	-	-	4	ns
			C _L =30 pF, V _{CC} ≥1.8 V	-	-	6	
			C _L =10 pF, V _{CC} ≥2.7 V	-	-	2.5	
			C _L =10 pF, V _{CC} ≥1.8 V	-	-	3.5	

1. The maximum frequency is defined in Figure 3-8.
2. The load capacitor CL must take into account the capacitances of the PCB and the MCU pins (the capacitance of the MCU pins can be roughly estimated to be 10 pF).

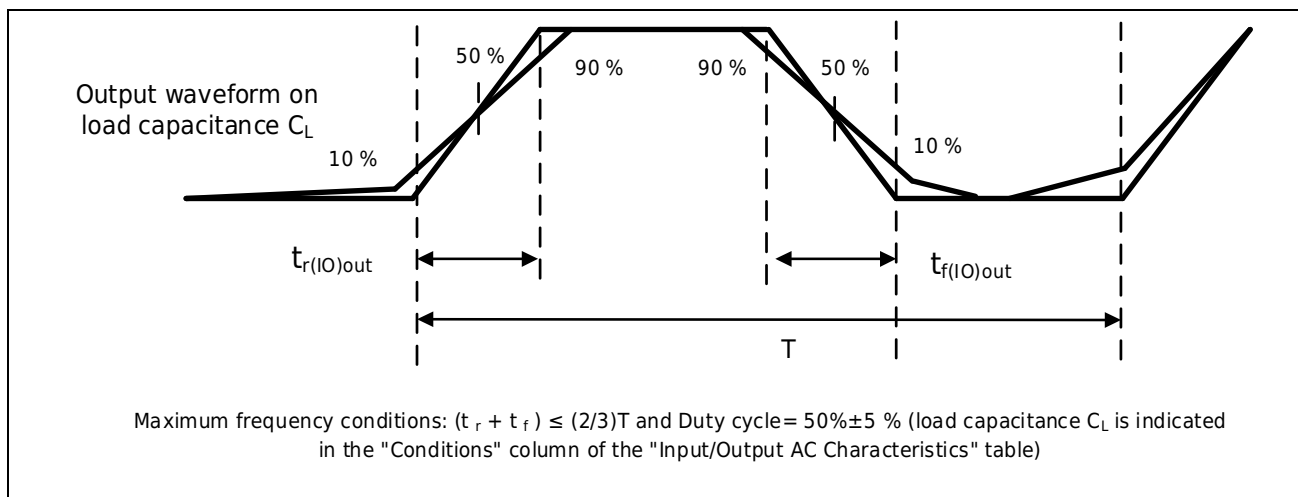


Figure 3-8 I/O AC Characteristics Definition

3.3.12 I2C Interface Characteristics

Table 3-35 I2C Electrical Characteristics

Symbol	Parameter	Standard mode (SM)		Fast mode (FM)		Unit
		Min	Max	Min	Max	
fSCL	SCL frequency	0	100	0	400	kHz
tHD;STA	Start condition/restart condition Hold	4.0	-	0.6	-	μs
tLOW	SCL Low Level	4.7	-	1.3	-	μs
tHIGH	SCL High Level	4	-	0.6	-	μs
tSU;STA	Restarting Condition Setup	4.7	-	0.6	-	μs
tHD;DAT	Data Hold	0	-	0	-	μs
tSU;DAT	Data Setup	30+	-	30+	-	ns
		tI2C reference clock period		tI2C reference clock period		
tR	Ascending time of SCL/SDA	-	1000	-	300	ns
tF	Falling time of SCL/SDA	-	300	-	300	ns
tSU;STO	Stop Condition Setup	4	-	0.6	-	μs
tBUF	BUS Idle Time Between Stop Condition and Start Condition	4.7	-	1.3	-	μs
Cb	Load capacitance	-	400	-	400	pF

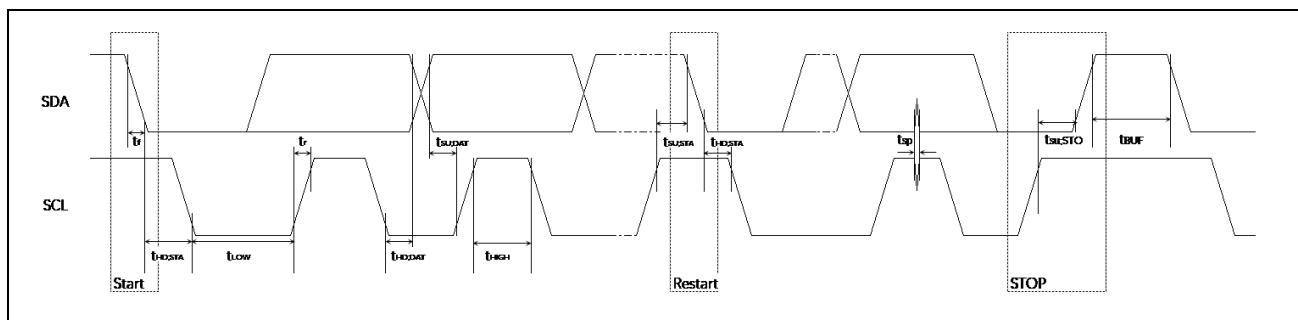


Figure 3-9 I2C bus timing definition

3.3.13 SPI Interface Characteristics

Table 3-36 SPI Electrical Characteristics

Symbol	Parameter	Conditions	Minimum value	Maximum value	Unit
$t_w(SCKH)$	SCK high and low time	master mode *4 $1.8V \leq V_{CC} \leq 3.6V$	$T_{pclk1} - 1 * 1$	$T_{pclk1} + 1 * 1$	ns
		slave mode $1.8V \leq V_{CC} \leq 3.6V$	$3 \times T_{pclk1} - 1 * 1$	$3 \times T_{pclk1} + 1 * 1$	ns
master mode *4 $1.8V \leq V_{CC} < 3.6V$		$T_{pclk1} - 1 * 1$	$T_{pclk1} + 1$	ns	
slave mode $1.8V \leq V_{CC} < 3.6V$		$3 \times T_{pclk1} - 1 * 1$	$3 \times T_{pclk1} + 1 * 1$	ns	
$t_w(SCKL)$					
$t_{su}(SI)$	Data input setup time	slave mode $1.8V \leq V_{CC} \leq 3.6V$	4	-	ns
$t_h(SI)$	Data input hold time	slave mode $1.8V \leq V_{CC} \leq 3.6V$	3	-	ns
$t_v(SO)$	Data output valid time	slave mode $2.7V \leq V_{CC} \leq 3.6V$	-	15	ns
		slave mode $1.8V \leq V_{CC} < 2.7V$	-	26	ns
$t_{su}(MI)$	Data input setup time	master mode $2.7V \leq V_{CC} \leq 3.6V$	5	-	ns
		master mode $1.8V \leq V_{CC} < 2.7V$	9	-	ns
$t_h(MI)$	Data input hold time	master mode $1.8V \leq V_{CC} \leq 3.6V$	$T_{pclk1} * 1$	-	ns
$t_{su}(SS)$	SS setup time	slave mode $1.8V \leq V_{CC} \leq 3.6V$	$6 \times T_{pclk1} * 1$	-	ns
		master mode $2.7V \leq V_{CC} \leq 3.6V$	$-5 + N \times T_{sck} * 1 * 2$	-	ns
		master mode $1.8V \leq V_{CC} < 2.7V$	$-10 + N \times T_{sck} * 1 * 2$	-	ns
$t_h(SS)$	SS hold time	slave mode $1.8V \leq V_{CC} \leq 3.6V$	$6 \times T_{pclk1} * 1$	-	ns
		master mode $2.7V \leq V_{CC} \leq 3.6V$	$-5 + N \times T_{sck} * 1 * 3$	-	ns
		master mode $1.8V \leq V_{CC} < 2.7V$	$-10 + N \times T_{sck} * 1 * 3$	-	ns
$t_v(MO)$	Data output valid time	master mode $2.7V \leq V_{CC} \leq 3.6V$	-	4	ns
		master mode $1.8V \leq V_{CC} \leq 2.7V$	-	9	ns

*1: T_{pclk1} refers to 1 cycle of the clock PCLK1, and T_{sck} refers to 1 cycle of the SPI communication clock.

*2: $N=1 \sim 8$ is determined by register SPI_CFG1.MSSI[2:0].

*3: $N=1 \sim 8$ is determined by register SPI_CFG1.MSSDL[2:0].

*4: The values of $t_w(SCKH)$ and $t_w(SCKL)$ are given by SPI_CFG2.MBR decision, the values listed in the table are SPI_ The value of CFG2.MBR=0.

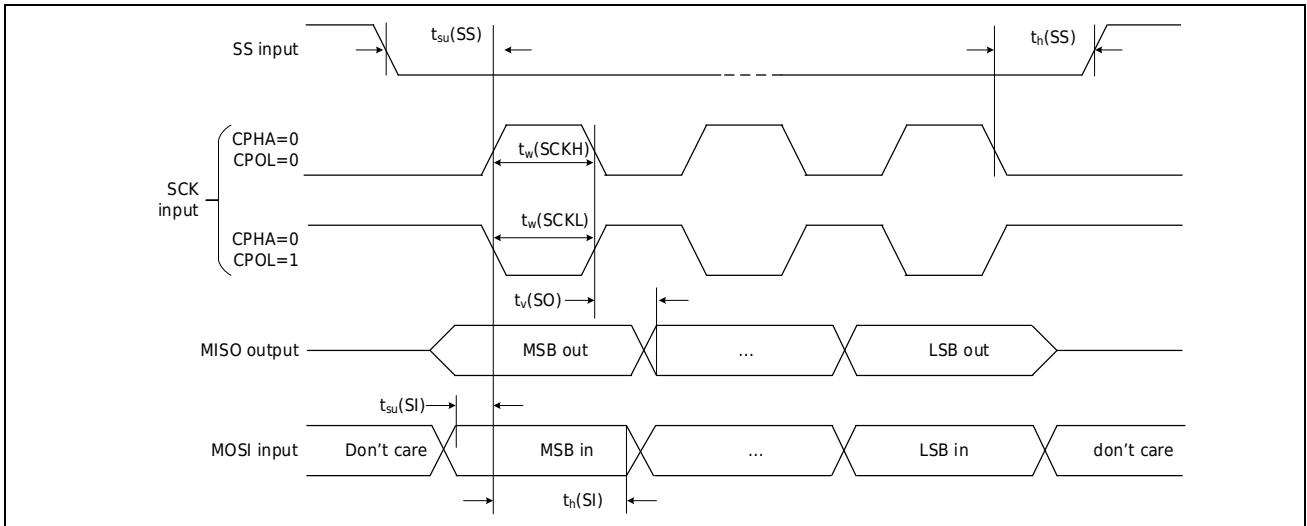


Figure 3-10 SPI timing diagram -slave mode and CPHA=0

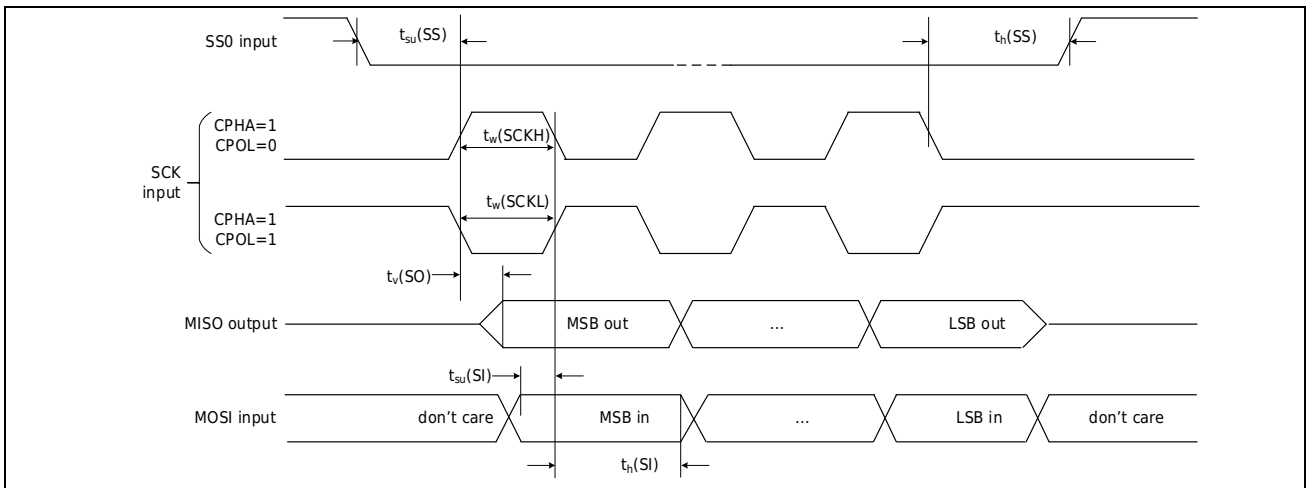


Figure 3-11 SPI timing diagram -slave mode and CPHA=1

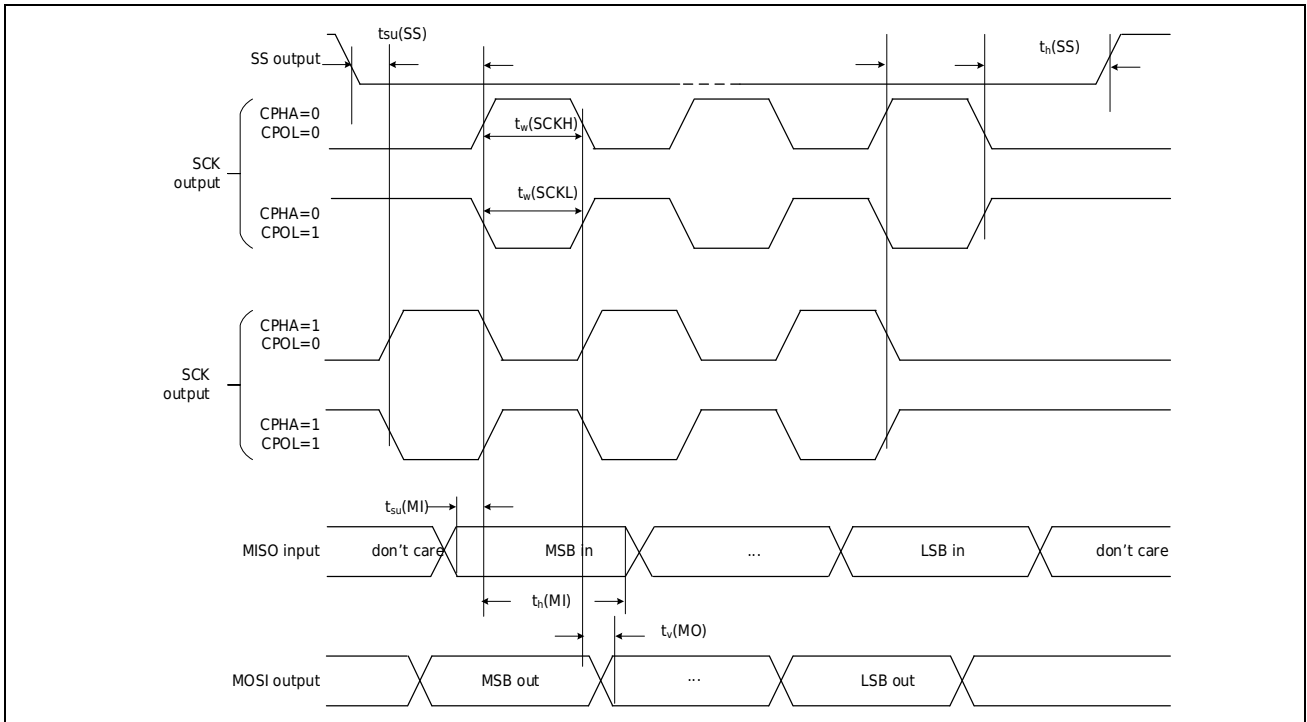


Figure 3-12 SPI timing diagram - master mode

3.3.14 QSPI Interface Characteristics

Table 3-37 QSPI Electrical Characteristics

Symbol	Parameter	Minimum value	Maximum value	Unit
t _{Qscyc}	QSPCK clock cycle	2	48	thclk
t _{QSWH}	QSPCK high level	t _{Qscyc} ×0.4	-	ns
t _{QSWL}	QSPCK low level	t _{Qscyc} ×0.4	-	ns
t _{SU}	data input setup time (2.7 V~3.6 V)	5	-	ns
	data input setup time (1.8 V~2.7 V)	5	-	ns
t _{IH}	data input hold time (2.7 V~3.6 V)	11	-	ns
	data input hold time (1.8 V~2.7 V)	15	-	ns
t _{OD}	data output delay	-	4	ns
t _{OH}	data output hold time	0	-	ns

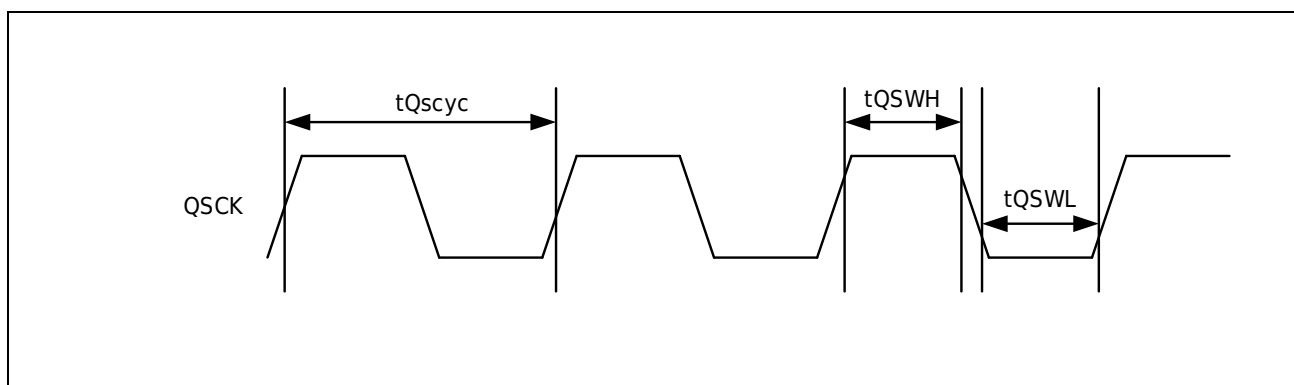


Figure 3-13 QSPCK output timing diagram

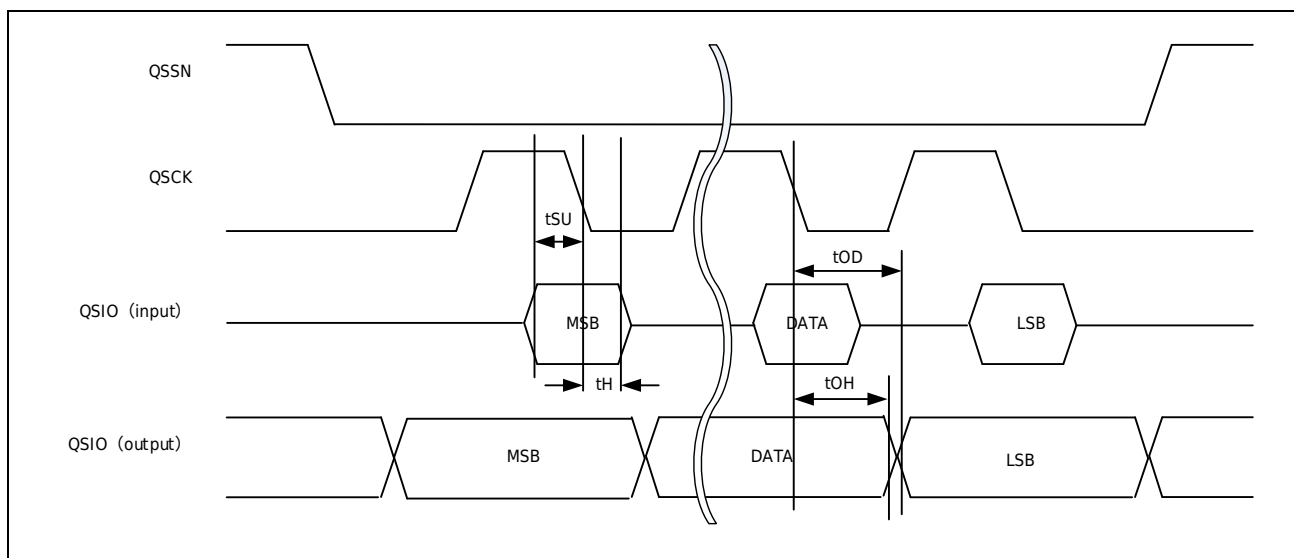


Figure 3-14 QSPI data receiving and sending timing diagram

3.3.15 I2S Interface Characteristics

Table 3-38 I2S Electrical Characteristics

Symbol	Performance	Conditions	Minimum value	Maximum value	Unit
f _{MCK}	I2S main clock output	-	256 * 8 K	256*Fs	MHz
f _{CK}	I2S clock frequency	Master data: 32 bits	20	64*Fs	MHz
		Slave data: 32 bits	-	64*Fs	
D _{CK}	I2S clock frequency duty cycle	Slave receiver	30	70	%
t _v (WS)	WS valid time	Master mode	-	6	ns
t _{su} (WS)	WS setup time	Slave mode	7.5	-	
t _h (WS)	WS hold time	Slave mode	6	-	
t _{su} (SD_MR)	Data input setup time	Master receiver (2.7 V~3.6 V)	22	-	
		Master receiver (1.8 V~2.7 V)	25	-	
t _{su} (SD_SR)		Slave receiver	7	-	
t _h (SD_MR)	Data input hold time	Master receiver	0	-	
t _h (SD_SR)		Slave receiver	7	-	
t _v (SD_ST)	Data output valid time	Slave transmitter (after enable edge)	-	24	
t _h (SD_ST)					
t _v (SD_MT)		Master transmitter (after enable edge)	-	10	

1. Fs: I2S sampling frequency

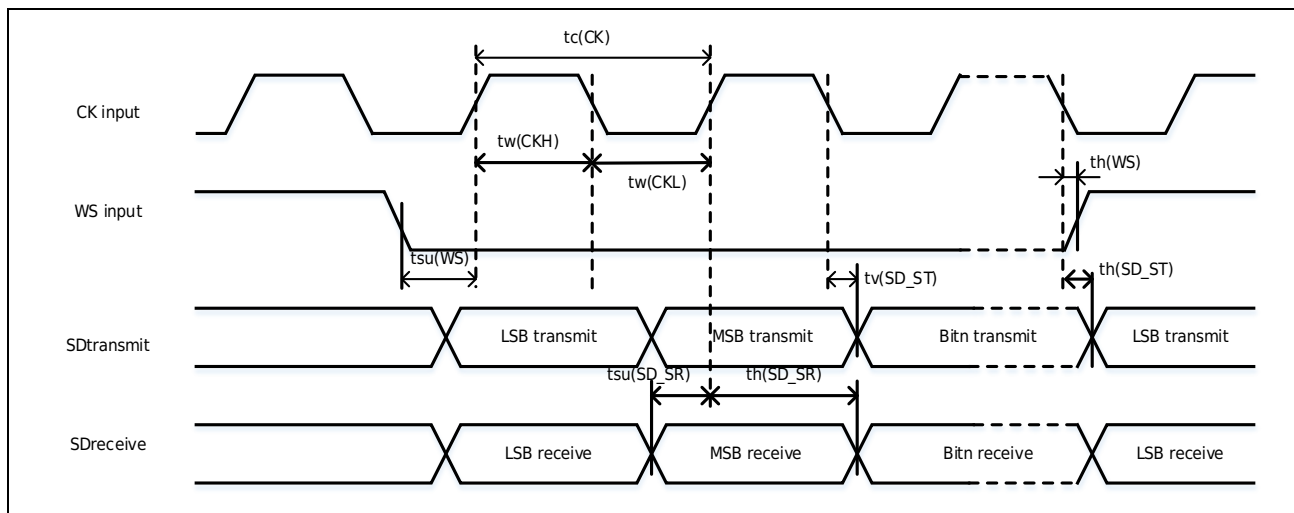


Figure 3-15 I2S slave mode timing (Philips protocol)

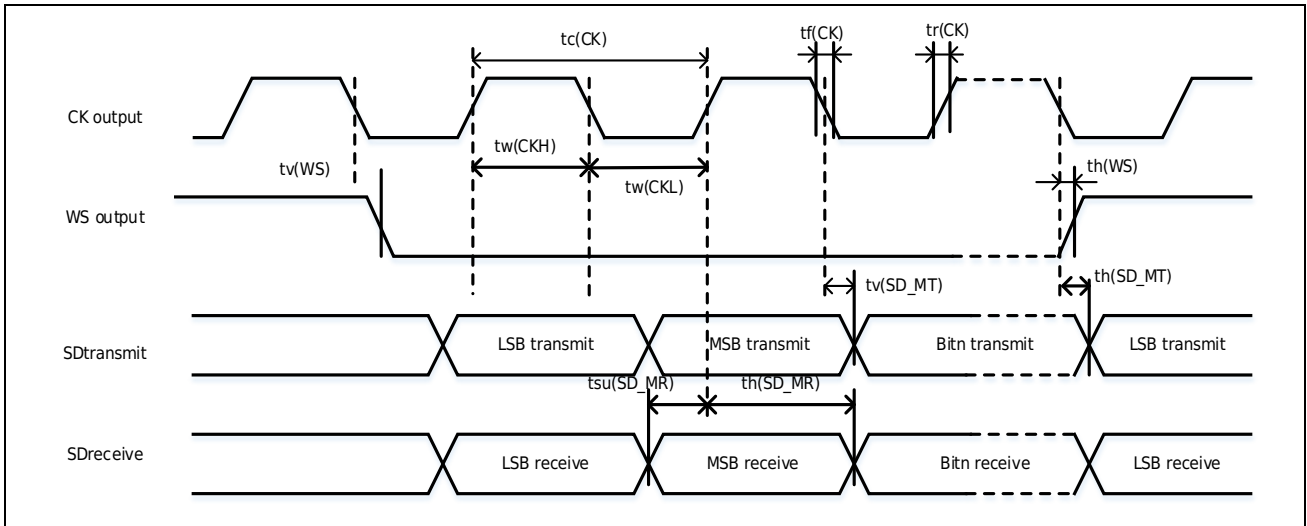


Figure 3-16 I2S host mode timing (Philips protocol)

3.3.16 CAN FD/CAN2.0B Interface Characteristics

For the port characteristics of CANx_TX and CANx_RX, please refer to [I/O port characteristics].

3.3.17 USB Interface Characteristics

Table 3-39 USB Full-Speed Electrical Characteristics

Symbol		Parameter	Conditions	Min. ⁽¹⁾	Typ.	Max. ⁽¹⁾	Unit
Input	V _{CC}	Operating Voltage	-	3.0 ⁽²⁾	-	3.6	V
	V _{IL}	input low level	-	-	-	0.8	V
	V _{IH}	input high level	-	2.0	-	-	V
	V _{DI}	Differential Input Sensitivity	-	0.2	-	-	V
	V _{CM}	Differential Common Mode Voltage	-	0.8	-	2.5	V
Output	V _{OL}	Static output low level	R _L =1.5 kΩ to 3.6 V ⁽⁴⁾	-	-	0.3	V
	V _{OH}	Static output high	R _L =15 kΩ to V _{SS} ⁽⁴⁾	2.8	-	3.6	V
	V _{CRS}	Cross-over voltage	C _L =50 pF	1.3	-	2.0	V
	t _R	Rise Time	C _L =50 pF, 10%~90% of V _{OH} -V _{OL}	4	-	20	ns
	t _F	fall time	C _L =50 pF, 10%~90% of V _{OH} -V _{OL}	4	-	20	ns
	t _{RFMA}	Rise and fall time ratio t _R /t _F	C _L =50 pF	90	-	111	%
R _{PD}	Pull-down resistance	V _{IN} = V _{CC} , in host mode	-	15.0	-	kΩ	
R _{PU} ⁽³⁾	Pull-up resistance	V _{IN} = V _{SS} , idle state	0.900	1.2	1.575	kΩ	
		V _{IN} = V _{SS} , in device mode	1.425	2.3	3.090	kΩ	
Z _{DRV}	Output impedance ⁽⁵⁾	Driving high or low	28	36	44	Ω	

1. All voltages are measured based on local ground potential.
2. When operating down to 2.7 V, the functionality of the USB full-speed transceiver is still guaranteed, but the full USB full-speed electrical characteristics are not guaranteed, which degrades over the V_{CC} voltage range of 2.7 to 3.0 V.
3. Guarantee of mass production test.
4. R_L is the load connected to the USB full speed drive.
5. The DP and DM ports do not need an external series resistor for impedance matching, and the driver output already includes the matching resistor.
6. The DP and DM ports do not need external pull-up/ pull-down resistors, and the PHY is integrated inside.

Table 3-40 USB Low-Speed Electrical Characteristics

Symbol	Parameter	Conditions	Min. ⁽¹⁾	Typ.	Max. ⁽¹⁾	Unit	
Input	V _{CC}	Operating Voltage	-	3.0 ⁽²⁾	-	3.6	V
	V _{IL}	input low level	-	-	0.8	V	
	V _{IH}	input high level	-	2.0	-	V	
	V _{DI}	Differential Input Sensitivity	-	0.2	-	V	
	V _{CM}	Differential Common Mode Voltage	-	0.8	-	2.5	V
Output	V _{OL}	Static output low level	R _L =1.5 kΩ to 3.6 V ⁽⁴⁾	-	-	0.3	V
	V _{OH}	Static output high	R _L =15 kΩ to V _{SS} ⁽⁴⁾	2.8	-	3.6	V
	V _{CRS}	Cross-over voltage	C _L =200 pF~600 pF	1.3	-	2.0	V
	t _R	Rise Time	C _L =200 pF~600 pF, 10%~90% of V _{OH} -V _{OL}	75	-	300	ns
	t _F	fall time	C _L =200 pF~600 pF, 10%~90% of V _{OH} -V _{OL}	75	-	300	ns
t _{RFMA}	Rise and fall time ratio t _R /t _F	C _L =200 pF~600 pF	80	-	125	%	
R _{PD}	pull-down resistor	V _{IN} = V _{CC} , in host mode	-	15.0	-	kΩ	
Z _{DRV}	Output Impedance ⁽⁵⁾	Driving high or low	28	36	44	Ω	

1. All voltages are measured based on local ground potential.
2. When operating down to 2.7 V, the functionality of the USB low-speed transceiver is still guaranteed, but the full USB low-speed electrical characteristics are not guaranteed, which will degrade over the V_{CC} voltage range of 2.7 to 3.0 V.
3. Guarantee of mass production test.
4. R_L is the load connected to the USB low speed drive.
5. The DP and DM ports do not need an external series resistor for impedance matching, and the driver output already includes the matching resistor.
6. The DP and DM ports do not need external pull-up/ pull-down resistors, and the PHY is integrated inside.

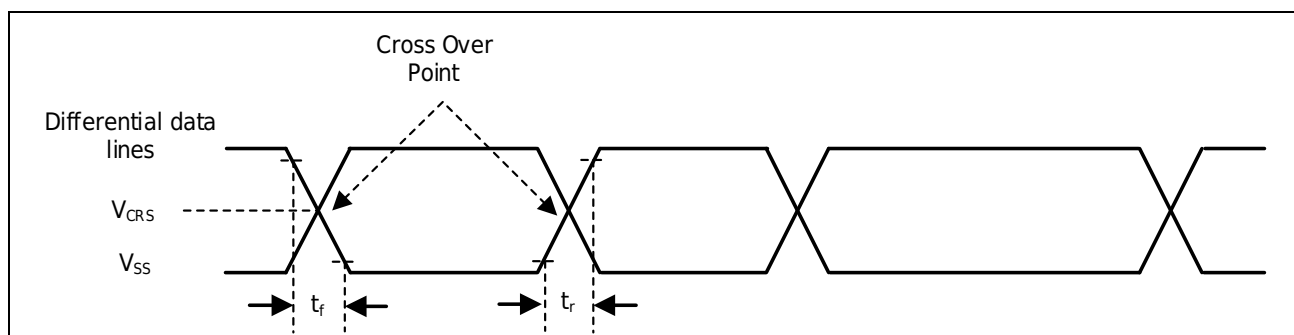


Figure 3-17 Definition of USB Rise/ Fall Time and Cross Over Voltage

Table 3-41 ULPI HS Clock Timing Parameters

Symbol	Parameters (1)	Conditions	Minimum(2)	Typical value (2)	Max(2)	Unit
t_{SC}	Control signal setup time (ULPI_DIR, ULPI_NXT) setup time	2.7 V ≤ V _{CC} ≤ 3.6 V C _L = 20 pF -40 ~ 105 °C	3.0	-	-	ns
t_{HC}	Control signal hold time (ULPI_DIR, ULPI_NXT) hold time		2.0	-	-	ns
t_{SD}	data creation time		3.0	-	-	ns
t_{HD}	data retention time		2.2	-	-	ns
t_{DC}/t_{DD}	Data/Control Signal Output Delay		4.5	7.5	10.6	ns

1. The ULPI_CLK clock needs to follow the UTMI+ Low Pin Interface Specification, Revision 1.1, 20/10/2004 protocol.
2. The corresponding IO should be set to high drive.

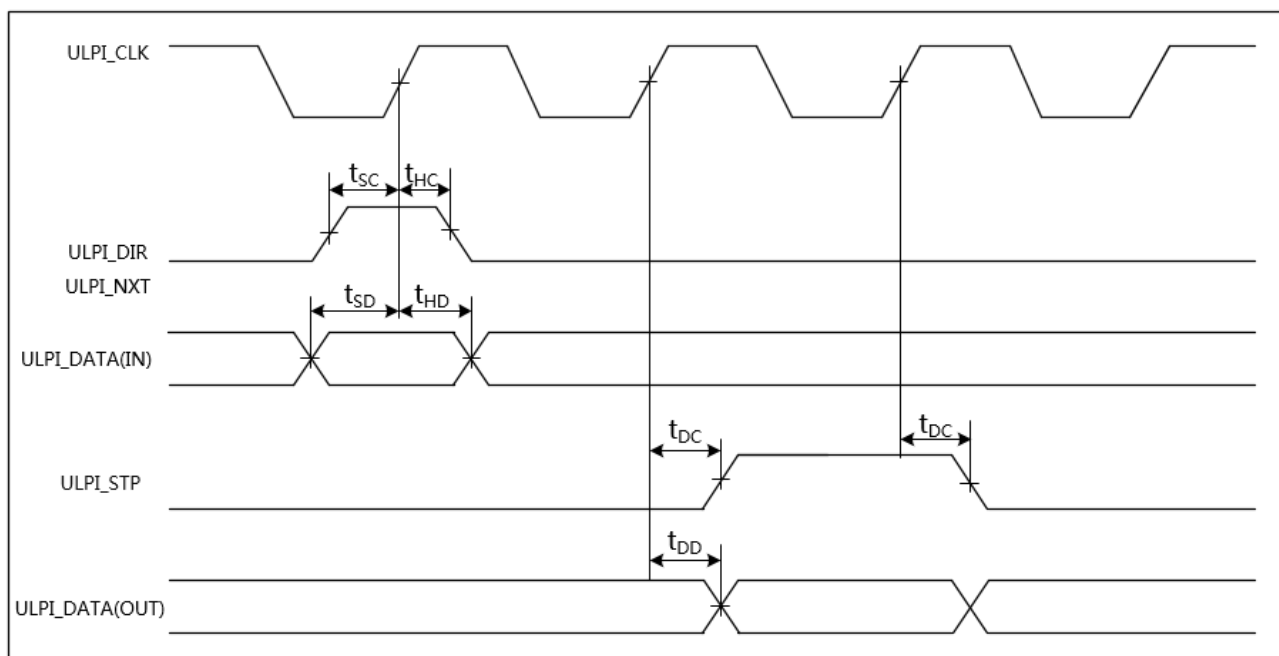


Figure 3-18 ULPI Timing Diagram

3.3.18 ETHMAC Characteristics

3.3.18.1 SMI Interface

Table 3-42 ETHMAC_SMI interface characteristics

Symbol	Parameter	Min	Typ	Max	Unit
t_mdc	SMI_MDC output frequency	400	420	425	ns
t_mdo_d	SMI_MDO output delay time (2.7 V~3.6 V)	-	-	Tpclk1+9	ns
	SMI_MDO output delay time (1.8 V~2.7 V)	-	-	Tpclk1+12	ns
t_mdi_s	SMI_MDI input Setup time	11	-	-	ns
t_mdi_h	SMI_MDI input Hold time	0	-	-	ns

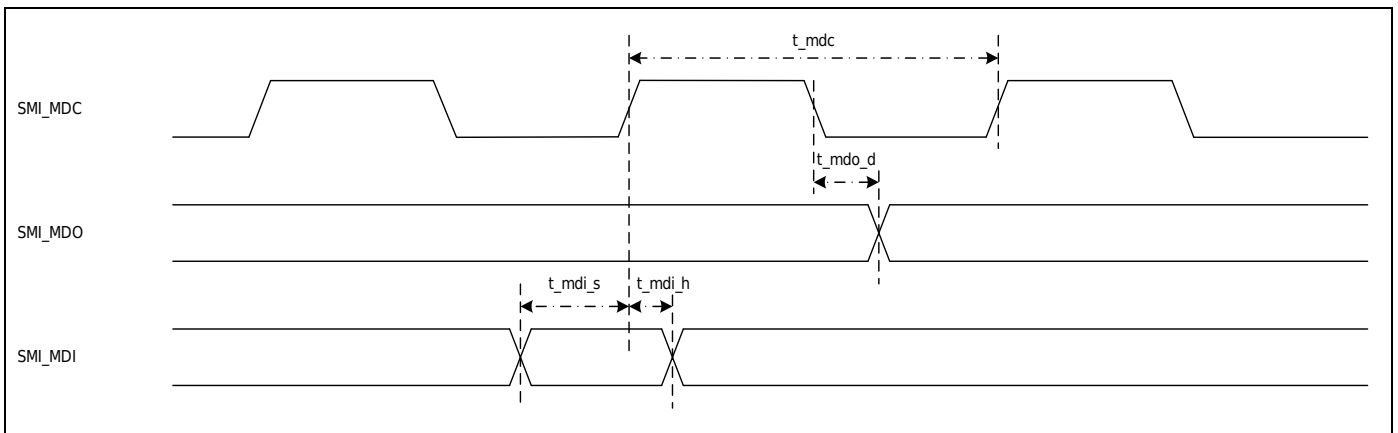


Figure 3-19 ETHMAC-SMI interface timing diagram

3.3.18.2 MII Interface

Table 3-43 ETHMAC_MII interface characteristics

Symbol	Parameter	Min	Typ	Max	Unit
t_mii_tx_clk	MII_TX_CLK clock input frequency	-	40	-	ns
t_mii_txen_d	MII_TX_EN output delay time (2.7 V~3.6 V)	5	-	15	ns
	MII_TX_EN output delay time (1.8 V~2.7 V)	5	-	21	ns
t_mii_txer_d	MII_TX_ER output delay time (2.7 V~3.6 V)	5	-	15	ns
	MII_TX_ER output delay time (1.8 V~2.7 V)	5	-	21	ns
t_mii_txd_d	MII_TXD output delay time (2.7 V~3.6 V)	5	-	15	ns
	MII_TXD output delay time (1.8 V~2.7 V)	5	-	21	ns
t_mii_rx_clk	MII_RX_CLK clock input frequency	-	40	-	ns
t_mii_rxdv_s	MII_RX_DV input Setup time	8	-	-	ns
t_mii_rxdv_h	MII_RX_DV input Hold time	4	-	-	ns
t_mii_rxer_s	MII_RX_ER input Setup time	8	-	-	ns
t_mii_rxer_h	MII_RX_ER input Hold time	4	-	-	ns
t_mii_rxd_s	MII_RXD input Setup time	8	-	-	ns
t_mii_rxd_h	MII_RXD input Hold time	4	-	-	ns

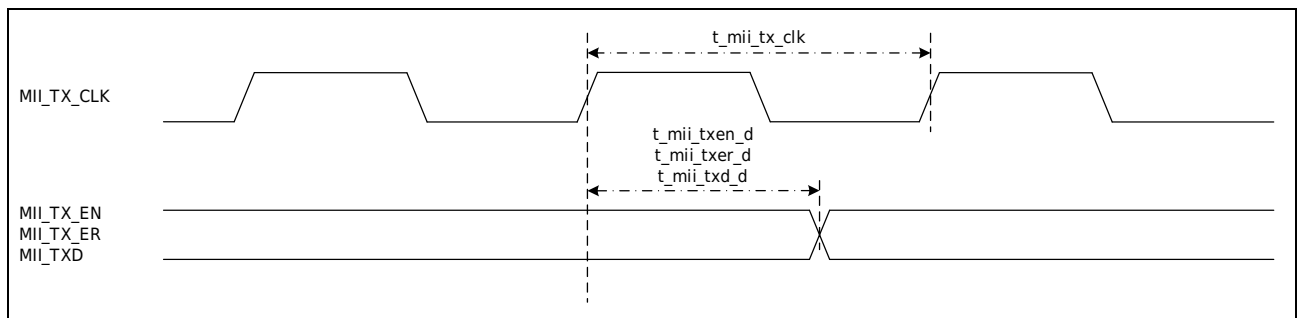


Figure 3-20 ETHMAC-MII interface output signal timing diagram

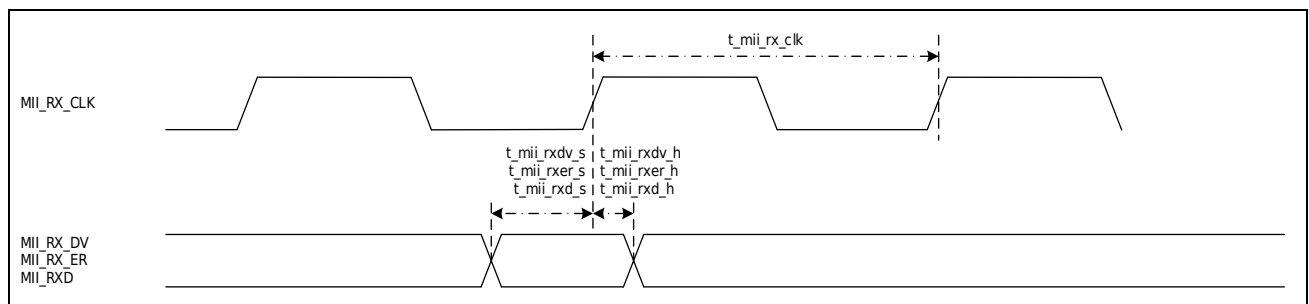


Figure 3-21 ETHMAC-MII interface input signal timing diagram

3.3.18.3 RMI Interface

Table 3-44 ETHMAC_RMII interface characteristics

Symbol	Parameter	Min	Typ	Max	Unit
t_rmii_clk	RMII_REF_CLK reference clock input frequency	-	20	-	ns
t_rmii_txen_d	RMII_TX_EN output delay time (2.7 V~3.6 V)	5	-	12.5	ns
	RMII_TX_EN output delay time (1.8 V~2.7 V)	5	-	15	ns
t_rmii_txd_d	RMII_TXD output delay time (2.7 V~3.6 V)	5	-	12.5	ns
	RMII_TXD output delay time (1.8 V~2.7 V)	5	-	15	ns
t_rmii_crsdv_s	RMII_CRSDV input Setup time	4	-	-	ns
t_rmii_crsdv_h	RMII_CRSDV input Hold time	2	-	-	ns
t_rmii_rxd_s	RMII_RXD input Setup time	4	-	-	ns
t_rmii_rxd_h	RMII_RXD input Hold time	2	-	-	ns

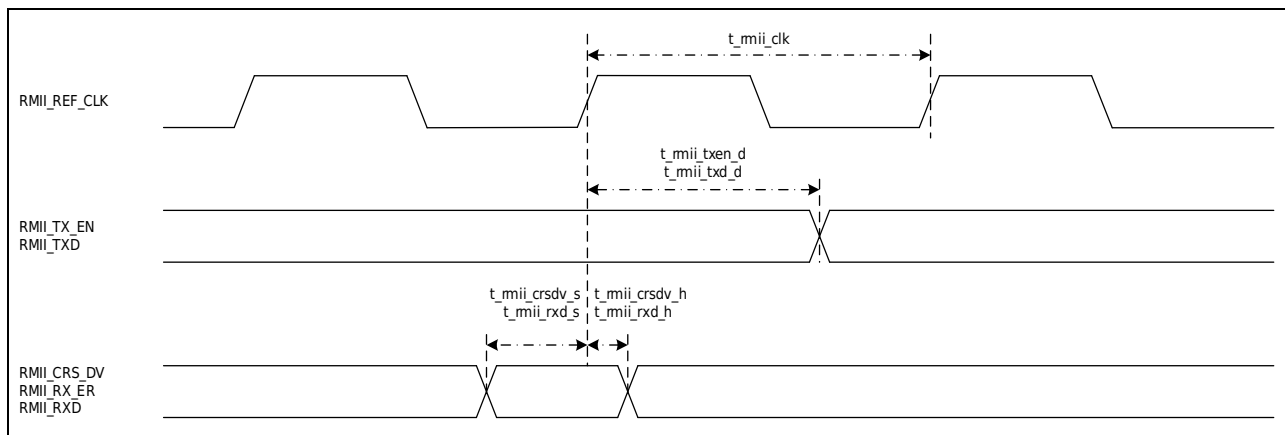


Figure 3-22 ETHMAC-RMII interface timing diagram

3.3.19 USART Interface Characteristics

Table 3-45 USART AC Timing

Symbol	Parameter		Minimum value	Maximum value	Unit
t_{cyc}	Input clock cycles	UART	4	-	t_{PCLK1}
		Clock synchronization mode	6	-	
t_{CKW}	input clock width		0.4	0.6	t_{cyc}
t_{CKr}	Input clock rise time		-	5	ns
t_{CKf}	Input clock fall time		-	5	ns
t_{TD}	send delay time $2.7 V \leq V_{CC} \leq 3.6 V$	Clock synchronization mode	-	23	ns
	send delay time $1.8 V \leq V_{CC} < 2.7 V$	Clock synchronization mode	-	30	ns
t_{RDS}	Receive data setup time $2.7 V \leq V_{CC} \leq 3.6 V$	Clock synchronization mode	17	-	ns
	Receive data setup time $1.8 V \leq V_{CC} < 2.7 V$	Clock synchronization mode	23	-	ns
t_{RDH}	Receive data hold time	Clock synchronization mode	5	-	ns

Table 3-46 USART AC Timing

Pattern		Highest baud rate
UART	Internal timer	$PCLK1/8$
	External timer	$PCLK1/32$
Clock synchronization mode $2.7 V \leq V_{CC} \leq 3.6 V$		12.0Mbps
Clock synchronization mode $1.8 V \leq V_{CC} < 2.7 V$		8.0Mbps

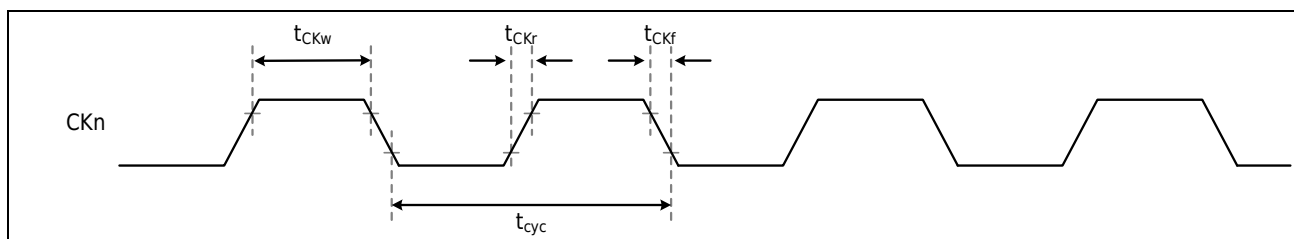


Figure 3-23 USART clock timing

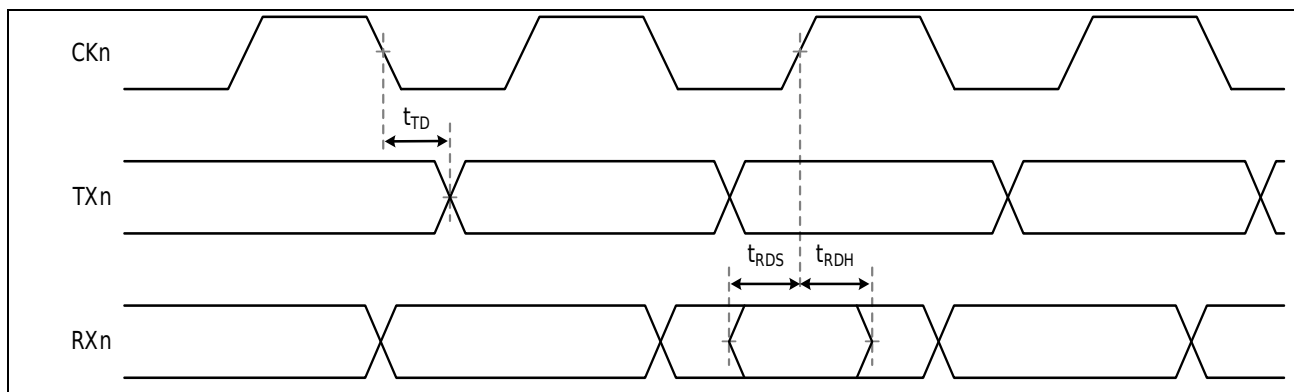


Figure 3-24 USART (CSI) input and output timing

3.3.20 JTAG Interface Characteristics

Table 3-47 JTAG interface features

Symbol	Item	Min	Typ	Max	Unit
t_{TCKcyc}	JTCK clock cycle time	50	-	-	ns
t_{TCKH}	JTCK clock high pulse width	15	-	-	ns
t_{TCKL}	JTCK clock low pulse width	15	-	-	ns
t_{TCKr}	JTCK clock rise time	-	-	5	ns
t_{TCKf}	JTCK clock fall time	-	-	5	ns
t_{TMSS}	JTMS setup time	10	-	-	ns
t_{TMSh}	JTMS hold time	10	-	-	ns
t_{TDIs}	JTDI setup time	10	-	-	ns
t_{TDIh}	JTDI hold time	10	-	-	ns
t_{TDod}	JTDO data delay time	10	-	25	ns

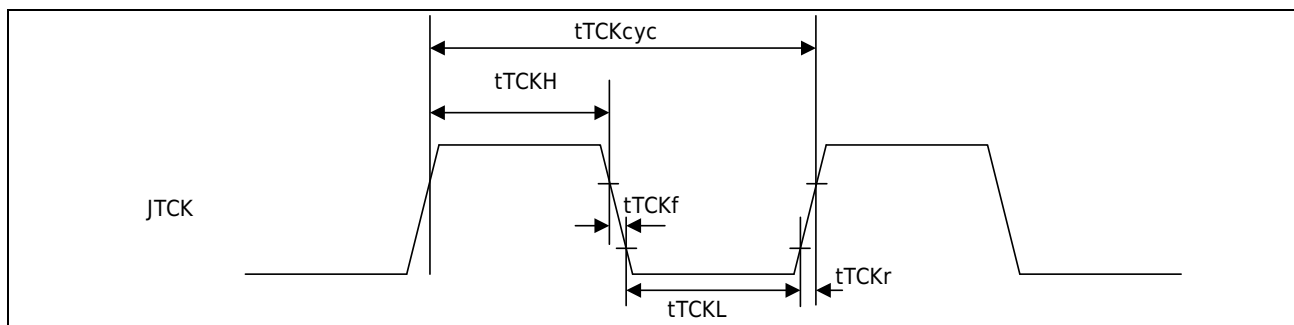


Figure 3-25 JTAG TCK clock

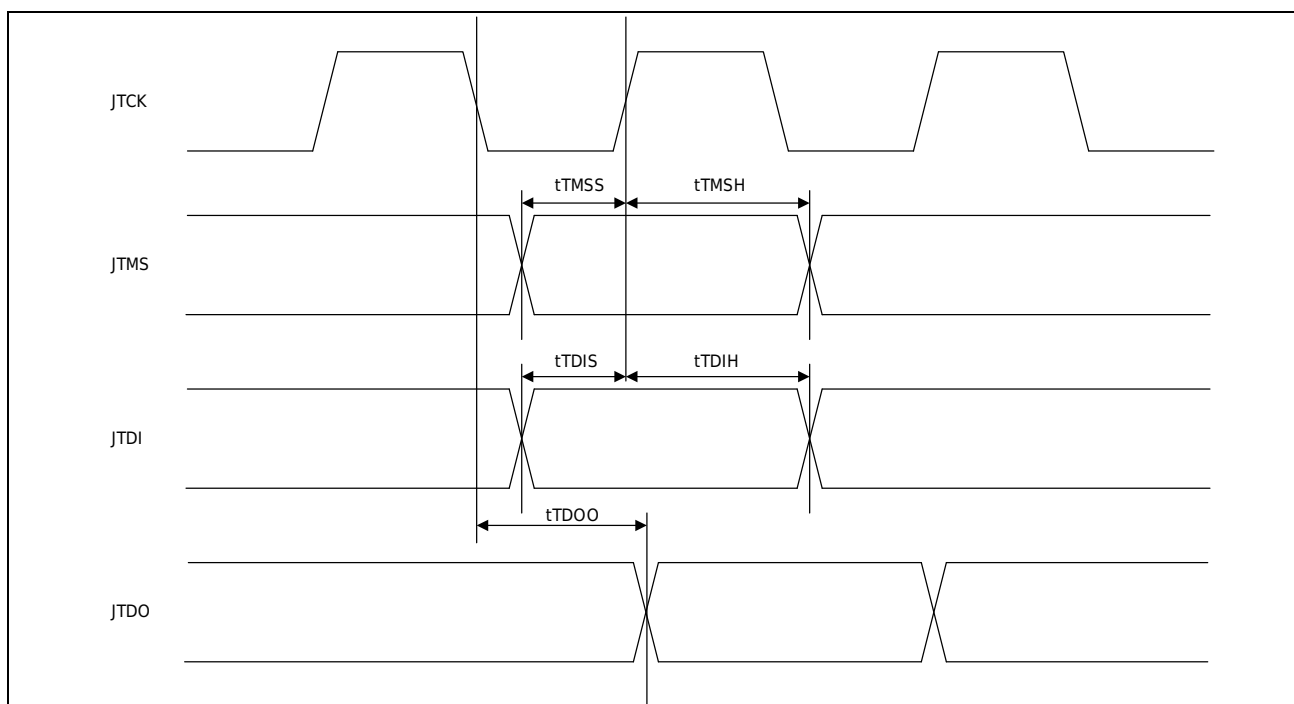


Figure 3-26 JTAG input and output

3.3.21 SWD Interface Characteristics

Table 3-48 SWD interface features

Symbol	Item	Min	Typ	Max	Unit
t _{SWCLKcyc}	SWCLK clock cycle time	50	-	-	ns
t _{SWCLKH}	SWCLK clock high pulse width	15	-	-	ns
t _{SWCLKL}	SWCLK clock low pulse width	15	-	-	ns
t _{SWCLKr}	SWCLK clock rise time	-	-	5	ns
t _{SWCLKf}	SWCLK clock fall time	-	-	5	ns
t _{SWDIs}	SWDI setup time	10	-	-	ns
t _{SWDIh}	SWDI hold time	10	-	-	ns
t _{SWDOd}	SWDO data delay time	10	-	25	ns

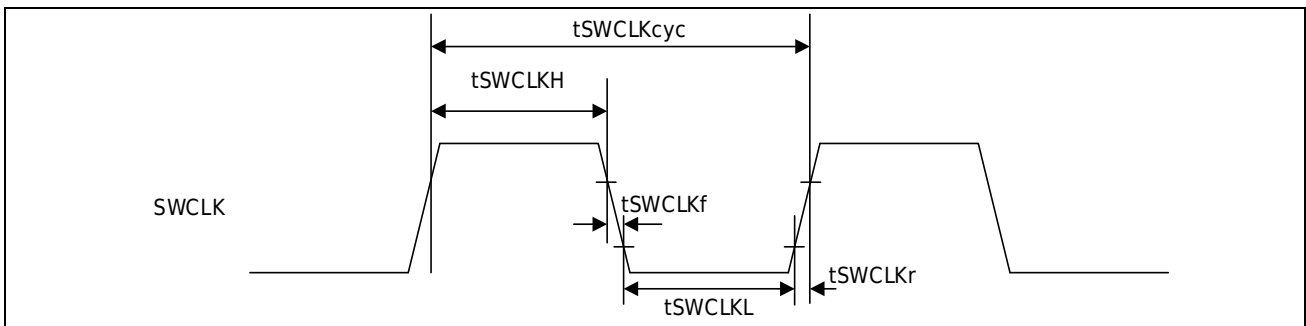


Figure 3-27 SWD SWCLK clock

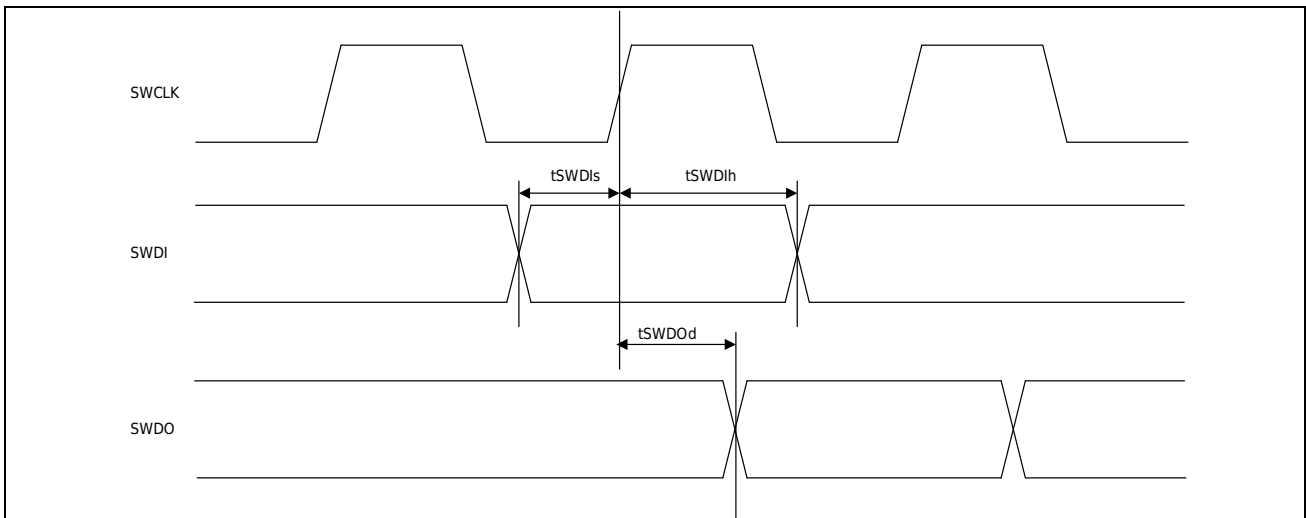


Figure 3-28 SWDIO input and output

3.3.22 ETM Interface Characteristics

Table 3-49 ETM interface features

Symbol	Item	Min	Typ	Max	Unit
$t_{TRCLKcyc}$	TRACECK clock cycle time	20	-	-	ns
t_{TRCKH}	TRACECK clock high pulse width	7	-	-	ns
t_{TRCKL}	TRACECK clock low pulse width	7	-	-	ns
t_{TRCKr}	TRACECK clock rise time	-	-	2.5	ns
t_{TRCKf}	TRACECK clock fall time	-	-	2.5	ns
t_{TRDd}	TRACED [3:0] output delay time	1.6	-	8.4	ns

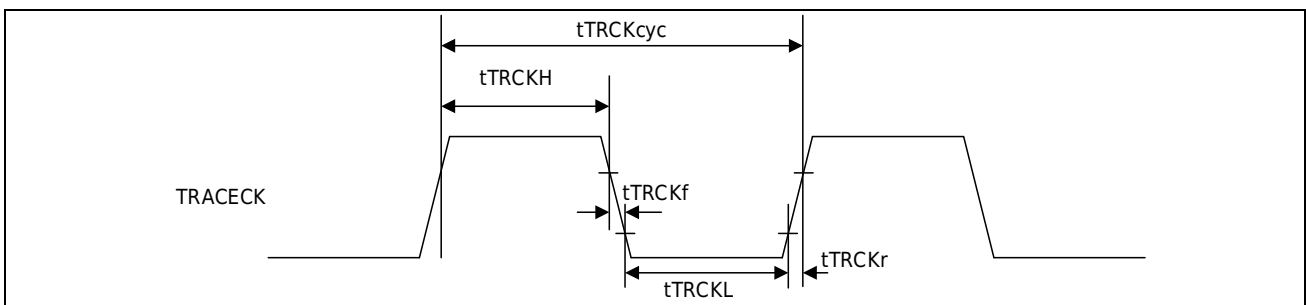


Figure 3-29 TRACE clock

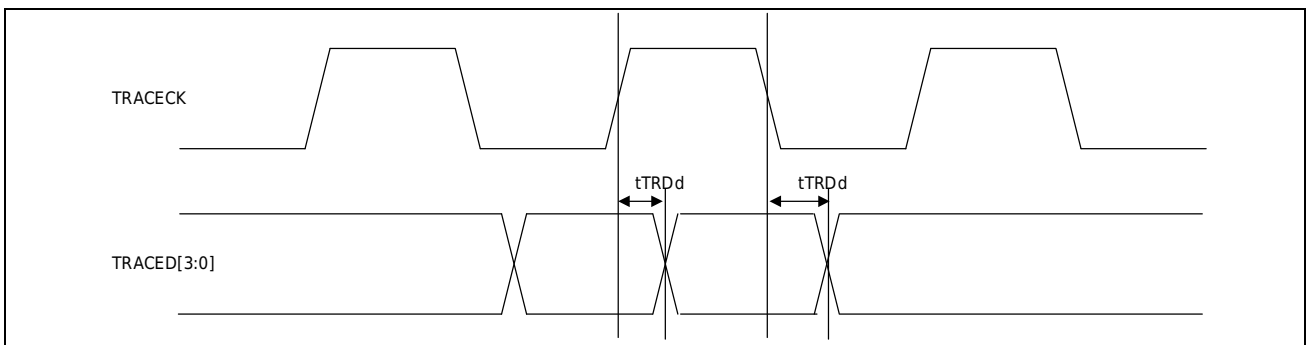


Figure 3-30 TRACE DATA output

3.3.23 12-bit ADC Characteristic

Table 3-50 ADC characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{AVCC}	Power supply	-	1.8	-	3.6	V
V _{REFH} ⁽¹⁾	Positive reference voltage	-	1.8	-	V _{AVCC}	V
f _{ADC}	ADC conversion clock frequency	In high-speed working mode V _{AVCC} = 2.4 ~ 3.6 V	1	-	60	MHz
		In low speed working mode V _{AVCC} = 1.8 ~ 2.4 V	1	-	30	
		Ultra-low speed working mode	1	-	8	
V _{AIN}	Conversion voltage range	-	V _{REFL}	-	V _{REFH}	V
R _{AIN}	External input impedance	Refer to Formula 1 for details	-	-	50	kΩ
R _{ADC}	Sampling switch resistance	-	-	3	6	kΩ
C _{ADC}	Internal sampling and retention capacitance	-	-	4	7	Pf
t _d	Trigger conversion delay	f _{ADC} = 60 MHz	-	-	0.3	μs

Table 3-51 ADC Characteristics (continued)

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
t _s	Sampling time	f _{ADC} = 60 MHz	0.183	-	4.266	μs
			11	-	255	1/f _{ADC}
t _{CONV}	Single-channel total conversion time (Including sampling time)	f _{ADC} = 60 MHz 12 bit resolution	0.4	-	-	μs
		f _{ADC} = 60 MHz 10-bit resolution	0.37	-	-	μs
		f _{ADC} = 60 MHz 8-bit resolution	0.34	-	-	μs
		20 to 268 (Sampling time T _s + successively approaching n-bit resolution+1)	-	-	-	1/f _{ADC}
f _s	Sampling rate f _{ADC} = 60 MHz	12-Bit Resolution Single ADC	-	-	2.5	Msp/s
t _{ST}	Power-on time	-	-	1	2	μs

1. 0 ≤ V_{AVCC} - V_{REFH} ≤ 1.2 V

Formula 1: RAIN maximum formula

$$R_{AIN} = \frac{k-1}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$$

The above formula (Formula 1) is used to determine the maximum external impedance to make the error lower than 1/4 LSB. Where N = 12 (12bit resolution), k is the number of sampling cycles defined in the ADC_SSTR register.

Table 3-52 ADC123_IN0~3, ADC12_IN4~9, ADC12_IN14~15 input channel accuracy @ $f_{ADC} = 60$ MHz

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
E_T	Absolute error	$f_{ADC} = 60$ MHz Input source impedance < 1 K Ω $V_{REFH} = V_{AVCC} = 2.4 \sim 3.6$ V	± 4.5	± 6	LSB
E_O	Offset error		± 3.5	± 6	LSB
E_G	Gain error		± 3.5	± 6	LSB
E_D	Differential Nonlinear Error		± 1	± 3	LSB
E_L	Integral nonlinear error		± 1.5	± 4	LSB

Table 3-53 ADC123_IN0~3, ADC12_IN4~9, ADC12_IN14~15 input channel accuracy @ $f_{ADC} = 8/30$ MHz

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
E_T	Absolute error	$f_{ADC} = 8/30$ MHz Input source impedance < 1 K Ω $V_{REFH} = V_{AVCC} = 1.8$ V	± 4.5	± 6	LSB
E_O	Offset error		± 3.5	± 6	LSB
E_G	Gain error		± 3.5	± 6	LSB
$E_D^{(1)}$	Differential Nonlinear Error		± 1	± 3	LSB
$E_L^{(1)}$	Integral nonlinear error		± 1.5	± 4	LSB

1. Guarantee of mass production test.

Table 3-54 ADC123_IN0~3, ADC12_IN4~9, ADC12_IN14~15 Input Channel Accuracy @ $f_{ADC} = 60$ MHz

Symbol	Parameter	Conditions	Minimum value	Maximum value	Unit
ENOB	significant digits	$f_{ADC} = 60$ MHz Input signal frequency = 2 kHz Input source impedance = 0ohm $V_{REFH} = V_{AVCC} = 2.4 \sim 3.6$ V	10.5	-	Bits
SINAD	Signal-to-noise harmonic ratio		64.3	-	dB
SNR	signal to noise ratio		64.4	-	dB
THD	total harmonic distortion		-	-78.1	dB

Table 3-55 ADC123_IN0~3, ADC12_IN4~9, ADC12_IN14~15 Input Channel Accuracy @ $f_{ADC} = 8/30$ MHz

Symbol	Parameter	Conditions	Minimum value	Maximum value	Unit
ENOB	significant digits	$f_{ADC} = 8/30$ MHz Input signal frequency = 2 kHz Input source impedance = 0ohm $V_{REFH} = V_{AVCC} = 1.8$ V	10.6	-	Bits
SINAD	Signal-to-noise harmonic ratio		67.0	-	dB
SNR	signal to noise ratio		67.1	-	dB
THD	total harmonic distortion		-	-75.1	dB

Table 3-56 ADC12_IN10~13, ADC3_IN4~15 input channel accuracy @ $f_{ADC} = 60$ MHz

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
E _T	Absolute error	$f_{ADC} = 60$ MHz Input source impedance <1 K Ω $V_{REFH} = V_{AVCC} = 2.4 \sim 3.6$ V	± 5.5	± 7	LSB
E _O	Offset error		± 4.5	± 7	LSB
E _G	Gain error		± 4.5	± 7	LSB
E _D	Differential Nonlinear Error		± 1.5	± 3	LSB
E _L	Integral nonlinear error		± 2.0	± 4	LSB

Table 3-57 ADC12_IN10~13, ADC3_IN4~15 input channel accuracy @ $f_{ADC} = 30$ MHz

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
E _T	Absolute error	$f_{ADC} = 8/30$ MHz Input source impedance <1 K Ω $V_{REFH} = V_{AVCC} = 1.8$ V	± 5.5	± 7	LSB
E _O	Offset error		± 4.5	± 7	LSB
E _G	Gain error		± 4.5	± 7	LSB
E _D ⁽¹⁾	Differential Nonlinear Error		± 1.5	± 3	LSB
E _L ⁽¹⁾	Integral nonlinear error		± 2.0	± 4	LSB

1. Guarantee of mass production test.

Table 3-58 ADC12_IN10~12, ADC3_IN4~15 Input Channel Dynamic Accuracy @ $f_{ADC} = 60$ MHz

Symbol	Parameter	Conditions	Minimum value	Maximum value	Unit
ENOB	significant digits	$f_{ADC} = 60$ MHz Input signal frequency = 2 kHz Input source impedance = 0ohm $V_{REFH} = V_{AVCC} = 2.4 \sim 3.6$ V	10.5	-	Bits
SINAD	Signal-to-noise harmonic ratio		64.4	-	dB
SNR	signal to noise ratio		64.4	-	dB
THD	total harmonic distortion		-	-80.3	dB

Table 3-59 ADC12_IN10~13, ADC3_IN4~15 input channel dynamic accuracy @ $f_{ADC} = 8/30$ MHz

Symbol	Parameter	Conditions	Minimum value	Maximum value	Unit
ENOB	significant digits	$f_{ADC} = 8/30$ MHz Input signal frequency = 2 kHz Input source impedance = 0ohm $V_{REFH} = V_{AVCC} = 1.8$ V	10.6	-	Bits
SINAD	Signal-to-noise harmonic ratio		66.6	-	dB
SNR	signal to noise ratio		66.8	-	dB
THD	total harmonic distortion		-	-79.4	dB

Table 3-60 ADC+Sample and Hold Circuit Channel Accuracy @ $f_{ADC} = 60$ MHz

Symbol	Parameter	Conditions	Typical value	Maximum value	Unit
E _T	Absolute error	$f_{ADC} = 60$ MHz Input source impedance = 1 K Ω $V_{REFH} = V_{AVCC} = 2.7 \sim 3.6$ V	± 6.0	± 8.0	LSB
E _O	Offset error		± 6.0	± 8.0	LSB
E _G	Gain error		± 6.0	± 8.0	LSB
E _D	Differential Nonlinear Error		± 2	± 3	LSB
E _L	Integral nonlinear error		± 3	± 4	LSB

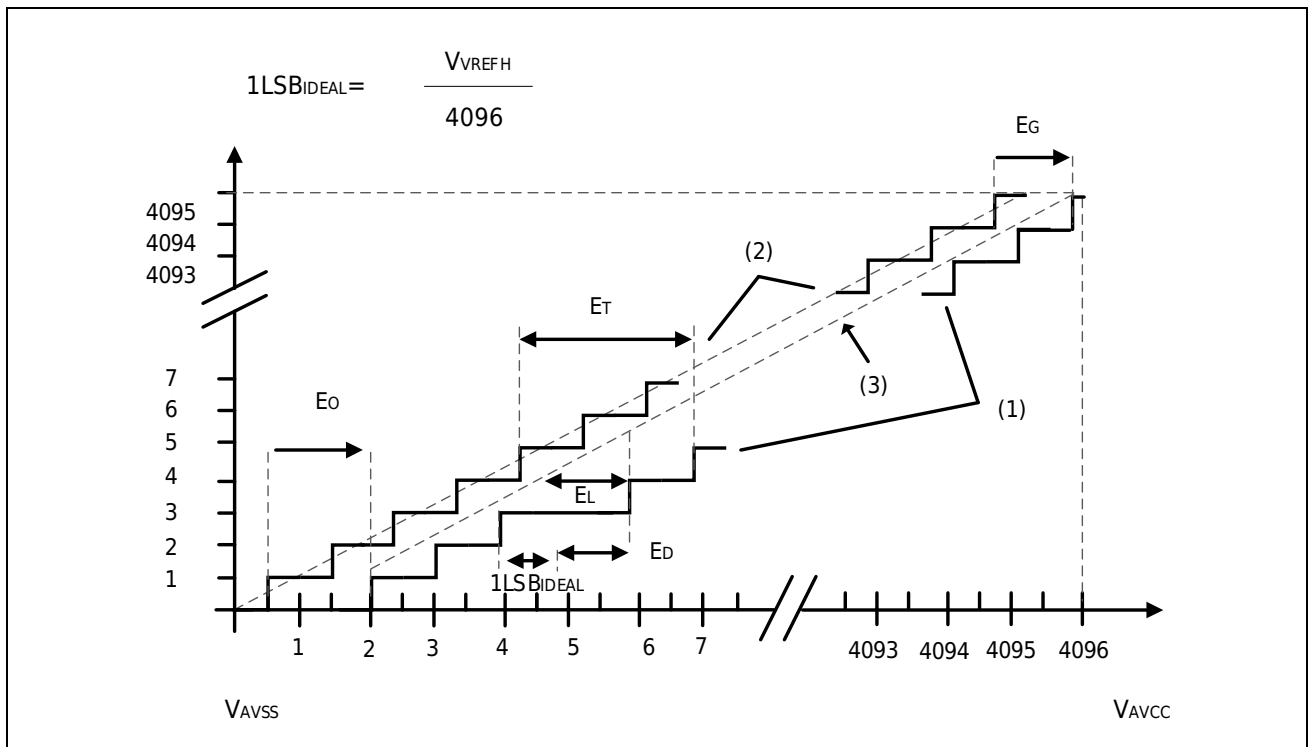


Figure 3-31 ADC Accuracy Characteristics

1. Examples of actual transmission curves.
2. Ideal transfer curve.
3. Endpoint correlation line.
4. E_T = total unadjusted error: Maximum deviation between actual and ideal transmission curves.
 E_O = offset error: Deviation between the first actual transition and the first ideal transition.
 E_G = gain error: Deviation between the last ideal conversion and the last actual conversion.
 E_D = differential nonlinearity error: Maximum deviation between actual step and ideal value.
 E_L = integral nonlinearity error: The maximum deviation between any actual transformation and the endpoint correlation line.

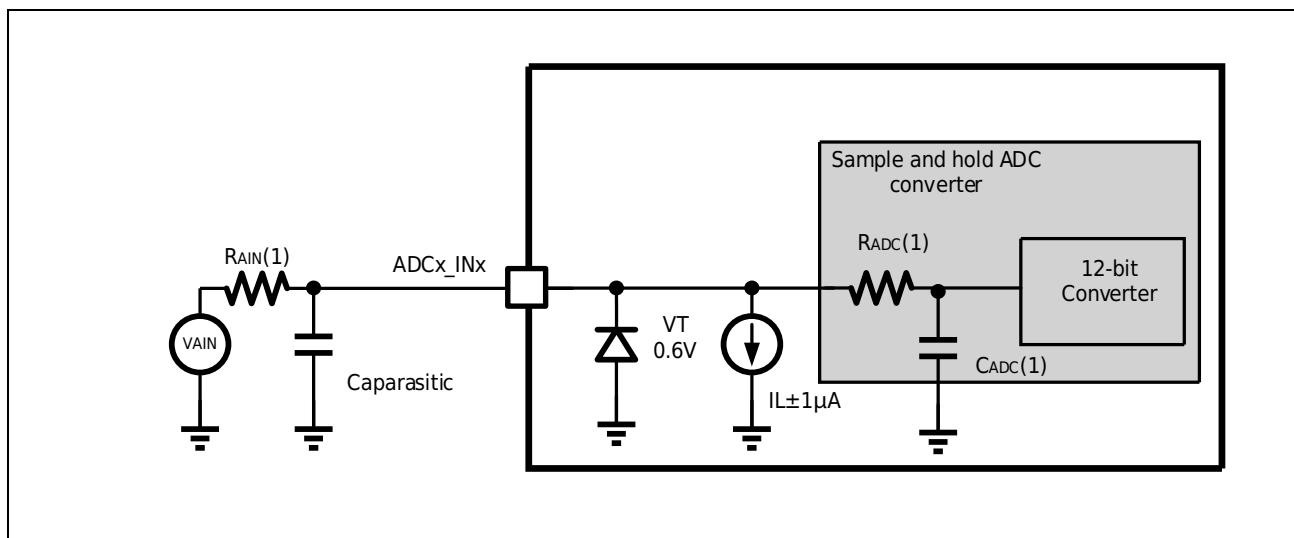


Figure 3-32 Typical Connection Using ADC

1. About R_{AIN} , R_{ADC} and C_{ADC} value information, see Table 3-50.
2. $C_{parasitic}$ means PCB capacitance (depending on soldering and PCB routing quality) and pad capacitance (about 5 Pf). Higher $C_{parasitic}$ value will result in lower conversion accuracy. To solve this problem, the F_{adc} .

General PCB design guidelines

The power supply should be decoupled as shown in the diagram below, depending on whether VREFH is connected to AVCC and the number of AVCC pins. The $0.1\mu\text{F}$ capacitor should be a (high quality) ceramic capacitor. These capacitors should be as close as possible to the core piece.

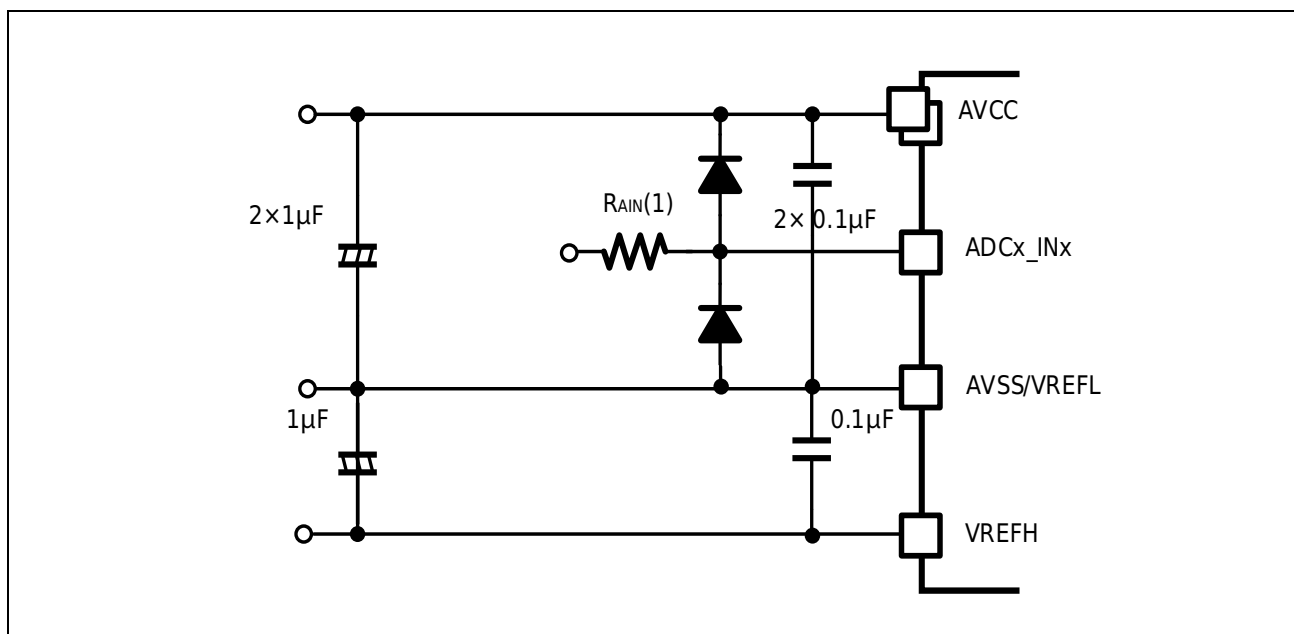


Figure 3-33 Supply and Reference Supply Decoupling Example

3.3.24 12-bit DAC Characteristics

Table 3-61 12-bit DAC port output enabled and output amplifier enabled characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{AVCC}	Analog supply voltage	-	1.8	3.3	3.6	V
Aref	Reference Supply Voltage (V _{REFH})	= V _{AVCC}	1.8	3.3	3.6	V
AO	Output voltage range	-	0.2	-	Aref-0.2	-
RL	Load Resistance	-	5	-	-	kΩ
CL	Load capacitance	-	-	-	50	Pf
DNL ⁽¹⁾	Differential nonlinearity error (deviation between two consecutive codes - 1LSB)	-	-	-	3 ⁽¹⁾	LSB
INL ⁽¹⁾	Integral nonlinearity error (difference between the value measured at code I and the value at code I on the line between code 0 and the last code 4095)	-	-	-	5 ⁽¹⁾	LSB
OE	Offset error (difference between measured value at code (0x800) and ideal value VREF+/2)	V _{REFH} =3.6V	-	-	±15	LSB
		V _{REFH} =1.8V	-	-	±25	LSB
GE	Gain error	-	-	-	±1	%
T _{st}	Settling time (full scale: Applies to 12-bit input code conversion between the lowest input code and the highest input code until the DAC output reaches the final value ±4LSB)	-	-	1.2	2.1	μs
T _{wakeup}	Start-up time (DAC enabled, until output reaches ±1 LSB)	-	-	5	7.5	μs
I _{avcc}	Analog supply current (quiescent current, no load)	-	-	604	800	μA
I _{aref}	Reference supply current (quiescent current)	-	-	161	270	μA

1. Guarantee of mass production test.

Table 3-62 12-bit DAC port output enabled and output amplifier disabled characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{AVCC}	Analog supply voltage	-	1.8	3.3	3.6	V
Aref	Reference supply voltage	= V _{AVCC}	1.8	3.3	3.6	V
AO	Output voltage range	-	0	-	Aref-1LSB	V
CL	Load capacitance	-	-	-	20	Pf
RO	output resistance	-	-	8.6	12	kΩ
DNL	Differential nonlinearity error (deviation between two consecutive codes - 1LSB)	-	-	-	±2	LSB
TUE	total unadjustable error	-	-	-	±24	LSB
T _{st}	Settling time (applies to 12-bit input code conversion between the lowest input code and the highest input code when the DAC output reaches the final value ±4LSB, CL=10Pf)	-	-	0.9	1.2	μs
T _{wakeup}	Start-up time (DAC enabled, until output reaches ±1 LSB)	-	-	2	5	μs
I _{avcc}	Analog supply current (quiescent current)	-	-	0.1	2	μA
I _{aref}	Reference supply current (quiescent current)	-	-	146	260	μA

Table 3-63 12-bit DAC port output disabled and output amplifier disabled characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{AVCC}	Analog supply voltage	-	1.8	3.3	3.6	V
Aref	Reference supply voltage	= V _{AVCC}	1.8	3.3	3.6	V
AO	Output voltage range	-	0	-	Aref-1LSB	-
DNL	Differential nonlinearity error (deviation between two consecutive codes - 1LSB)	-	-	-	±2	LSB
TUE	total unadjustable error	-	-	-	±5	LSB
T _{st}	Settling time (applies to 12-bit input code conversion between the lowest input code and the highest input code until the DAC output reaches the final value ±1 LSB, V _{avcc} ≥2.7)	-	-	65.3	81	ns
	Settling time (applies to 12-bit input code conversion between the lowest input code and the highest input code when the DAC output reaches the final value ±32 LSB, V _{avcc} ≥2.7)	-	-	36	44.9	ns
	Settling Time (Applies to 12-bit input code transition between lowest input code and highest input code until DAC output reaches final value ±1 LSB, V _{avcc} <2.7)	-	-	-	83.82	ns
	Settling Time (Applies to 12-bit input code transition between lowest input code and highest input code until DAC output reaches final value ±32 LSB, V _{avcc} <2.7)	-	-	-	48.55	ns
I _{avcc}	Analog supply current (quiescent current)	-	-	0.1	2	μA
I _{aref}	Reference supply current (quiescent current)	-	-	146	260	μA

3.3.25 Temperature Sensor

Table 3-64 Temperature sensor characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
T _L	temperature linearity	-	-2	-	+2	°C
T _E	Absolute Accuracy ⁽¹⁾	25 °C, 105°C two-point calibration	-2	-	+2	°C

- Actual characteristics are related to the accuracy of the calibration point temperature. If the preset data calibration of the chip is used, the characteristics are not guaranteed due to the temperature deviation of the mass production test environment.

3.3.26 Comparator Characteristics

Table 3-65 Comparator Characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
V _{AVCC}	Analog supply voltage	-	1.8	3.3	3.6	V
V _I	Input voltage range	-	0	-	V _{AVCC}	V
T _{cmp}	Comparison time	Comparator resolution voltage = 100 mV	-	30	50	ns
T _{set}	Input channel switching stabilization time	-	-	100	200	ns
T _{start}	Stabilization time	-	-	-	1	us

3.3.27 EXMC Characteristics

Table 3-66 EXMC features

Symbol	Parameter	Min	Typ	Max	Unit
t_add_d	Address line output delay time (2.7 V~3.6 V)	-	-	12	ns
	Address line output delay time (1.8 V~2.7 V)	-	-	18	ns
t_data_d	Data line output delay time (2.7 V~3.6 V)	-	-	12	ns
	Data line output delay time (1.8 V~2.7 V)	-	-	18	ns
t_ce_d	CE output delay time (2.7 V~3.6 V)	-	-	9	ns
	CE output delay time (1.8 V~2.7 V)	-	-	12	ns
t_we_d	WE output delay time (2.7 V~3.6 V)	-	-	9	ns
	WE output delay time (1.8 V~2.7 V)	-	-	12	ns
t_oe_d	OE output delay time (2.7 V~3.6 V)	-	-	9	ns
	OE output delay time (1.8 V~2.7 V)	-	-	12	ns
t_baa_d	BAA output delay time (2.7 V~3.6 V)	-	-	9	ns
	BAA output delay time (1.8 V~2.7 V)	-	-	12	ns
t_adv_d	ADV output delay time (2.7 V~3.6 V)	-	-	9	ns
	ADV output delay time (1.8 V~2.7 V)	-	-	12	ns
t_ale_d	ALE output delay time (2.7 V~3.6 V)	-	-	9	ns
	ALE output delay time (1.8 V~2.7 V)	-	-	12	ns
t_data_s	Data line input Setup time (2.7 V~3.6 V)	24	-	-	ns
	Data line input Setup time (1.8 V~2.7 V)	28	-	-	ns
t_data_h	Data line input Hold time	0	-	-	ns
t_rb_s	RB input Setup time (2.7 V~3.6 V)	24	-	-	ns
	RB input Setup time (1.8 V~2.7 V)	28	-	-	ns
t_rb_h	RB input Hold time	0	-	-	ns

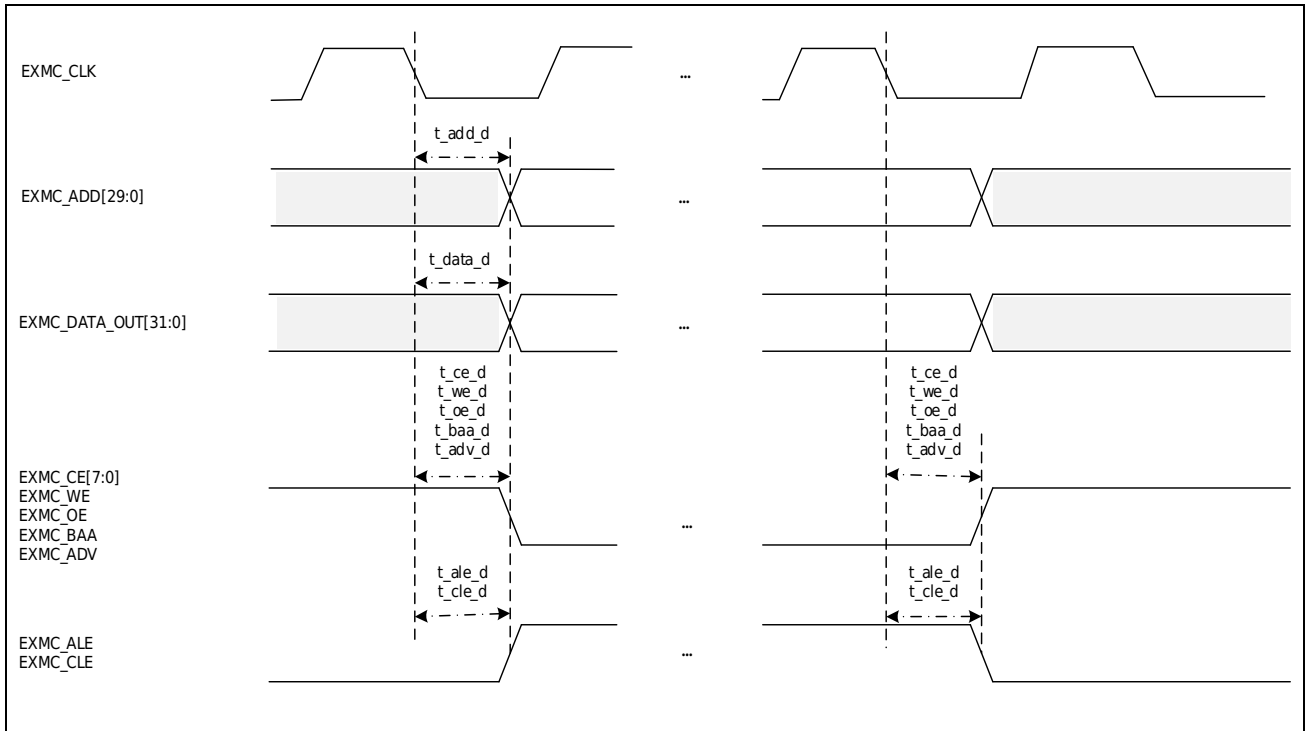


Figure 3-34 EXMC output signal timing diagram

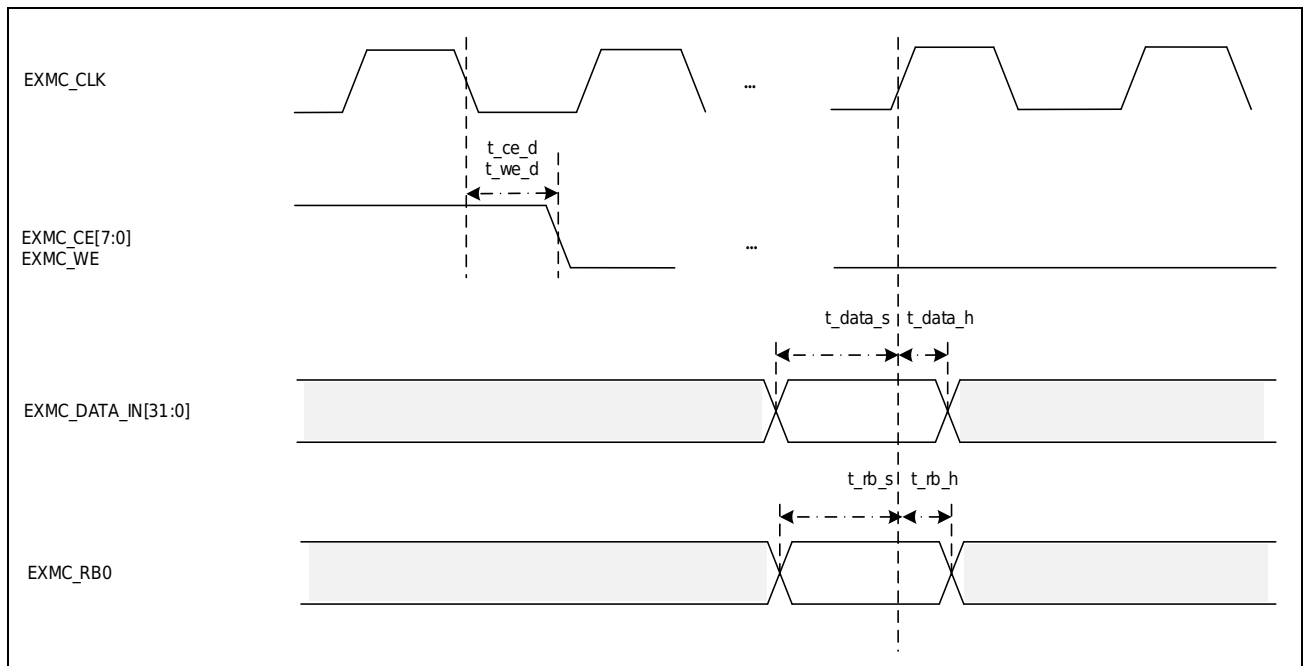


Figure 3-35 EXMC input signal timing diagram

3.3.28 DVP Characteristics

Table 3-67 DVP features

Symbol	Parameter	Min	Typ	Max	Unit
t_pixclk_s	Input data DVP_PIXCLK Setup time (2.7 V~3.6 V)	6	-	-	ns
	Input data DVP_PIXCLK Setup time (1.8 V~2.7 V)	9	-	-	ns
t_pixclk_h	Input data DVP_PIXCLK Hold time (2.7 V~3.6 V)	6	-	-	ns
	Input data DVP_PIXCLK Hold time (1.8 V~2.7 V)	9	-	-	ns
t_data_s	Input data DVP_DATA Setup time (2.7 V~3.6 V)	2.5	-	-	ns
	Input data DVP_DATA Setup time (1.8 V~2.7 V)	4	-	-	ns
t_data_h	Input data DVP_DATA Hold time (2.7 V~3.6 V)	2	-	-	ns
	Input data DVP_DATA Hold time (1.8 V~2.7 V)	3	-	-	ns
t_vsync_s	Input data DVP_VSYNC Setup time (2.7 V~3.6 V)	2.5	-	-	ns
	Input data DVP_VSYNC Setup time (1.8 V~2.7 V)	4	-	-	ns
t_vsync_h	Input data DVP_VSYNC Hold time (2.7 V~3.6 V)	1.5	-	-	ns
	Input data DVP_VSYNC Hold time (1.8 V~2.7 V)	3	-	-	ns
t_hsync_s	Input data DVP_HSYNC Setup time (2.7 V~3.6 V)	2.5	-	-	ns
	Input data DVP_HSYNC Setup time (1.8 V~2.7 V)	4	-	-	ns
t_hsync_h	Input data DVP_HSYNC Hold time (2.7 V~3.6 V)	1.5	-	-	ns
	Input data DVP_HSYNC Hold time (1.8 V~2.7 V)	3	-	-	ns

The following figure takes the setting conditions of DVP_VSYNC and DVP_HSYNC as the synchronization interval and the falling edge of DVP_PIXCLK to collect data as an example.

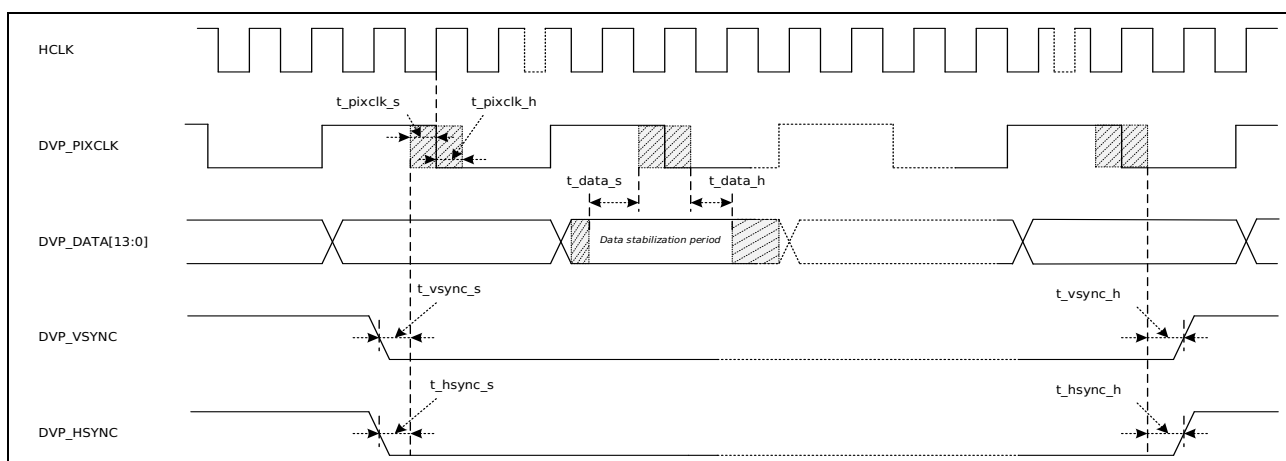


Figure 3-36 DVP input signal timing diagram

3.3.29 SD/SDIO MMC Card Host Interface (SDIO) Features

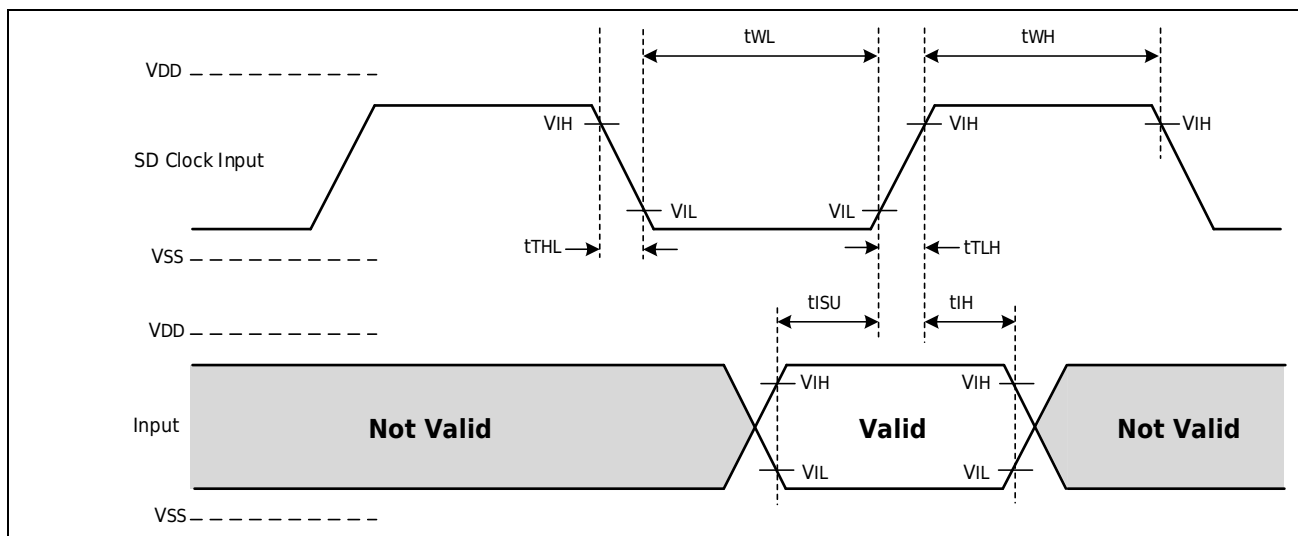


Figure 3-37 Default Speed Mode Input Timing Diagram

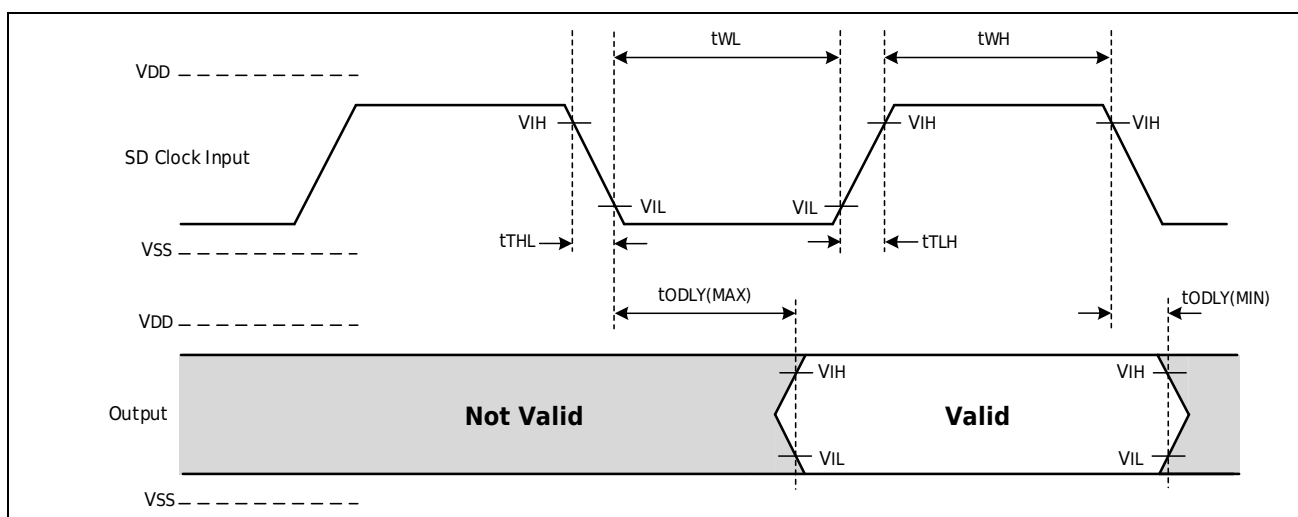


Figure 3-38 Default Speed Mode Output Timing Diagram

Table 3-68 Default Speed Mode Timing Parameters

Symbol	Parameter	Minimum value	Maximum value	Unit	Remark
-	Operating Voltage	1.8	3.6	V	
f _{PP}	transfer mode clock frequency	-	25	MHz	Load C = 30 Pf
f _{OD}	Card Identification Mode Clock Frequency	-	400	kHz	Load C = 30 Pf
t _{WL}	clock low time	10	-	ns	Load C = 30 Pf
t _{WH}	clock high time	10	-	ns	Load C = 30 Pf
t _{TLH}	clock rise time	-	10	ns	Load C = 30 Pf
t _{THL}	clock fall time	-	10	ns	Load C = 30 Pf
t _{ISU}	Data Input Setup Time	5	-	ns	Load C = 30 Pf
t _{IH}	Data Input Hold Time	14	-	ns	Load C = 30 Pf
t _{ODLY}	Data output delay	1	14	ns	Load C = 30 Pf

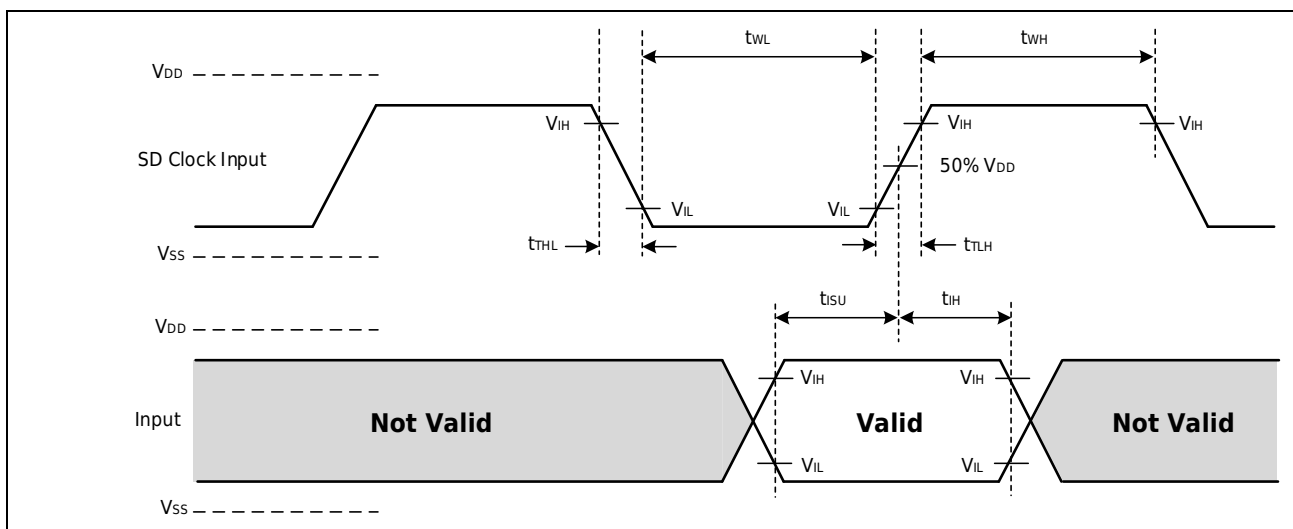


Figure 3-39 High-speed Mode Input Timing Chart

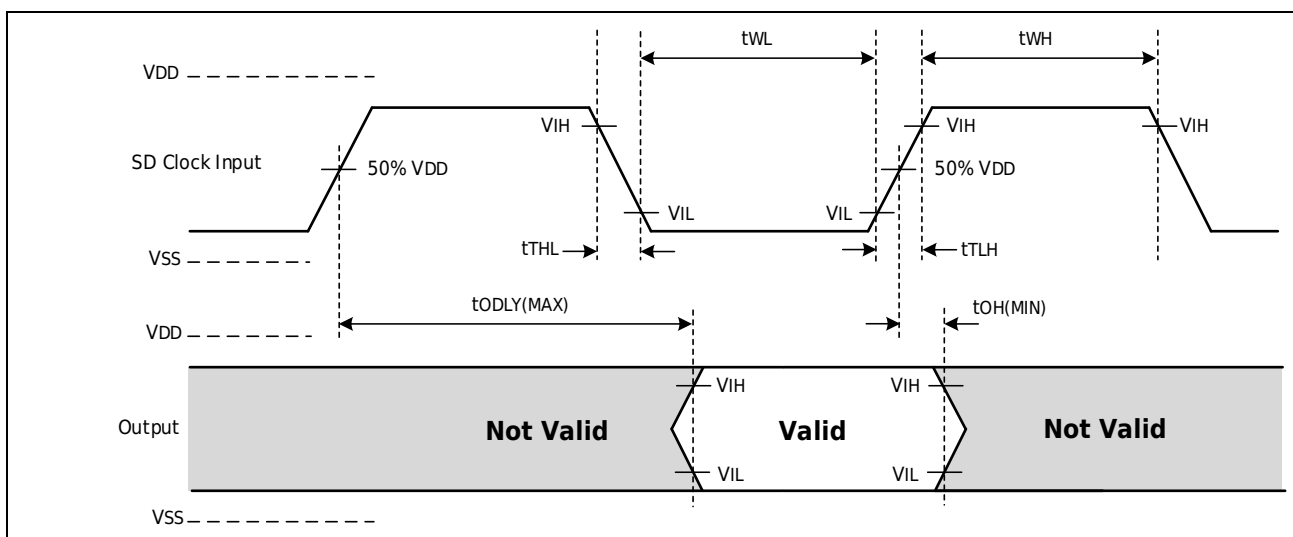


Figure 3-40 High Speed Mode Output Timing Chart

Table 3-69 High Speed Mode Timing Parameters

Symbol	Parameter	Minimum value	Maximum value	Unit	Remark
-	Operating Voltage	1.8	3.6	V	
f _{PP}	transfer mode clock frequency	-	50	MHz	Load C = 30 Pf
f _{OD}	Card Identification Mode Clock Frequency	-	400	kHz	Load C = 30 Pf
t _{WL}	clock low time	7	-	ns	Load C = 30 Pf
t _{WH}	clock high time	7	-	ns	Load C = 30 Pf
t _{TLH}	clock rise time	-	3	ns	Load C = 30 Pf
t _{THL}	clock fall time	-	3	ns	Load C = 30 Pf
t _{ISU}	Data Input Setup Time	5	-	ns	Load C = 30 Pf
t _{IH}	Data Input Hold Time	14	-	ns	Load C = 30 Pf
t _{ODLY}	Data output delay	-	14	ns	Load C = 30 Pf
t _{OH}	Data output hold time	3	-	ns	Load C = 30 Pf

3.3.30 Adjustable Gain Amplifier Characteristics

Table 3-70 Adjustable Gain Amplifier Characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit	
V _{AVCC}	Analog supply voltage	-	1.8	3.3	3.6	V	
V _{OS} ⁽¹⁾	Input offset voltage	-	-8	-	8	mV	
V _I	Input voltage range	-	0.1*V _{AVCC} /Gain	-	0.9*V _{AVCC} /Gain	V	
G _E	Gain error	Use external port PGAVSS as PGA input reference ground	Gain=2 ⁽¹⁾	-1	-	1	%
			Gain=2.133	-1	-	1	%
			Gain=2.286	-1	-	1	%
			Gain=2.667	-1	-	1	%
			Gain=2.909	-1	-	1	%
			Gain=3.2	-1.5	-	1.5	%
			Gain=3.556	-1.5	-	1.5	%
			Gain=4.0	-1.5	-	1.5	%
			Gain=4.571	-2	-	2	%
			Gain=5.333	-2	-	2	%
			Gain=6.4	-3.0	-	3.0	%
			Gain=8	-3.0	-	3.0	%
			Gain=10.667	-4.0	-	4.0	%
			Gain=16	-4.0	-	4.0	%
		Gain=32 ⁽¹⁾	-7.0	-	7.0	%	
		Use the internal analog ground AVSS as PGA input reference ground	Gain=2 ⁽¹⁾	-2	-	2	%
			Gain=2.133	-2	-	2	%
			Gain=2.286	-2	-	2	%
			Gain=2.667	-2	-	2	%
			Gain=2.909	-2	-	2	%
			Gain=3.2	-2.5	-	2.5	%
			Gain=3.556	-2.5	-	2.5	%
			Gain=4.0	-2.5	-	2.5	%
			Gain=4.571	-3.0	-	3.0	%
			Gain=5.333	-3.0	-	3.0	%
			Gain=6.4	-4.0	-	4.0	%
Gain=8	-4.0		-	4.0	%		
Gain=10.667	-5.0	-	5.0	%			
Gain=16	-5.0	-	5.0	%			
Gain=32 ⁽¹⁾	-8.0	-	8.0	%			

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3.3.31 VBAT Characteristics

Table 3-71 Backup Battery Domain Electrical Characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
VBATLVD	Low voltage monitoring voltage	PWC_PWRC4.VBATREFSEL=0	1.70	1.80	1.90	V
		PWC_PWRC4.VBATREFSEL=1	2.00	2.10	2.20	V

3.3.32 EIRQ Filtering Characteristics

Table 3-72 EIRQ Filtering Characteristics

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
WF_EIRQ	EIRQ input filter width	INTC_NOCCR.NOCSEL = 00b	0.4	-	0.9	μs
		INTC_NOCCR.NOCSEL = 01b	0.8	-	1.6	μs
		INTC_NOCCR.NOCSEL = 10b	1.5	-	3.0	μs
		INTC_NOCCR.NOCSEL = 11b	3.1	-	5.9	μs

3.3.33 RX Filter Characteristics in USART1 STOP Mode

Table 3-73 RX filter characteristics in USART1 STOP mode

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
WF_USART1	USART1 input filter width	USART1_NFC.USART1_NFS = 00b	0.4	-	0.9	μs
		USART1_NFC.USART1_NFS = 01b	0.8	-	1.6	μs
		USART1_NFC.USART1_NFS = 10b	1.5	-	3.0	μs
		USART1_NFC.USART1_NFS = 11b	3.1	-	5.9	μs

3.3.34 Filtering Characteristics in USB On-Chip Full-Speed PHY STOP Mode

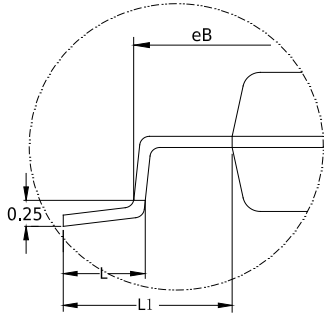
Table 3-74 Filtering Characteristics in USB On-Chip Full-Speed PHY STOP Mode

Symbol	Parameter	Conditions	Minimum value	Typical value	Maximum value	Unit
WF_USB	USB input filter width	USB_SYCTLREG.USBFS_NFS = 00b USB_SYCTLREG.USBHS_NFS = 00b	0.4	-	0.9	μs
		USB_SYCTLREG.USBFS_NFS = 01b USB_SYCTLREG.USBHS_NFS = 01b	0.8	-	1.6	μs
		USB_SYCTLREG.USBFS_NFS = 10b USB_SYCTLREG.USBHS_NFS = 10b	1.5	-	3.0	μs
		USB_SYCTLREG.USBFS_NFS = 11b USB_SYCTLREG.USBHS_NFS = 11b	3.1	-	5.9	μs

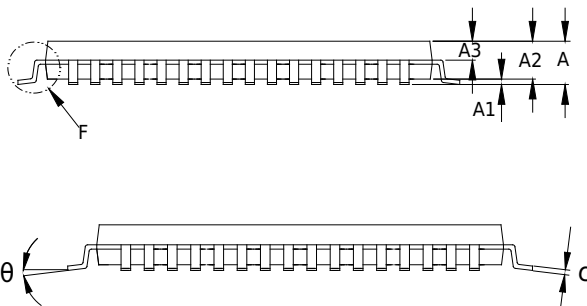
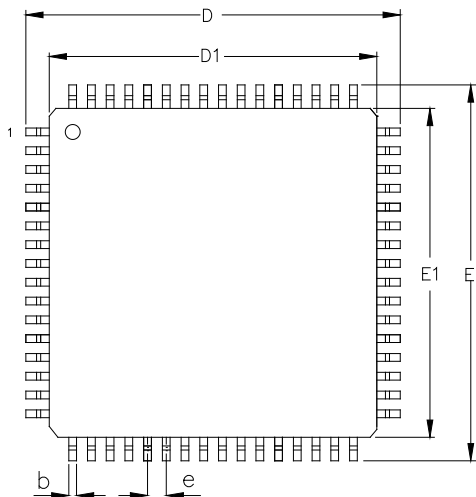
4 Package Information

4.1 Package Dimensions

LQFP64 package



DETAIL: F

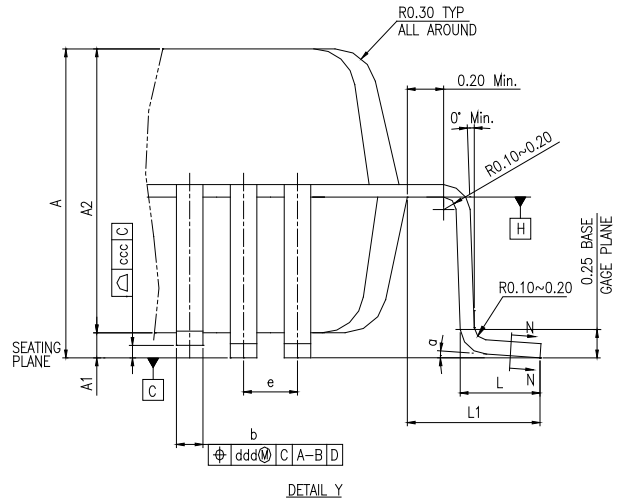
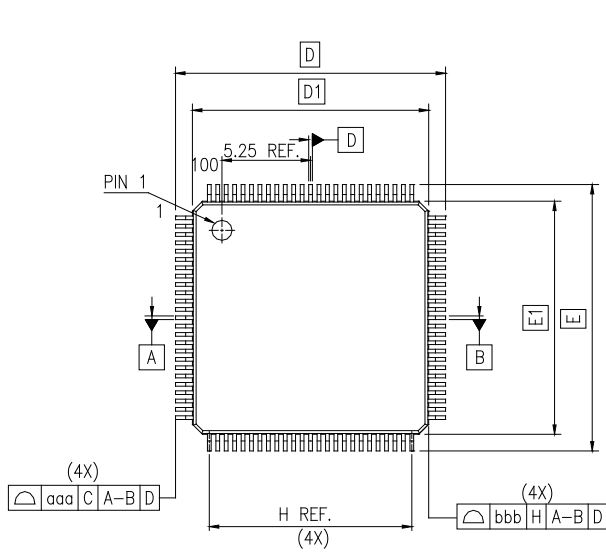


Symbol	10x10 Millimeter		
	Min	Nom	Max
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
A3	0.59	0.64	0.69
b	0.17	0.22	0.27
c	0.09	--	0.20
D	11.80	12.00	12.20
D1	9.90	10.00	10.10
E	11.80	12.00	12.20
E1	9.90	10.00	10.10
e	0.50BSC		
L	0.45	0.60	0.75
L1	1.00REF		
θ	0°	--	7°

NOTE:

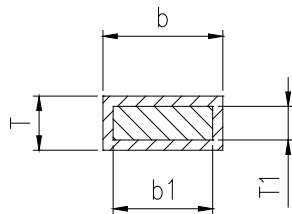
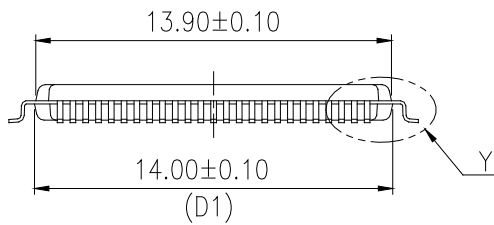
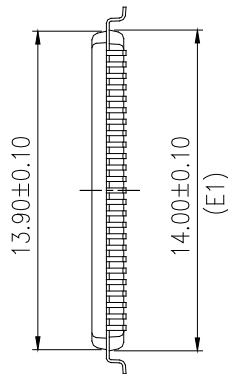
- Dimensions "D1" and "E1" do not include mold flash.

LQFP100 package



DIMENSION LIST (FOOTPRINT: 2.00)

S/N	SYM	DIMENSIONS	REMARKS
1	A	MAX. 1.60	OVERALL HEIGHT
2	A1	0.10±0.05	STANDOFF
3	A2	1.40±0.05	PKG THICKNESS
4	D	16.00±0.20	LEAD TIP TO TIP
5	D1	14.00±0.10	PKG LENGTH
6	E	16.00±0.20	LEAD TIP TO TIP
7	E1	14.00±0.10	PKG WIDTH
8	L	0.60±0.15	FOOT LENGTH
9	L1	1.00 REF.	LEAD LENGTH
10	T	0.15 ^{+0.05} _{-0.06}	LEAD THICKNESS
11	T1	0.127±0.03	LEAD BASE METAL THICKNESS
12	a	0°~7°	FOOT ANGLE
13	b	0.22±0.05	LEAD WIDTH
14	b1	0.20±0.03	LEAD BASE METAL WIDTH
15	e	0.50 BASE	LEAD PITCH
16	H(REF.)	(12.00)	CUM. LEAD PITCH
17	aaa	0.20	PROFILE OF LEAD TIPS
18	bbb	0.20	PROFILE OF MOLD SURFACE
19	ccc	0.08	FOOT COPLANARITY
20	ddd	0.08	FOOT POSITION

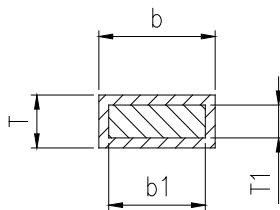
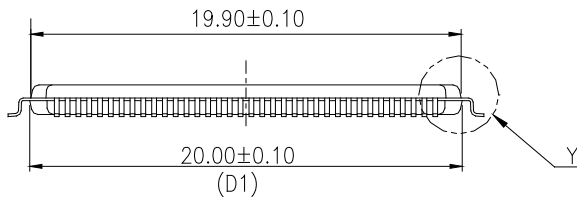
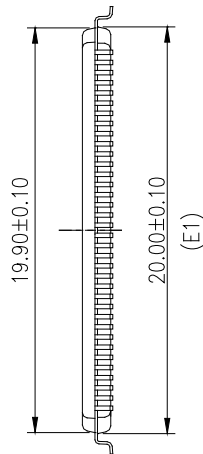
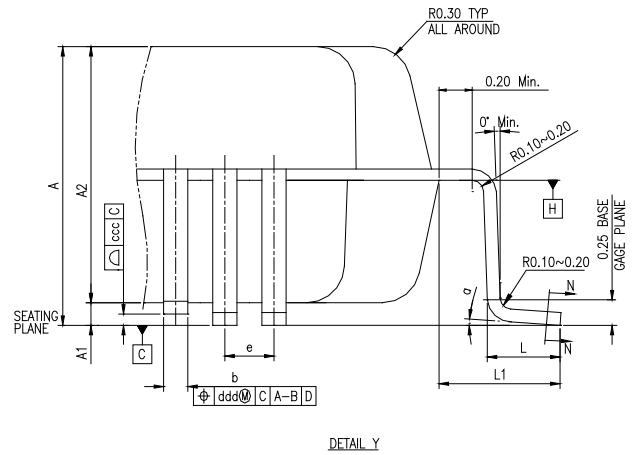
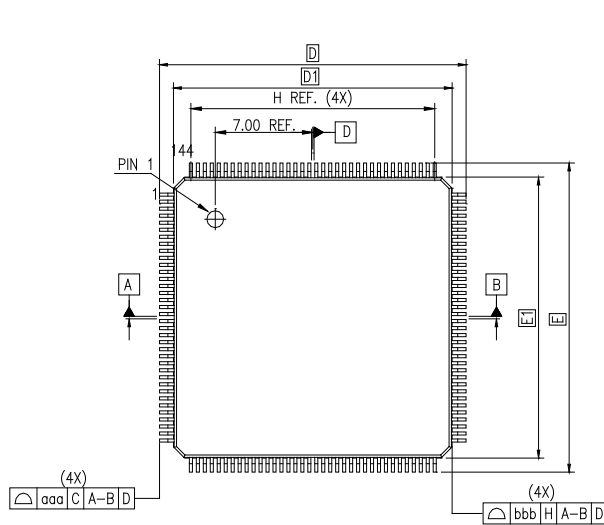


SECTION N-N

NOTE:

- Dimensions "D1" and "E1" do not include mold flash.

LQFP144 package



SECTION N-N

DIMENSION LIST (FOOTPRINT: 2.00)

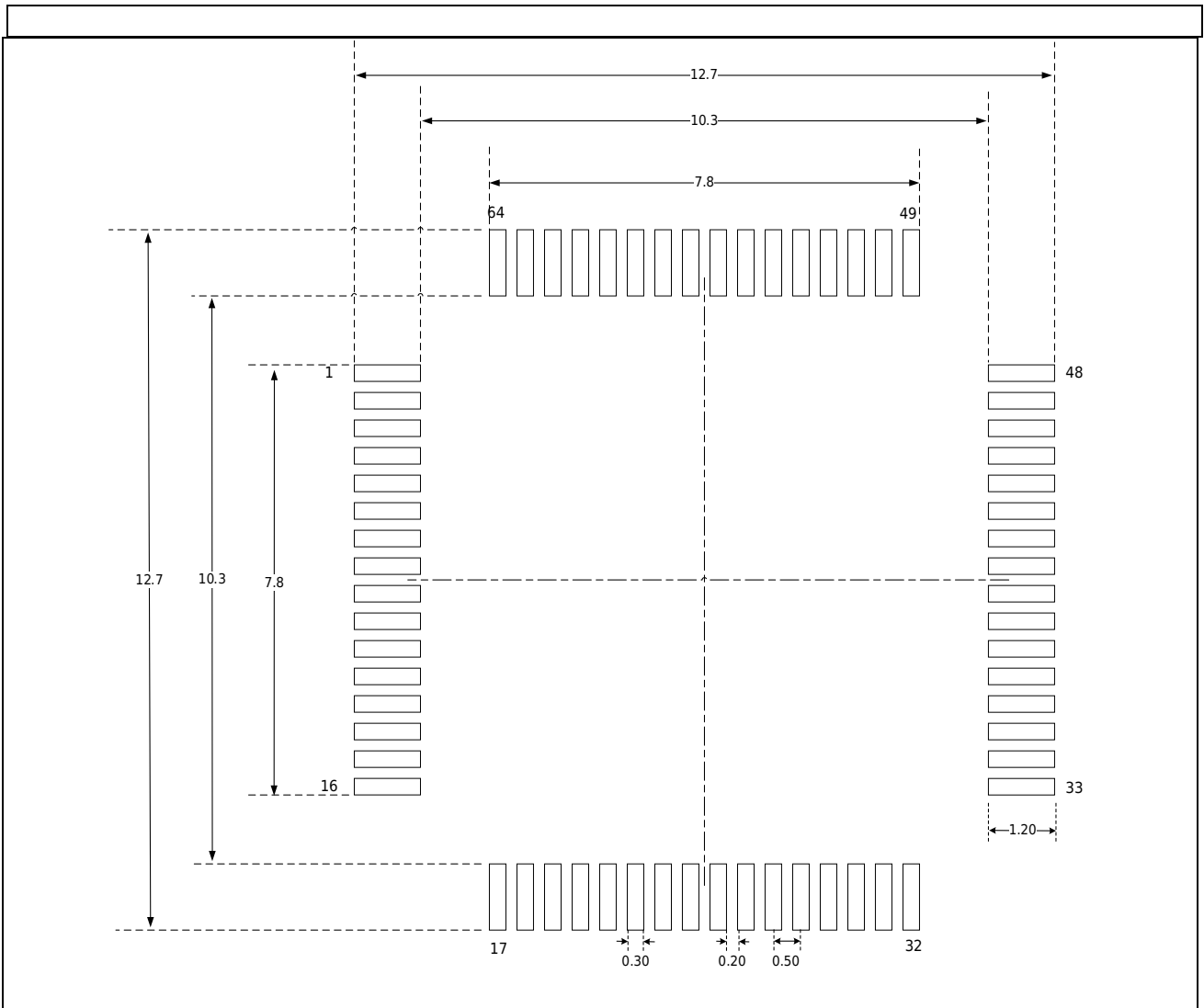
S/N	SYM	DIMENSIONS	REMARKS
1	A	MAX. 1.60	OVERALL HEIGHT
2	A1	0.10±0.05	STANDOFF
3	A2	1.40±0.05	PKG THICKNESS
4	D	22.00±0.20	LEAD TIP TO TIP
5	D1	20.00±0.10	PKG LENGTH
6	E	22.00±0.20	LEAD TIP TO TIP
7	E1	20.00±0.10	PKG WIDTH
8	L	0.60±0.15	FOOT LENGTH
9	L1	1.00 REF.	LEAD LENGTH
10	T	0.15 ^{+0.05} _{-0.06}	LEAD THICKNESS
11	T1	0.127±0.03	LEAD BASE METAL THICKNESS
12	a	0°~7°	FOOT ANGLE
13	b	0.22±0.05	LEAD WIDTH
14	b1	0.20±0.03	LEAD BASE METAL WIDTH
15	e	0.50 BASE	LEAD PITCH
16	H (REF.)	(17.50)	CUM. LEAD PITCH
17	aaa	0.20	PROFILE OF LEAD TIPS
18	bbb	0.20	PROFILE OF MOLD SURFACE
19	ccc	0.08	FOOT COPLANARITY
20	ddd	0.08	FOOT POSITION

NOTE:

- Dimensions "D1" and "E1" do not include mold flash.

4.2 Schematic Diagram of the Pad

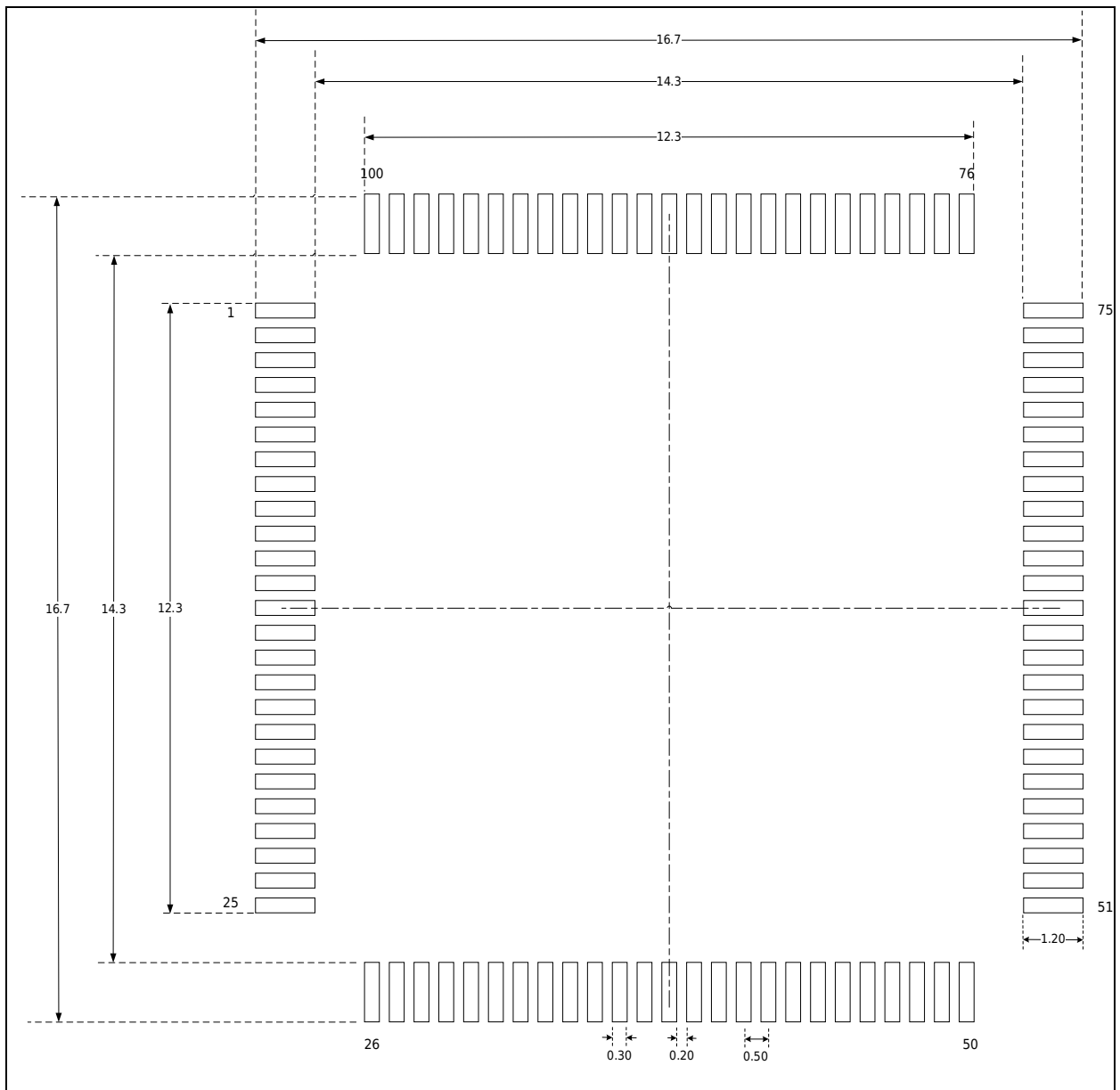
LQFP64 package (10 mm x 10 mm)



NOTE:

- Dimensions are expressed in millimeters.
- Dimensions are for reference only.

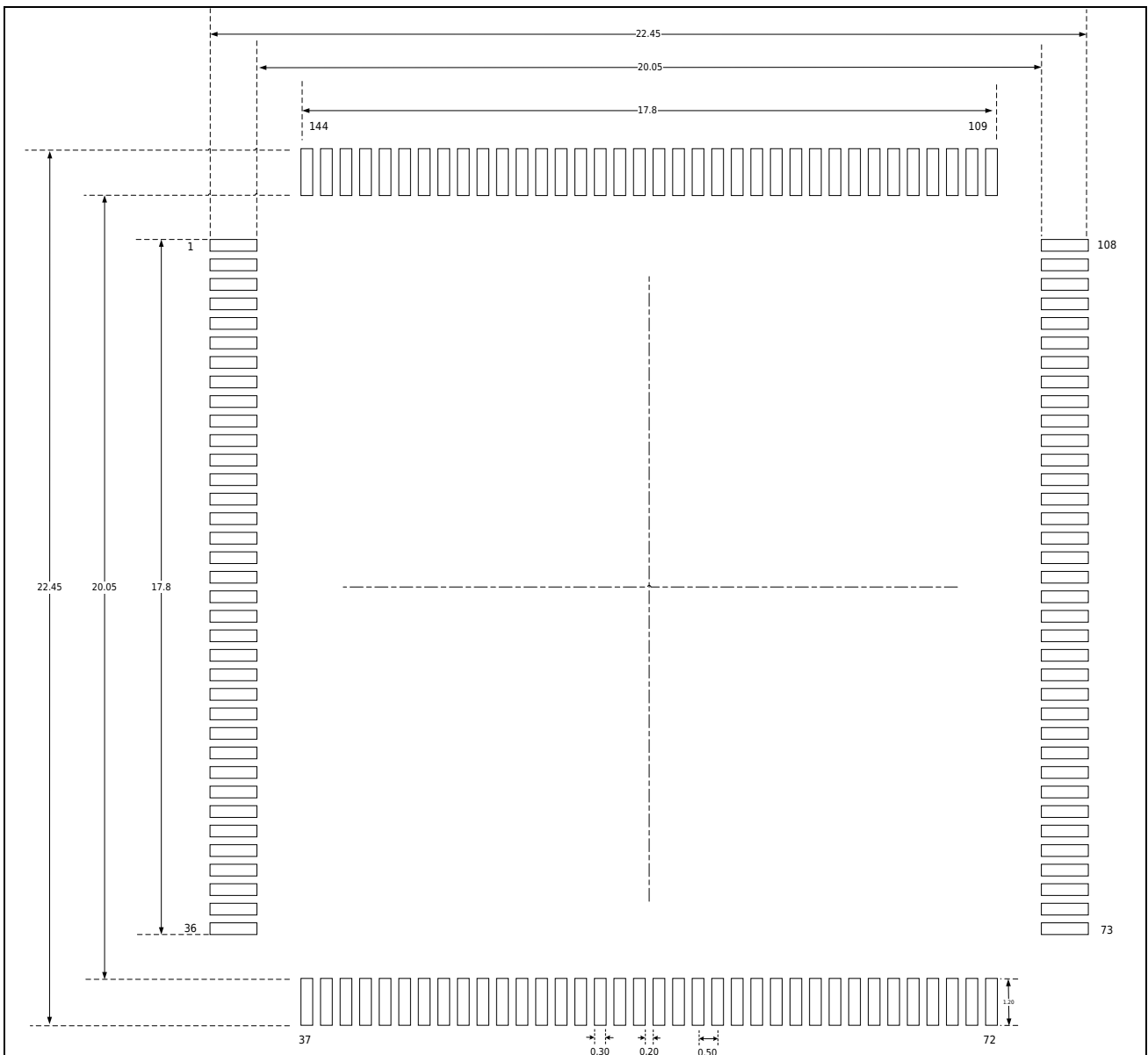
LQFP100 package (14 mm x 14 mm)



NOTE:

- Dimensions are expressed in millimeters.
- Dimensions are for reference only.

LQFP144 package (20 mm x 20 mm)



NOTE:

- Dimensions are expressed in millimeters.
- Dimensions are for reference only.

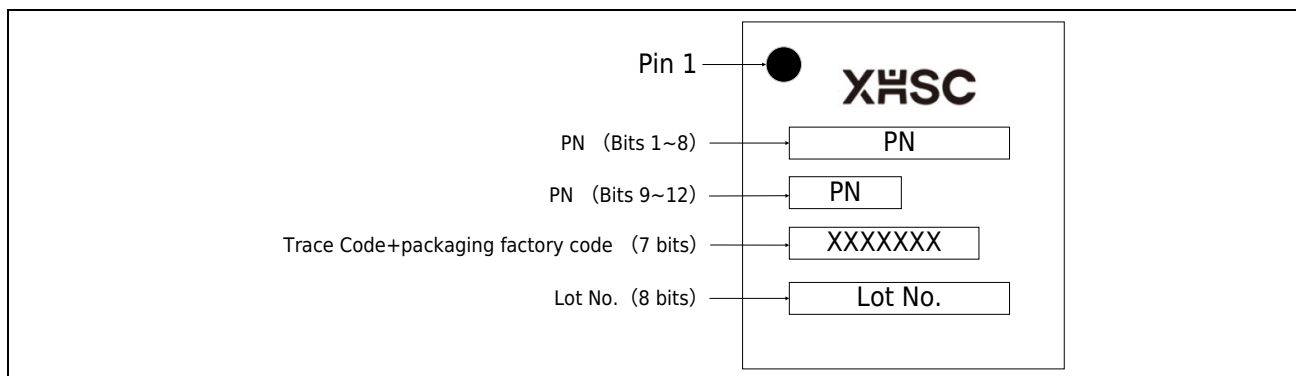
4.3 Silkscreen Instructions

The position and information of Pin 1 printed on the front of each package are given below.

LQFP64 package (10 mm x 10 mm)

LQFP100 package (14 mm x 14 mm)

LQFP144 package (20 mm x 20 mm)



Note:

- The blank boxes in the above figure indicate optional marks related to production, which are not explained in this section.

4.4 Package Thermal Resistance Coefficient

When the packaged chip is working at the specified working environment temperature, the junction temperature T_j (°C) of the chip surface can be calculated according to the following formula:

$$T_j = T_A + (P_D \times \theta_{JA})$$

- T_A refers to the working environment temperature when the packaged chip is working, the unit is °C;
- θ_{JA} refers to the thermal resistance coefficient of the package to the working environment, the unit is °C/W;
- P_D is equal to the sum of the internal power consumption (P_{INT}) of the chip and the power consumption ($P_{I/O}$) generated by the I/O pin when the chip is working, the unit is W.

$$P_{INT} = I_{CC} \times V_{CC}$$

$$P_{I/O} = \sum(V_{OL} \times I_{OL}) + \sum((V_{CC} - V_{OH}) \times I_{OH})$$

The junction temperature T_j on the surface of the chip when the chip is operating at the specified operating ambient temperature must not exceed the maximum junction temperature T_j allowed by the chip.

Table 4-1 Thermal resistance coefficient table of each package

Package Type and Size	Thermal Resistance Junction-ambient Value (θ_{JA})	Unit
LQFP64 10 mm x 10 mm / 0.5 mm pitch	55 +/- 10%	°C/W
LQFP100 14 mm x 14 mm / 0.5 mm pitch	42.6 +/- 10%	°C/W
LQFP144 20 mm x 20 mm / 0.5 mm pitch	40 +/- 10%	°C/W

5 Ordering Information

Product model		HC32F467RGTI-LQFP144	HC32F467PGTI-LQFP100	HC32F467KGTI-LQFP64
Clock Speed(MHz)		240	240	240
Core		M4	M4	M4
Flash(KB)		1024	1024	1024
OTP(KB)		134	134	134
RAM(KB)		512+4	512+4	512+4
GPIO		116	83	53
Voltage(V)		1.8 - 3.6	1.8 - 3.6	1.8 - 3.6
DMA		2*8ch	2*8ch	2*8ch
Timing and Counting	Timer	19	19	19
	RTC	✓	✓	✓
Communication Interface	UART	8	8	5
	I ² C	3	3	3
	SPI	6	6	6
	QSPI	1	1	1
	USB	USB 2.0 OTG FS + USB 2.0 OTG HS		
	CAN	2*CAN 2.0		
	EXMC	1	1	0
	ETHMAC	1	1	1
	I ² S	4	4	4
	SDIO	2	2	2
Analog	ADC 12bit	3*24ch	3*16ch	3*16ch
	SH	3ch	3ch	3ch
	DAC 12bit	2ch	2ch	2ch
	PGA	2	2	2
	Vcomp	3	3	3
	DVP	1	1	1
	LVD	✓	✓	✓
	LVR	✓	✓	✓
Safety	AES	AES256	AES256	AES256
	TRNG	1	1	1
	Hash	SHA256	SHA256	SHA256
Coprocessor	FMAC	1	1	1
	MAU	1	1	1
	DCU	8ch	8ch	8ch
Operating Temperature(°C)		-40~105	-40~105	-40~105
Pin Pitch		0.5mm	0.5mm	0.5mm
Package	Package Type	LQFP144 (20*20)	LQFP100 (14*14)	LQFP64 (10*10)
	Packaging Type	TRAY	TRAY	TRAY

Before ordering, please contact the sales window for the latest mass production information.

Version Revision History

Version number	Revision Date	Modify the content
Rev1.00	2024/08/12	First edition release.
Rev1.01	2024/10/09	Add LQFP64 Package Information
Rev1.02	2025/06/05	<ol style="list-style-type: none"> 1) Product Features: Modified the value of the internal low-speed RC oscillator. 2) 1.2: Updated the number of UART interfaces for HC32F467KGTI in Table 1-1. 3) 1.4.32: Changed "Full-Speed Module" to "High-Speed Module" for USB2.0. 4) 2.1: Corrected errors in the pin configuration diagram. 5) 2.2: In Table 2-1, modify the pin names as follows: Change "XTAL32_OUT" to "XTAL32_IN", "XTAL32_IN" to "XTAL32_OUT", "XTAL_IN" to "XTAL_EXT/XTAL_OUT", "XTAL_OUT" to "XTAL_IN", "USBHS_ULPICK" to "USBHS_ULPICK", and "JTDO_SWO" to "JTDO_TRACESWO". 6) 2.3: Updated ADC function names in Table 2-5; Modified Clock description; Revised EXMC IO attributes. 7) 3.2: Modify the note description of Table 3-2 Voltage Characteristics, change "Maximum Injection" to "Maximum". 8) 3.3.1: Added power dissipation and notes to Table 3-5. 9) 3.3.6.1: Updated description of high-speed external user clock characteristics in Table 3-17. 10) 3.3.6.2: Revised typical application information for 8MHz crystal oscillator in Figure 3-4. 11) 3.3.6.3: Revised typical application information for 32.768kHz crystal oscillator in Figure 3-5. 12) 3.3.10.2: Removed version information from conditions in Table 3-31. 13) 3.3.11: Updated description of I/O AC characteristics in Table 3-34. 14) 3.3.18.3: Deleted rxer-related information from Table 3-44 and Figure 3-22. 15) 3.3.23: Updated Figure 3-31 and its description. 16) 4.4: Modified thermal resistance coefficients for the package.
Rev1.03	2026/04/28	<ol style="list-style-type: none"> 1) Product features: optimized the crystal oscillator names; changed the main crystal oscillator to high-speed clock oscillator, and changed the secondary crystal oscillator to low-speed clock oscillator. 2) Pin configuration diagram: added the XTAL32_EXT pin name. 3) Pin function table: supplemented the GPO function description, and added the XTAL32_EXT pin name. 4) Pin function description: added the XTAL32_EXT description. 5) General operating conditions: optimized the description of precautions. 6) Reset and power control module characteristics: changed the standby wake-up in Table 3-7 to power down wake-up. 7) 3.3.5 Low power mode wake-up timing: changed the standby mode to power down mode. 8) 3.3.9 Optimized the flash erasure times and data retention period in Table 3-29.

Version number	Revision Date	Modify the content
		9) 12-bit DAC characteristics: divided the OE in Table 3-61 into two positions; added the start-up time T_{wakeup} in Table 3-61 and Table 3-62. 10) Comparator characteristics: added the stabilization time in Table 3-65. 11) Adjustable Gain amplifier characteristics: changed the negative input of PGA in Table 3-70 to PGA input reference ground.